



Third Quarter FY 2026 Quarterly Update

Infineon Technologies AG
Investor Relations



Infineon at a glance

Addressing long-term high-growth trends



Energy
green and efficient

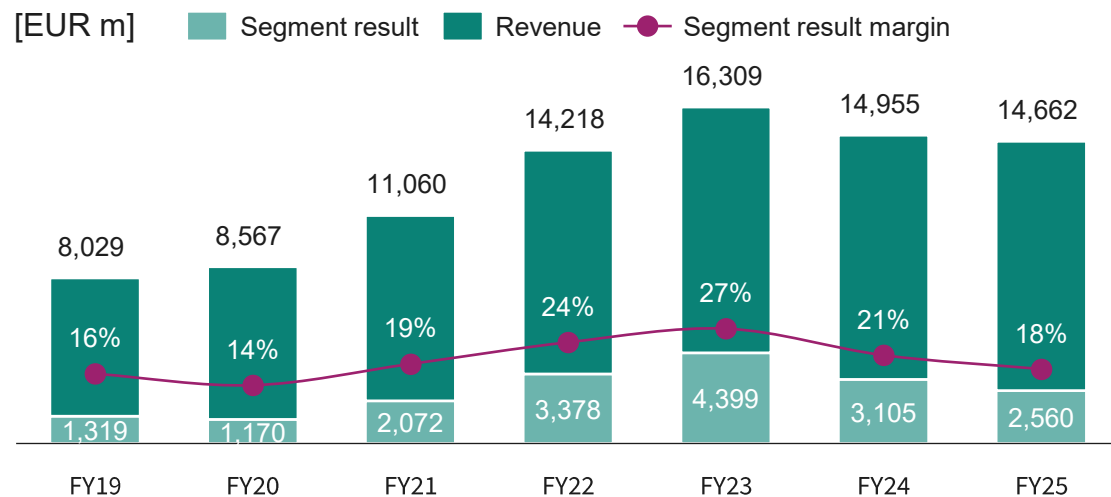


Mobility
clean and safe

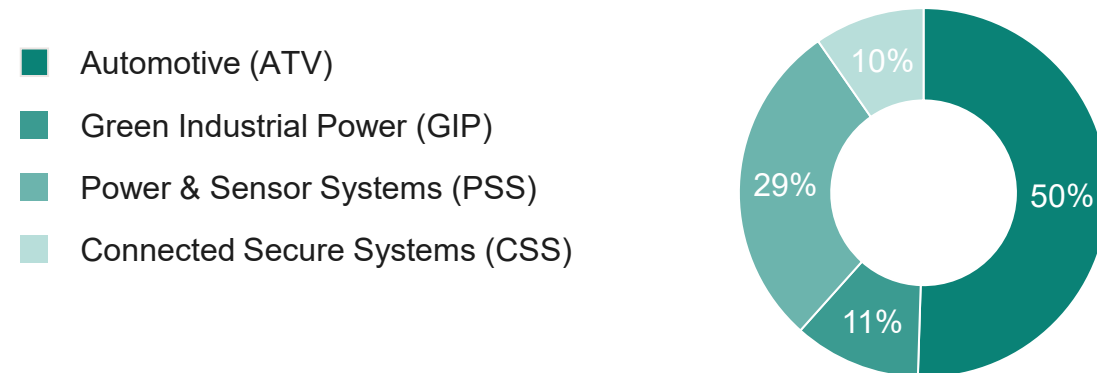


IoT
smart and secure

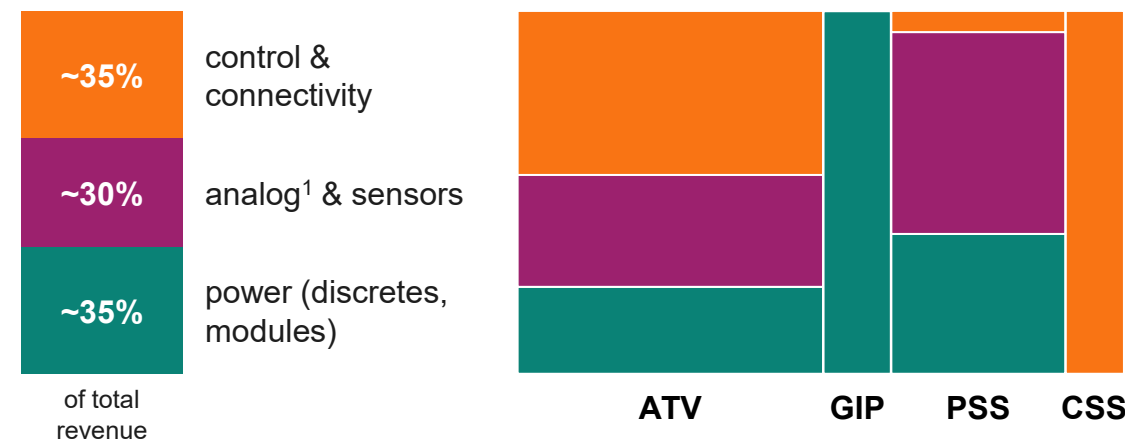
Financials



FY25 revenue by segment



FY25 revenue by product category

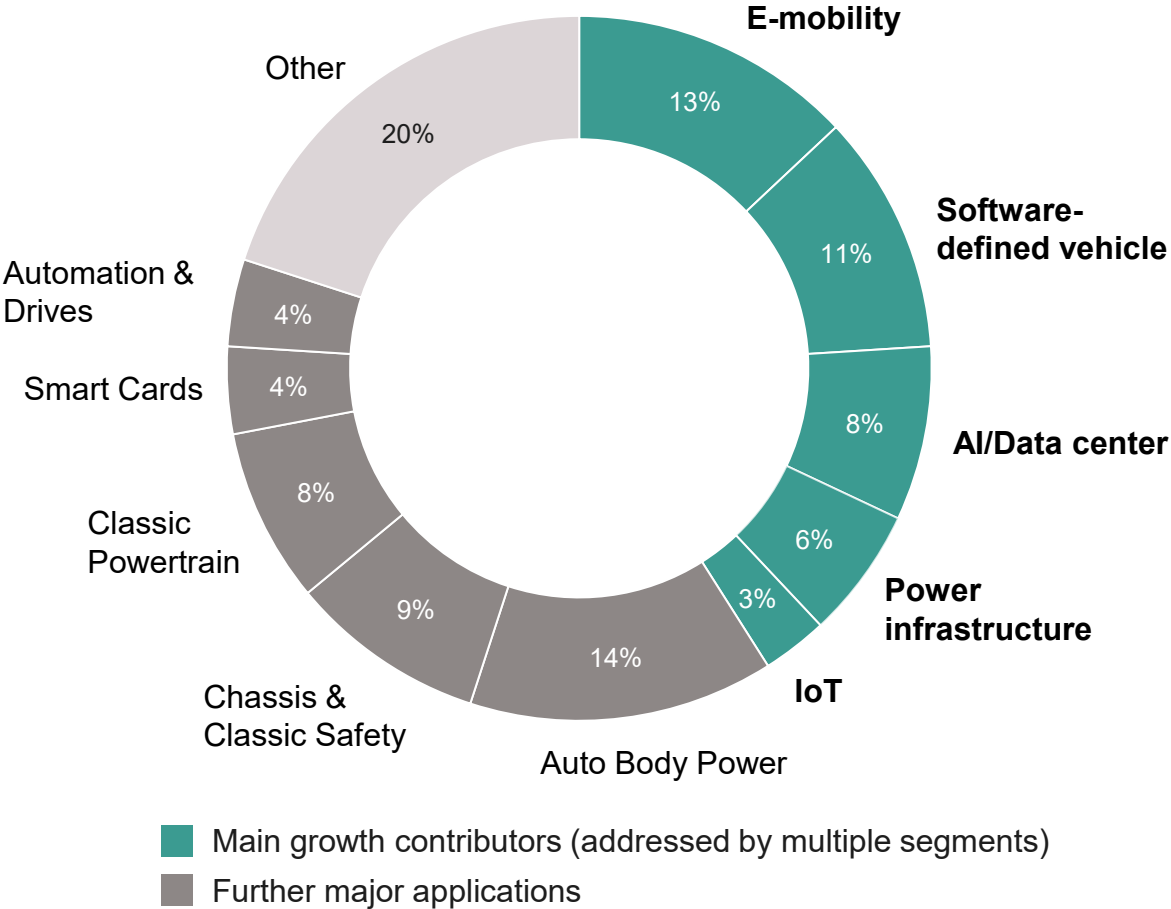
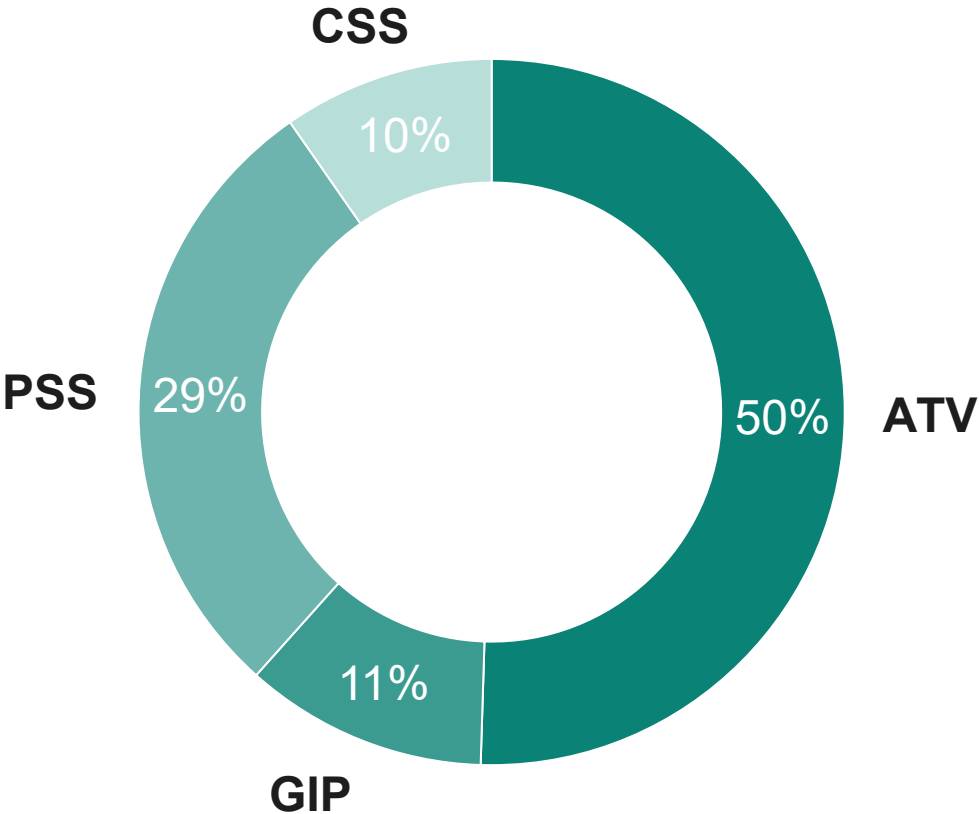


¹ including <5% of differentiating memory technologies

Well-balanced portfolio among segments and key applications, highest growth coming from Decarbonization and Digitalization



FY25 revenue of €14,662m by segment and key application

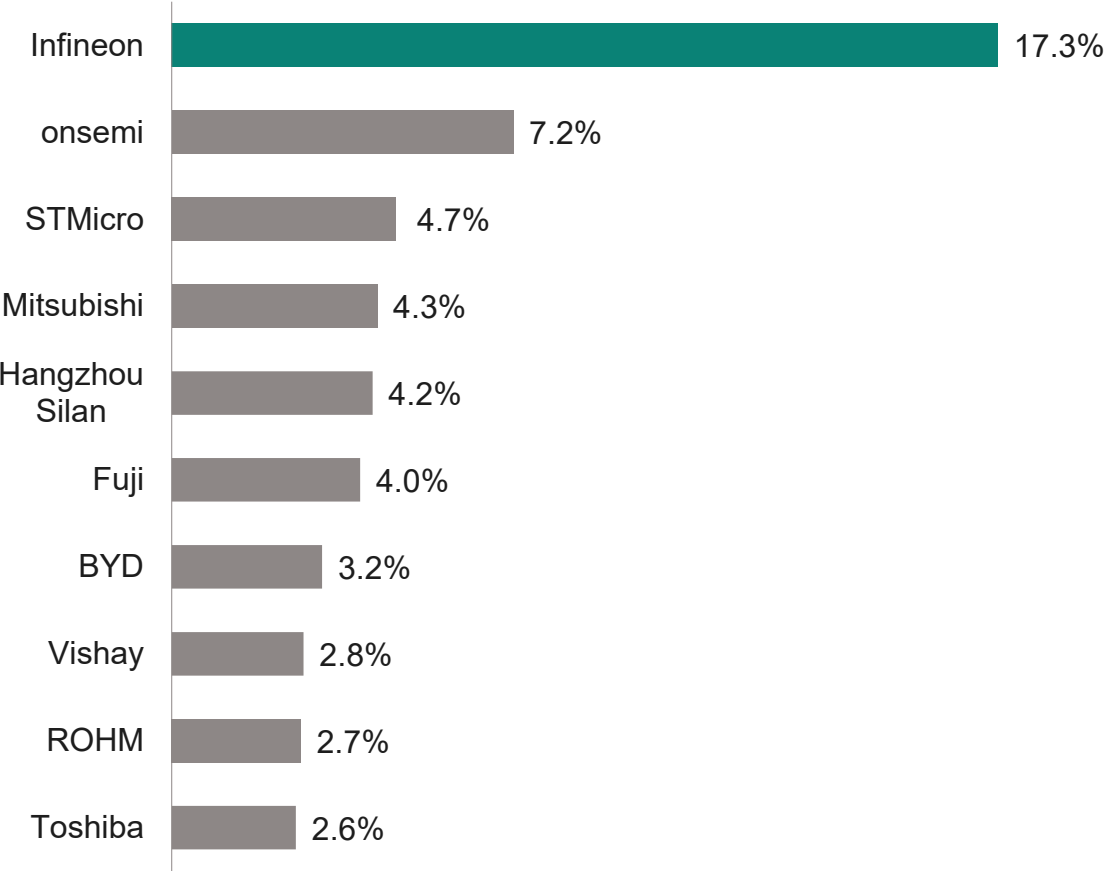


Infineon is a global player, clear #1 in power semiconductors, automotive semiconductors and microcontroller market



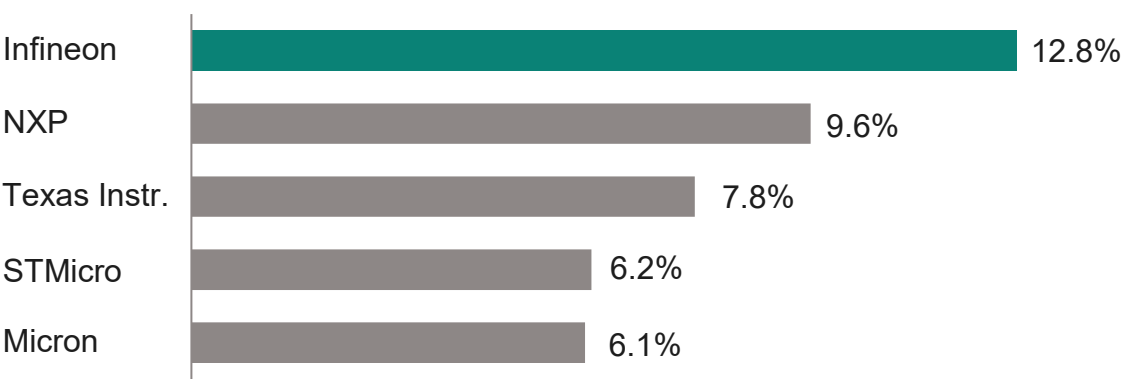
Power discretes and modules

2025 total global market: \$32.5bn¹



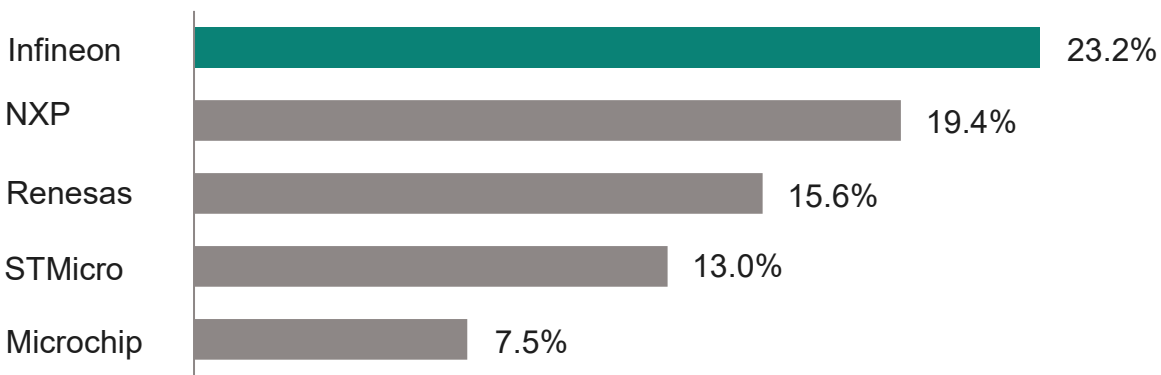
Automotive semiconductors

2025 total market: \$74.4bn²



Microcontroller

2025 total market: \$22.2bn³



¹ Based on or includes research from Omdia: Power Semiconductor Market Share Database – 1H26 (2025 Base Year). May 2026. | ² TechInsights: Automotive Semiconductor Vendor 2025 Market Shares. April 2026 | ³ Based on or includes research from Omdia: Annual 2001-2025 Semiconductor Market Share Competitive Landscaping Tool – 4Q25. March 2026. Results are not an endorsement of Infineon Technologies AG. Any reliance on these results is at the third party's own risk.

Our Target Operating Model: committing to ambitious financial goals and being the sustainability leader

Target Operating Model through cycle



Revenue growth

>10%



Segment Result Margin

25%



Adj. Free Cash
Flow Margin¹

10-15%

Sustainability leader
CO₂ neutrality 2030



¹ See notes for definition



Outlook for Q4 FY26 and FY26

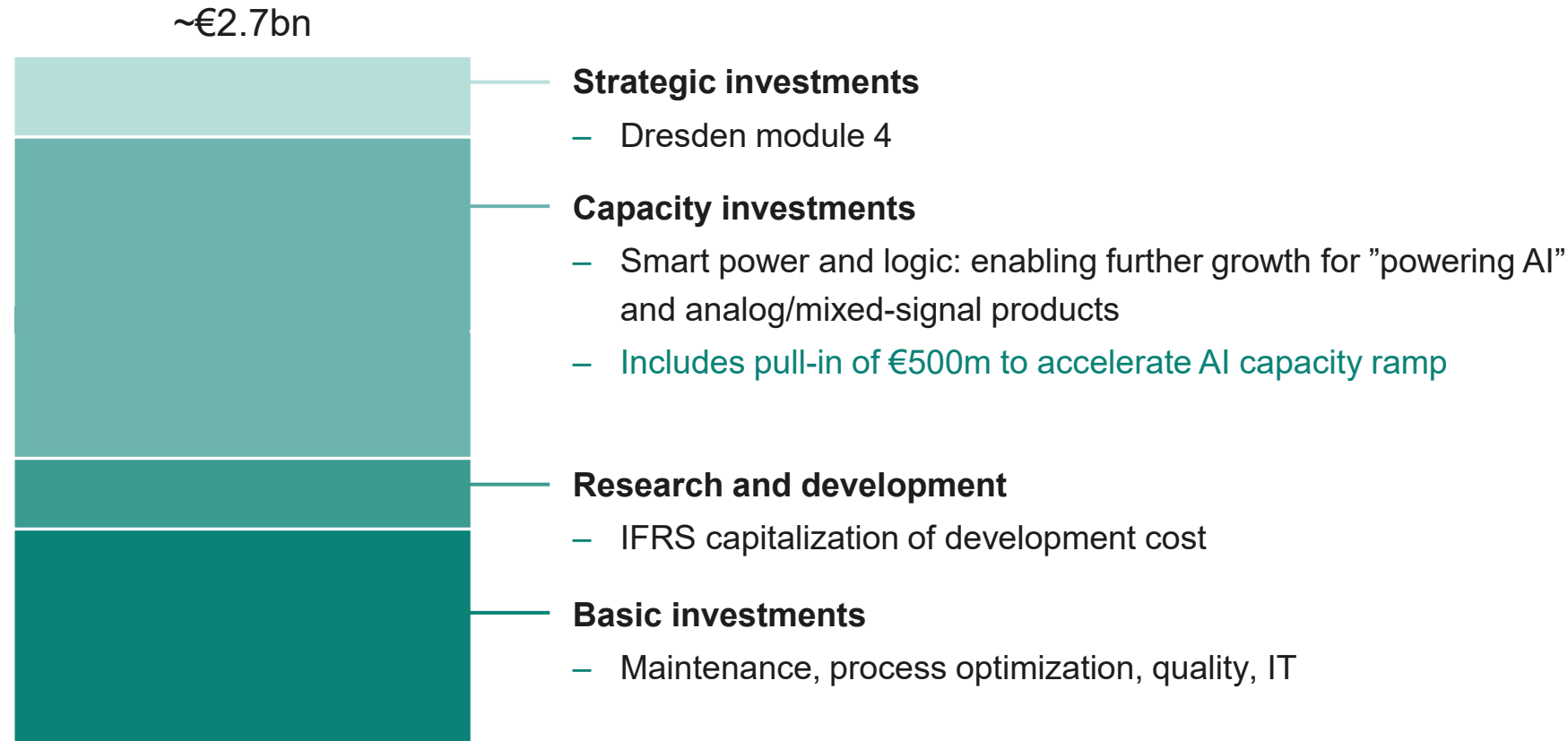
	Outlook Q4 FY26¹	Outlook FY26¹
Revenue	~€4.7bn	~€16.3bn
Adj. Gross Margin		low-to-mid 40s %
Segment Result Margin	~23%	~20%
FCF		~€0.9bn/ ~€1.85bn
Adj. FCF		
Investments		~€2.7bn
D&A		~€2.0bn ²

¹ Based on an assumed average exchange rate of \$1.15 for €1.00 for Q4

² Including the amortization of approximately 400 million Euros from purchase price allocations

Modular investment approach for long-term value creation – pull-in of AI related investments for faster ramp

Infineon investments¹ FY26



¹ Investments are defined as the total amount invested in property, plant and equipment and in other intangible assets, including capitalized development costs

The Smart Power Fab ramps production at exactly the right time to serve powering AI growth – ahead of construction schedule



Summer 2023
Building permit

Autumn 2023
Shell construction

Spring 2025
Facility equipment

Summer 2026
Ramp-up

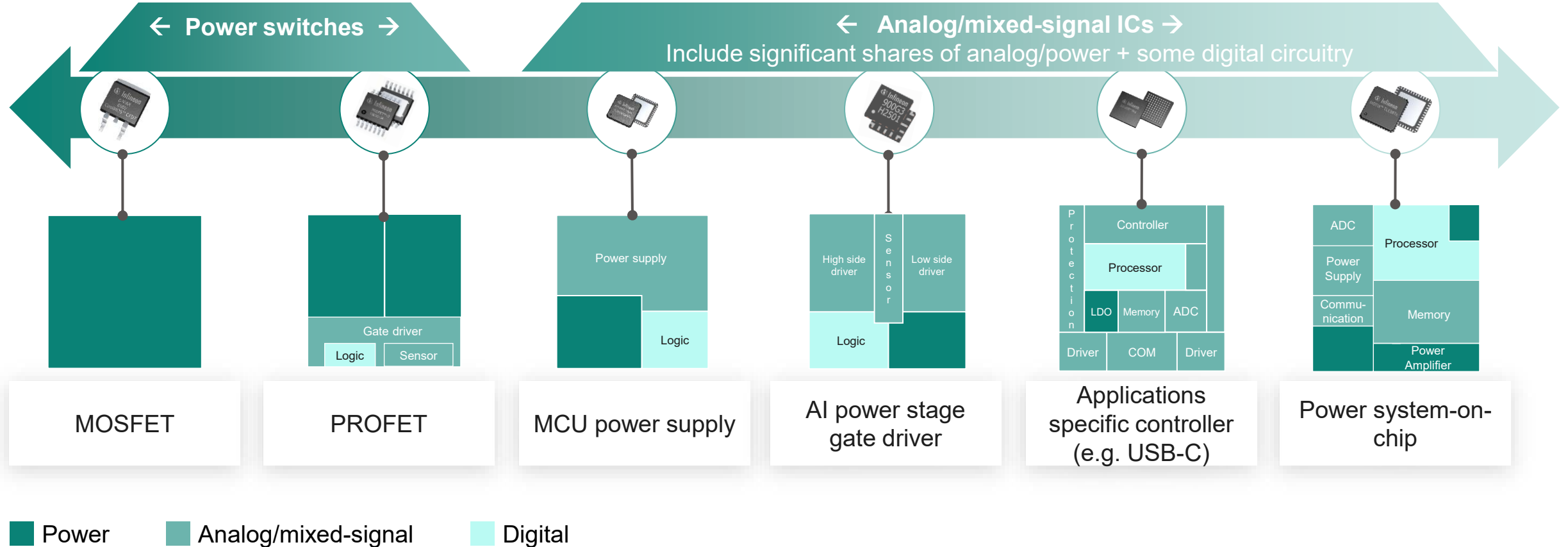


The Smart Power Fab – largest fab for intelligent power semiconductors worldwide

- **Largest fab** for intelligent power semiconductors worldwide and one of the **most advanced and flexible** 300 mm semiconductor manufacturing facilities
- **Creation of ~1,000 jobs**, supported by expanded vocational training, plus strong impact on the ecosystem
- Significantly **higher ramp speed** possible, supported by AI-optimized pre-planning and digital twin
- **At its core: semiconductors driving decarbonization and digitalization** – for automotive and industrial applications, including AI data centers
- **The combination of power semiconductors with analog/mixed-signal components** enables highly energy-efficient, intelligent system solutions



Our Smart Power Fab will serve a highly differentiating power and analog/mixed-signal product portfolio with high flexibility



The efficient and flexible product portfolio is a strategic advantage of the fab – e.g. enabling Powering AI growth

Hybrid manufacturing strategy balances inhouse manufacturing and outsourcing to strategic partners – sweet spot for Infineon

Strategic differentiation through right mix of inhouse manufacturing ...

We manufacture **differentiating power & analog/mixed-signal** primarily **inhouse**

This results in a **differentiation potential** – technology, manufacturing processes, cost



... and outsourcing to strategic manufacturing partners



Differentiation arises not from technology, but mainly from **product design** and **software**



Capital efficient growth, flexibility and reduced risks



Strategic localization

	IFX revenue split	Foundry supply globally	IFX outsourcing share
Control & connectivity	~35%	High	High
Analog & sensors	~30%	Medium	Medium
Power	~35%	Low	Low

From 4 to 3 divisions: New organizational structure to bring innovative system-level solutions to customers faster

From...



...to:



Focus applications (examples)

- SDV
- E-mobility

- Power infrastructure
- AI Datacenter

- Robotics & Edge AI
- Smart home

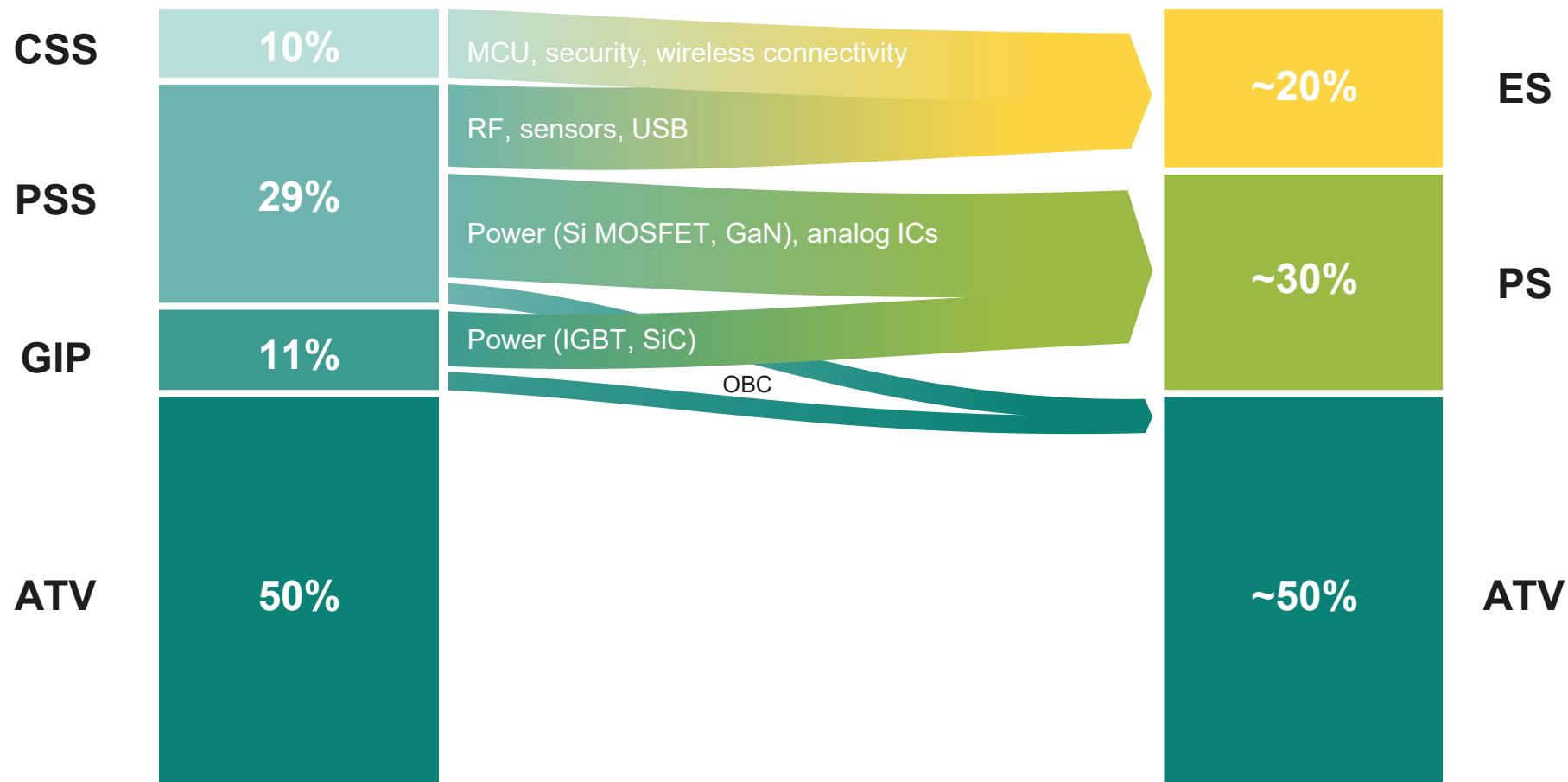
Clearer ownership
of focus applications

Reduced complexity
streamlines decision-making

Further accelerate
innovation-to-customer value

Well-balanced and simplified business setup

FY25 revenue of €14.7bn as reported and pro forma



Infiniteon strengthens its sensor leadership with the acquisition of ams OSRAM's non-optical analog/mixed-signal sensor portfolio



Closed as of
July 1st, 2026



ams OSRAM
analog/mixed-signal
sensor business

Transaction overview

CY26e revenue

~€230 m

Purchase price

€570 m

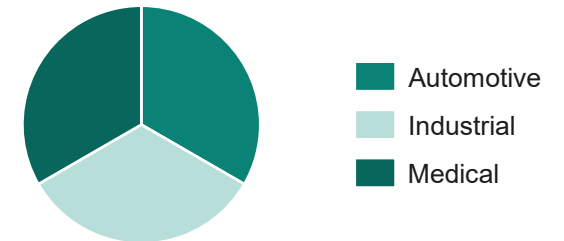
Employees

~230 employees, thereof ~150 in R&D
fabless asset-deal

Financial impact

EPS accretive from day 1

End market split



Strategic rationale

1

Strengthening our global sensor leadership position

- Acquisition of a top European sensor portfolio with complementary products in automotive and industrial end markets
- Expands footprint in high-value medical market

2

Accelerating growth and innovation

- Acceleration of innovation through synergetic R&D
- Acceleration of growth via established Infiniteon go-to-market channels

A unique opportunity to reinforce our leadership in analog/mixed-signal sensor solutions

Infiniteon serves all markets with a broad sensor portfolio to provide best solutions in Auto and Industrial



Automotive



- Radar sensors
- Magnetic position sensors
- Magnetic speed sensors
- Magnetic current sensors
- Inductive sensors
- Pressure sensors
- Gas/leakage sensors
- Silicon microphones
- CAPSENSE™ μ C



- Magnetic position sensors
- Capacitive sensors
- Battery sensors



Complementing Infineon's leading sensor and sensor IC portfolio across automotive and industrial applications

Industrial



- Radar sensors
- Magnetic position sensors
- Current sensors
- Pressure sensors
- Vibration sensors
- Gas/leakage sensors
- 3D ToF sensors
- CAPSENSE™ μ C



- Inductive position sensors
- Sensor interface IC
- X-ray sensor IC



Medical



- Temperature sensors
- Conventional and photon counting IC
- X-ray sensor IC

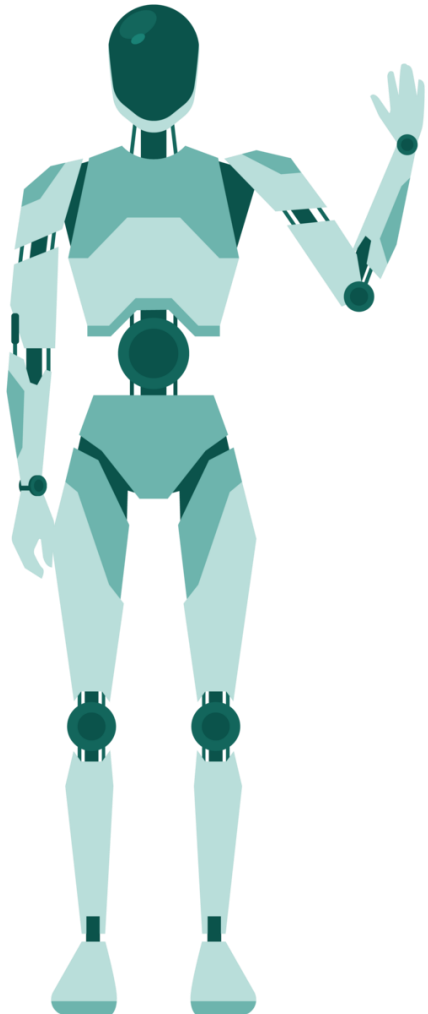


ams OSRAM
analog/mixed-signal
sensor business



Expanding our portfolio in medical applications

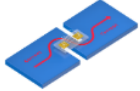
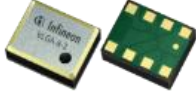
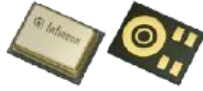
Strengthening of Infineon's leading robotics sensor solutions with acquired portfolio – addressing around 200 sensors



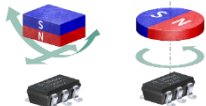
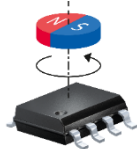
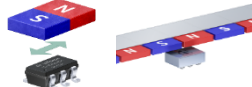
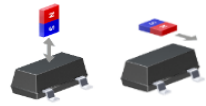
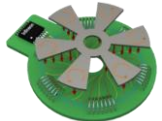
Humanoid sensor usage

- Broad range of **environmental sensors** (pressure, vibration, SiMiC, ToF, radar)
- Capacitive sensing for dexterous hands, **>100 position sensors**, e.g. for joints
- **Current sensors** for battery management

Infineon's current & environmental sensors portfolio

				
Current sensors	Pressure sensors	Radar systems	Microphones	3D time of flight

Infineon's combined position sensor portfolio

				
3D sensor	Angle sensors	Linear sensors	Magnetic switches	Inductive sensors

 acquired portfolio

Undisputed power systems leadership mastering all three key materials



- » Reliable multi sourcing of raw materials
- » World-scale fabs



- » Application understanding
- » Packaging know-how and hybridization competence

Leadership in Power Systems across all materials and technologies

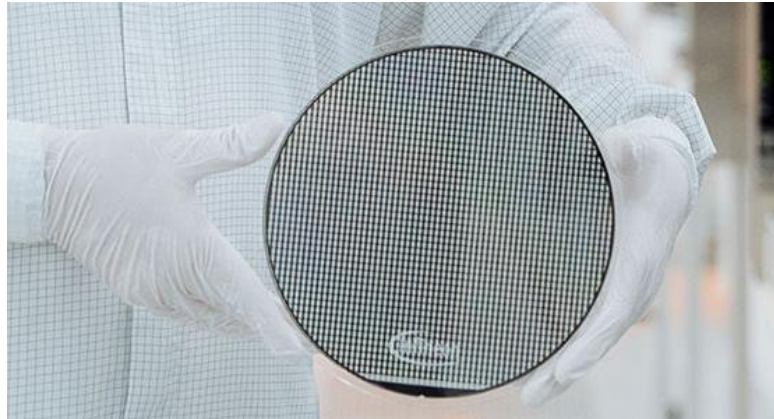
Silicon

Diode – MOSFET – IGBT – Driver – Controller



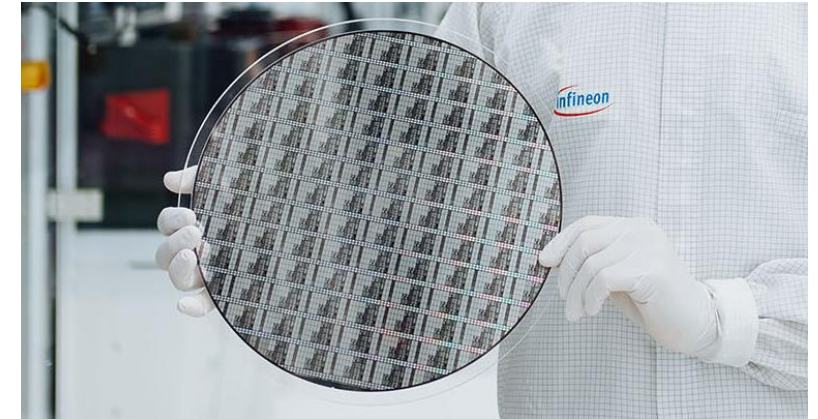
Silicon carbide

Diode – MOSFET



Gallium nitride

HEMT – Driver



Infineon is the leader across all power semiconductor technologies – unparalleled portfolio and know-how



Si

World's thinnest silicon power wafer with 20 µm on 300 mm

- Broadest Si-power portfolio in the market
- Unmatched quality and leading in all figures of merit (FOM)
- Best price/performance ratio

CoolMOS™

OptiMOS™

SiC

World's most competitive 200 mm silicon carbide power fab

- Broadest portfolio covering auto and industrial applications
- Leading trench performance
- High reliability and robustness in extreme conditions
- Smaller system size

CoolSiC™

GaN

World's first 300 mm gallium nitride power wafer

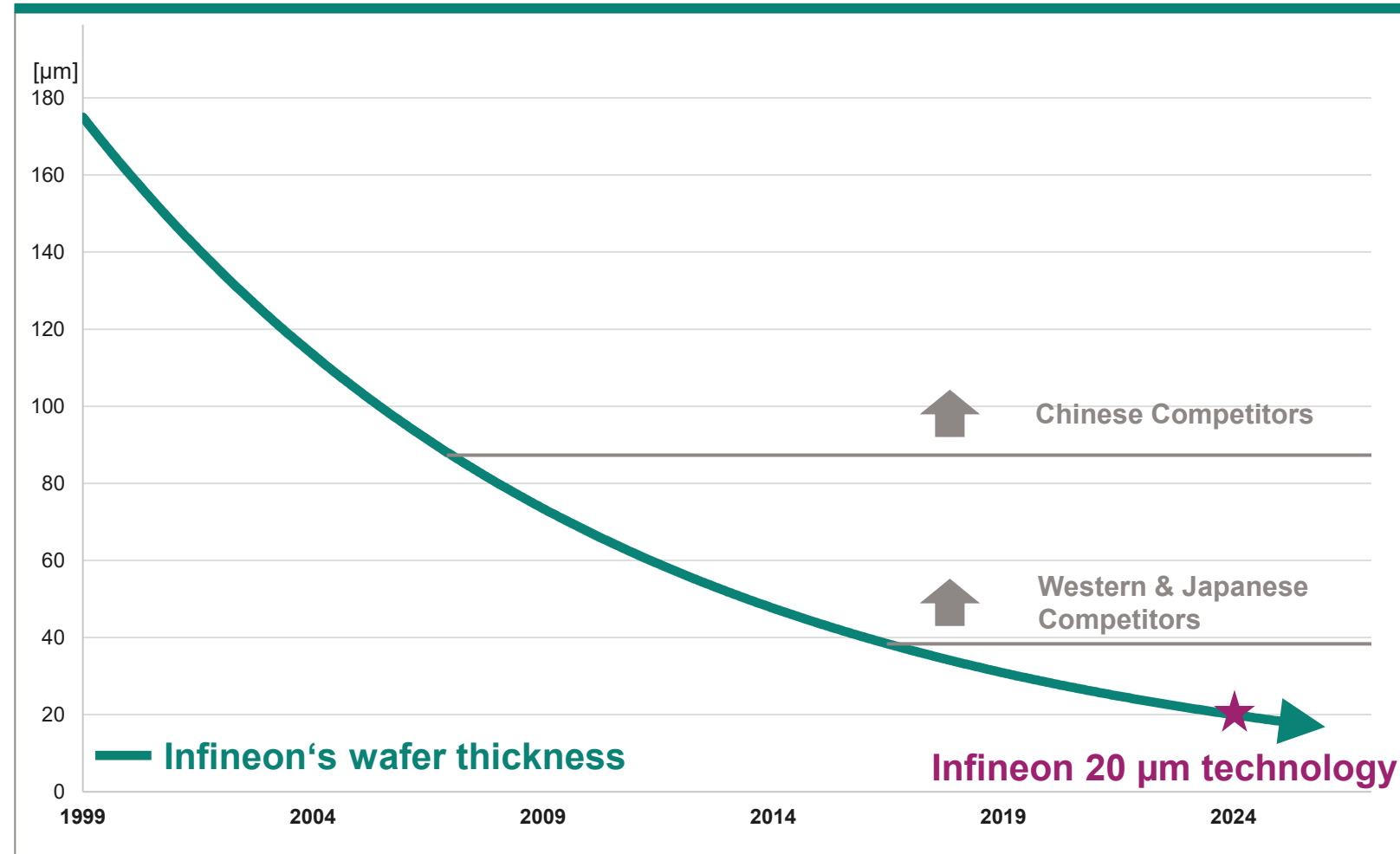
- Enabling cost parity with silicon
- Highest efficiency at the highest frequency enabling smallest system size
- Allow functional integration

CoolGaN™

Infineon is strengthening its position as the industry's innovation leader leading the way in all three power semiconductor materials

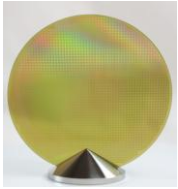
Infiniteon presents the world's thinnest silicon power wafer paving the way for more energy efficient power systems

Infiniteon reduces wafer thickness from 40 μm to 20 μm



- Infineon pioneers 20 μm process at high-scale production
- Halving thickness also halves resistance, reducing power loss by >15%
- Enables easy and robust signal routing from front to backside
- Technology qualified by customers and applied in Infineon's Integrated Smart Power Stages for DC-DC converter in AI servers

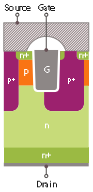
Infinion combines leading silicon carbide trench technology with the industry's most competitive manufacturing setup



SiC raw material supplier network



- More than 6 qualified SiC wafer and boule suppliers
- Globally diversified and resilient



Superior trench technology



- 30% more chips per wafer than planar
- Unmatched reliability with zero field returns



Packaging portfolio



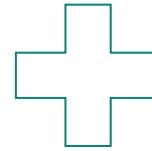
- Best-in-class in-house packaging solutions
- .XT technology for highest power density



Deep system understanding



- Decades of experience
- Broadest portfolio: off-the-shelf plus customized solutions

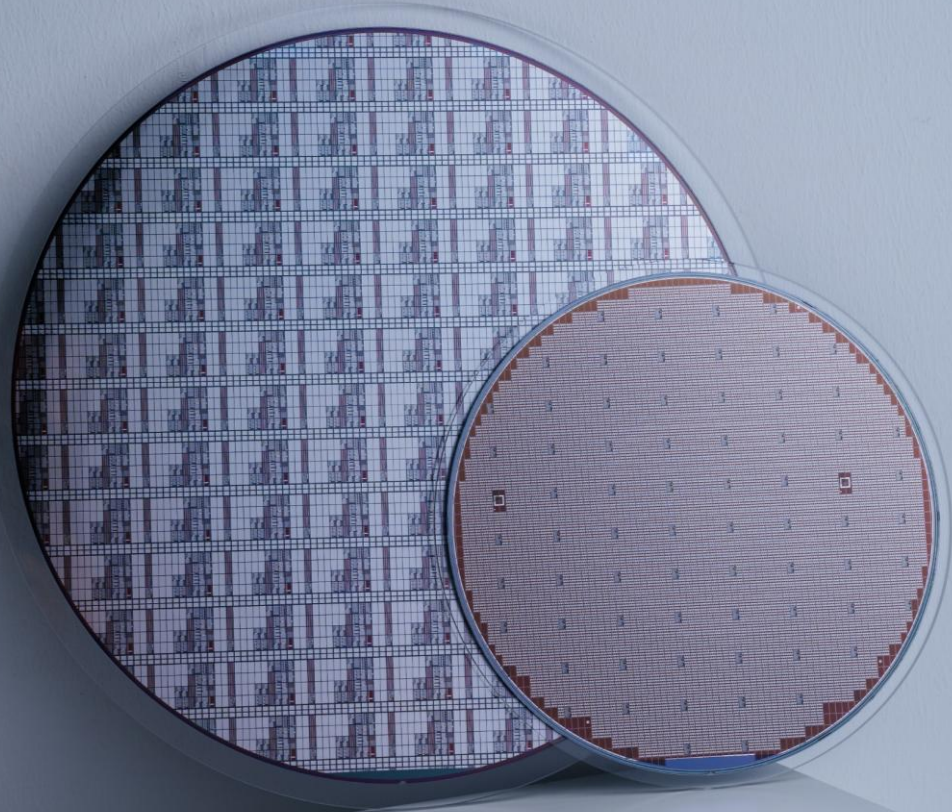


Most competitive 200 mm fab in Kulim
with industry-leading cost position.
Resilient setup together with Villach plant

Infiniteon is a leader in GaN technology and can build on the industry's broadest IP portfolio and application expertise



GaN



Broadest IP portfolio in the market
(~350 patent families)

Leading GaN product portfolio MV and HV applications

World's first 300 mm GaN manufacturing process strengthens cost-effectiveness

Leadership in GaN

Proven application expertise with > 400 GaN experts and system know-how

Superior customer supply stability through dual-sourcing and scalability

Infiniteon at the core of IoT – driving digitalization by serving strongly growing multi-application markets



Consumer IoT



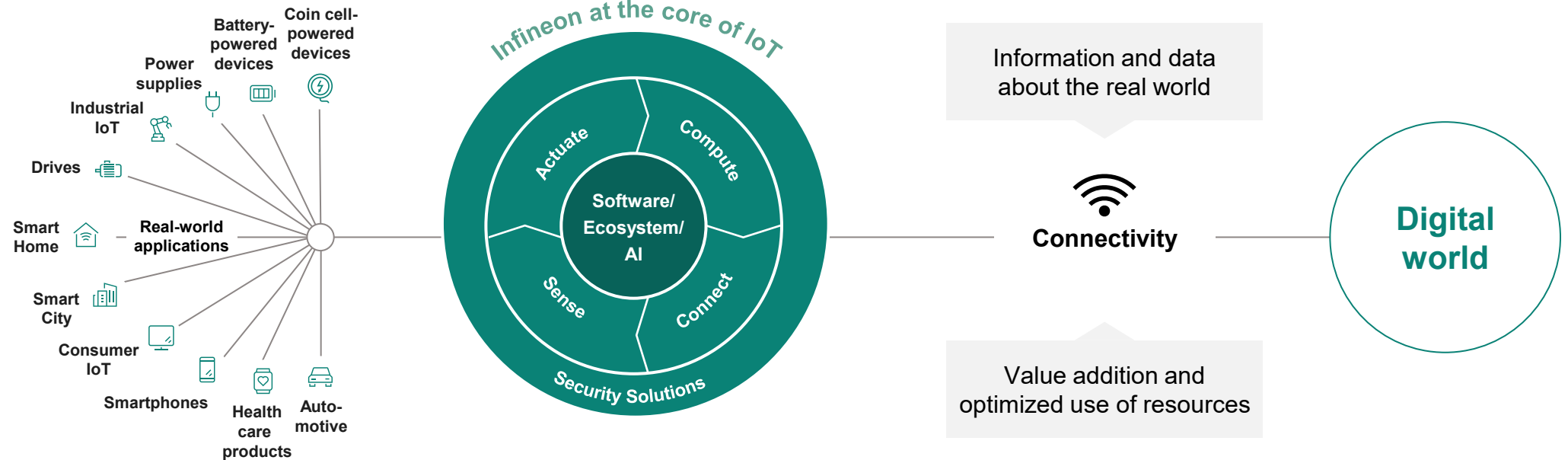
Industrial IoT



Automotive IoT



Products: MCU – Connectivity (Wi-Fi, BLE, NFC) – Sensors – Security – Power supply & switches



Infineon and NVIDIA enable quantum-resilient hardware root of trust for physical AI



Security across the robot lifecycle with Infineon OPTIGA™ TPM and NVIDIA Jetson Thor™

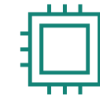
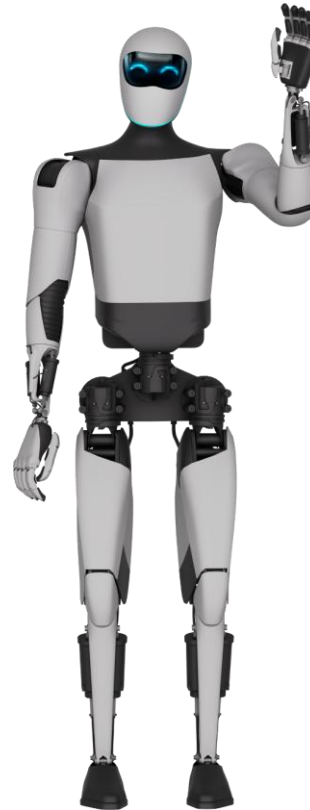
✓ Cryptographic check of software integrity

✓ Physically isolated, certified solution

✓ Secured AI models and encrypted communications

✓ PQC-protected firmware updates

✓ EU Cyber Resilience Act compliant



Platform security and authentication



Secured interactions



Security for tomorrow

ESG: Targets and achievements



Important milestone achieved: The Science Based Targets initiative (SBTi) has approved our CO₂ emission reduction targets

SBTi validation of Infineon's 2030 CO₂ reduction targets marks a major step in our decarbonization journey

- **Scope 1 and 2 targets align with the Paris Agreement, limiting global warming to 1.5°C**
Specifically, Infineon has committed towards SBTi to **reduce** absolute Scope 1 and 2 greenhouse gas (GHG) emissions by 72.5% by 2030 versus the base year 2019.
- **New Scope 3 commitment:** 72.5% of supplier emissions to be covered by science-based targets by 2029.
- **Key reduction measures** include green electricity, energy efficiency, and voluntary GHG abatement.
- Infineon remains **committed to 100% CO₂ neutrality** goal in Scope 1 and 2 by 2030, as announced back in 2020
This will include compensation for the smaller part that cannot be reduced



Our 2030 carbon neutrality goal is aligned with the Paris Climate Agreement's 1.5°C target



CO₂ burden¹

2.7 million tons of CO₂ equivalents



Ratio
~1:53
previously 1:45

CO₂ savings²

143 million tons of CO₂ equivalents

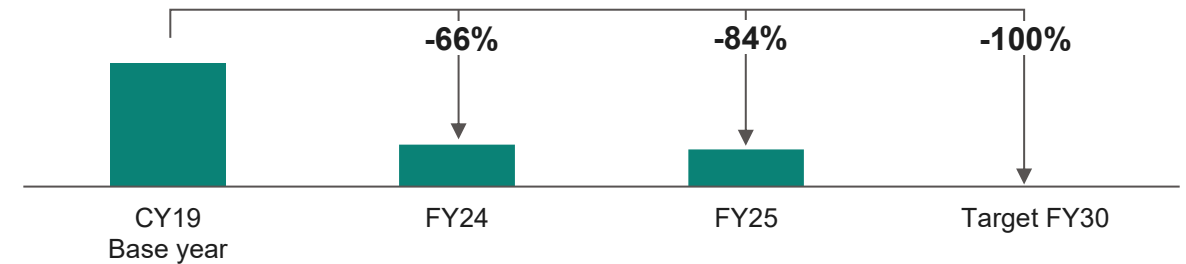


On the road to carbon neutrality³ we achieved significant milestones

- Overachievement of our 70% reduction target for FY2025
- Usage of green electricity in all our sites

Infineon's CO₂ target³ by 2025 and 2030

Net CO₂ emissions in million tons of CO₂ equivalents



» Net ecological benefit: CO₂ emissions reduction of more than 140 million tons

^{1, 2, 3} For further explanation see "ESG footnotes" in the appendix

Our Smart Power Fab in Dresden sets new standards for sustainability



Water management

- Industrial water instead of drinking water for operations
- Water recycling rate to up to 45% by 2033
- 90% of the used water will be returned to the Elbe River in same high quality



Climate tech

- For energy and resource efficiency using artificial intelligence



100% renewable energy

- Smart Power Fab is powered 85% by green electricity and 15% by district heating
- Fab operates entirely without natural gas
- Up to 45% of our energy recovery



LEED certification

- Aiming for the Leadership in Energy and Environmental Design (LEED) certificate as Infineon's first production facility
- Supports Infineon's overarching goal of being CO2-neutral by 2030

External recognitions confirm our engagement in contributing to a sustainable society

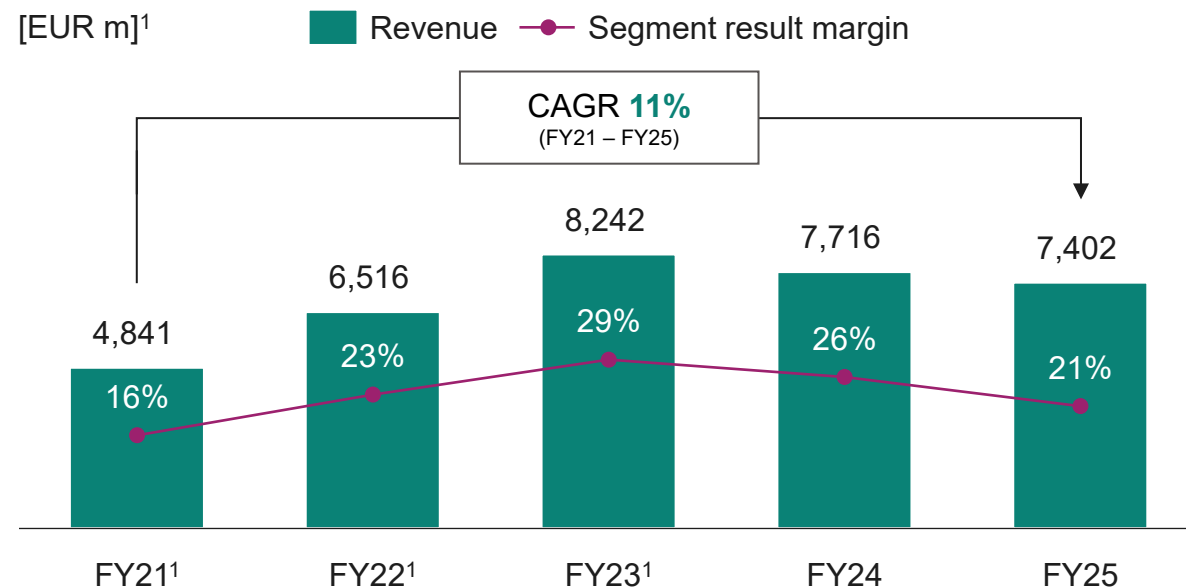
	Rating/Score	Scale	Date
 MSCI ESG	AA	CCC to AAA	04/2026
 CDP	B climate scoring B water scoring	F to A	01/2026
 Ecovadis	99th percentile “Platinum” award	0 to 100	08/2026
 Dow Jones Best-in-Class Index	Dow Jones Best-in-Class World & Europe Index listing	-	04/2026
 ISS ESG Corporate Rating	Prime Status	-	04/2026
 FTSE4Good Index	Index member	-	07/2026
 Sustainalytics	ESG low risk	-	01/2026

Automotive



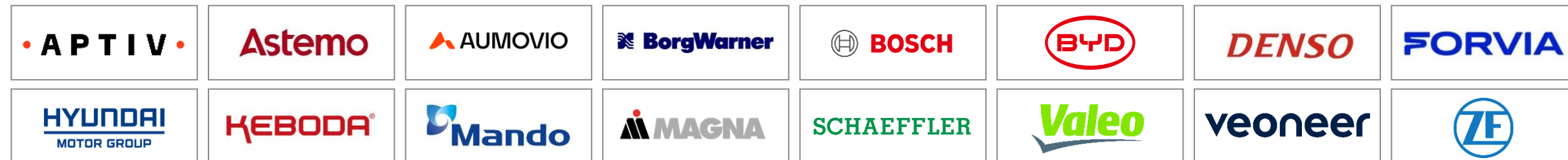
ATV at a glance

ATV revenue and segment result margin

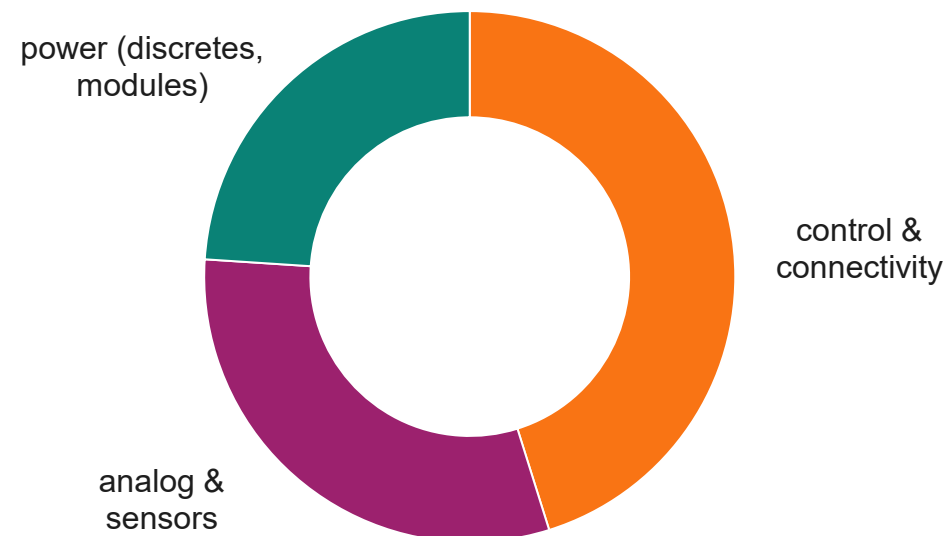


¹ Transfer of "Sense & Control" business line from ATV to PSS from 1 January 2025 onwards not reflected in prior year numbers

Key customers



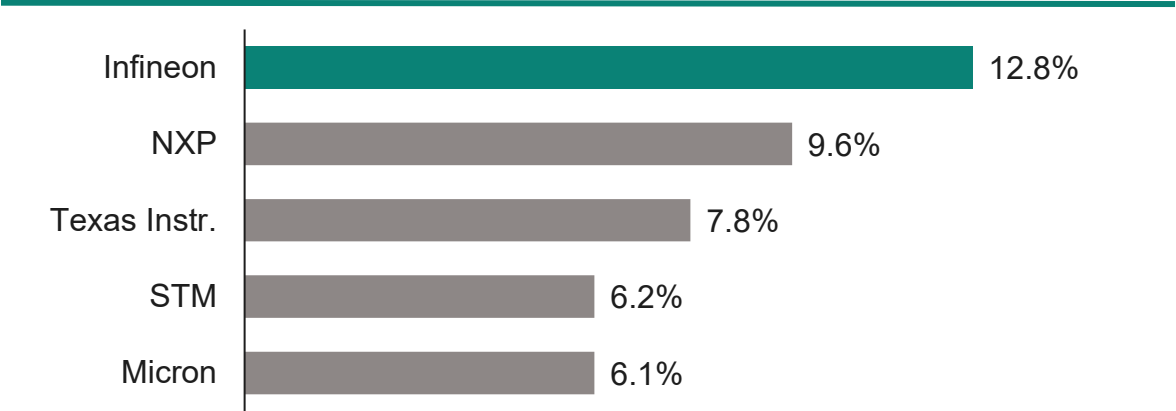
FY25 revenue split by product group



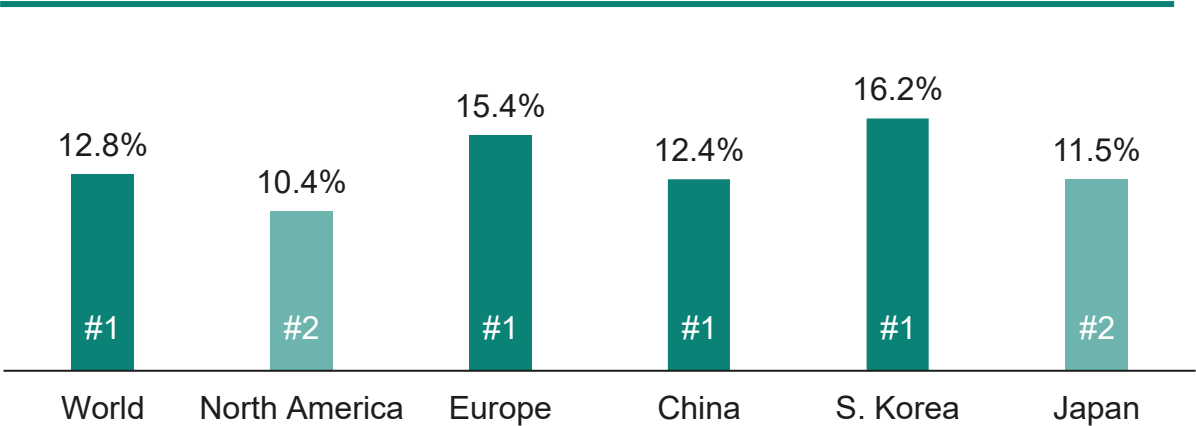
Infiniteon's top market position is built on system competence based and an industry-leading product portfolio



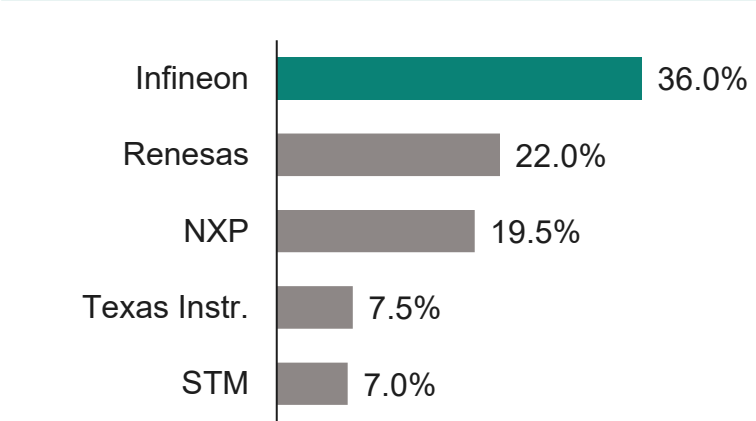
Automotive semiconductors (2025 total market: \$74,408m; +6.4% y-y)



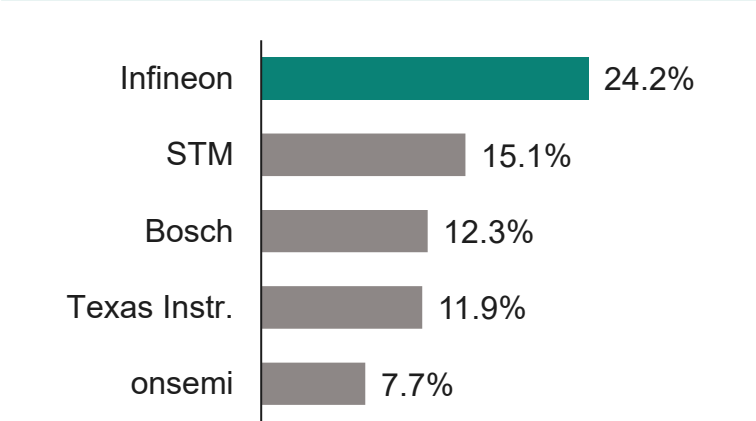
Infineon's 2025 market share and position by region



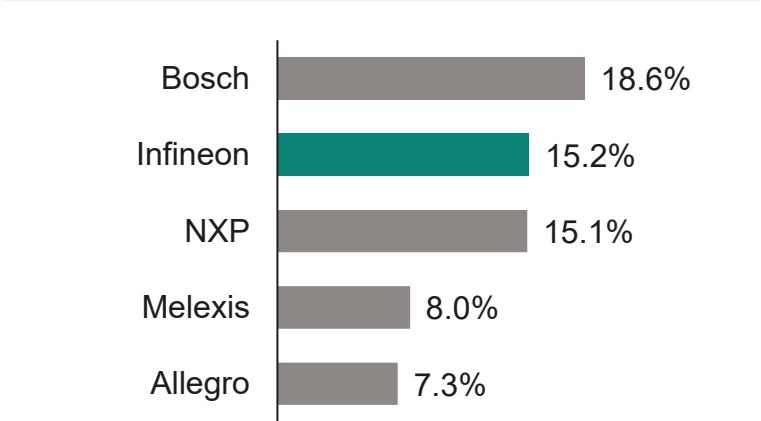
MCUs



Power



Sensors¹



TechInsights: Automotive Semiconductor Vendor Market Shares. April 2026. ¹ Sensors: Mobility Global: Automotive Semiconductor Market Shares 2025. April 2026.

Several strong content growth drivers for Infineon in xEV and software-defined vehicles, even at flat LV production

Structural trends fueling our growth

xEV

- Strong volume growth of BEVs and PHEVs
- Increasing share of SiC in traction inverters
- More kW per vehicle lead to higher BoM in inverter

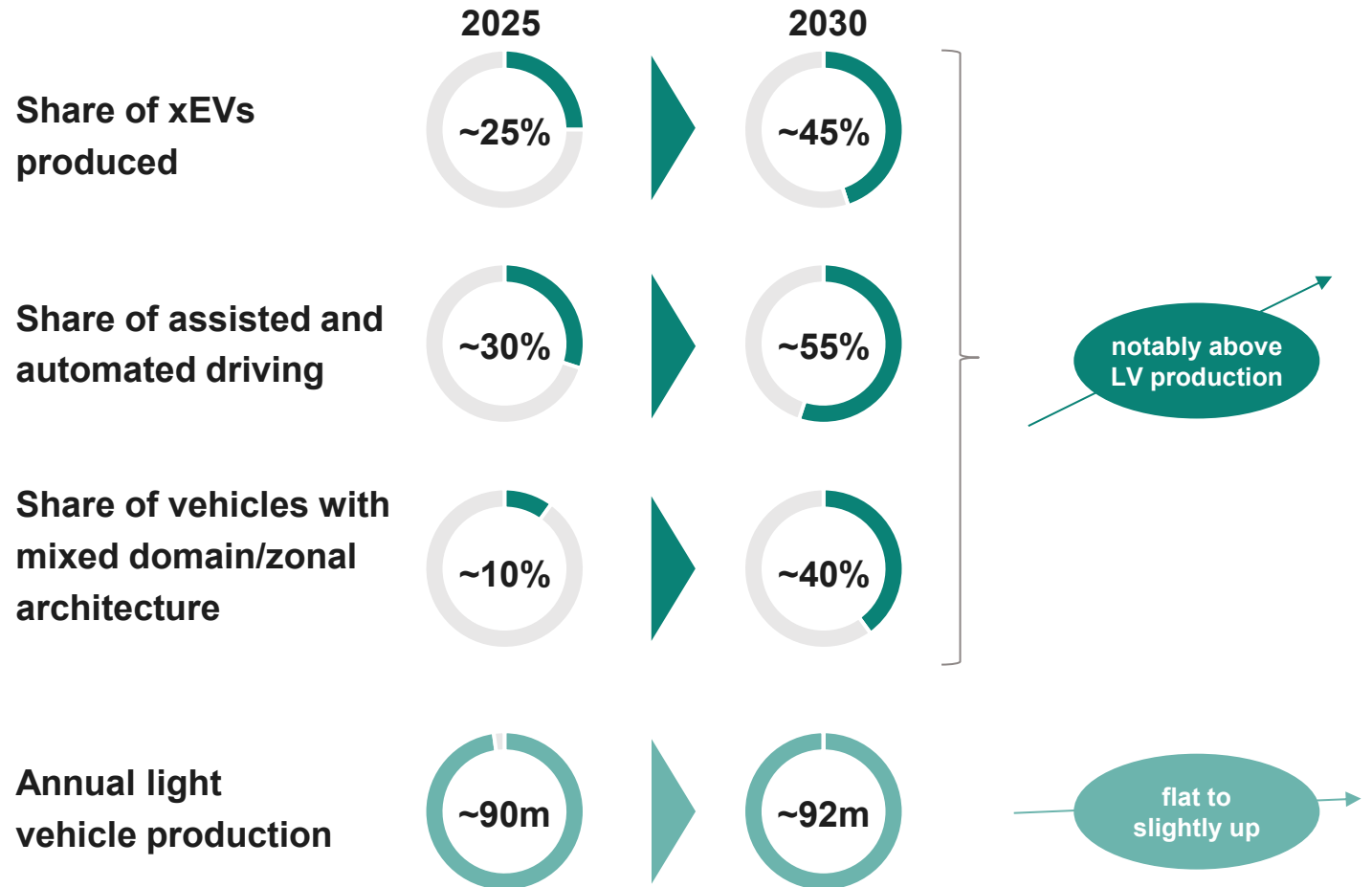
SDV

- Transformation of E/E architecture towards central computing with zonal controllers
- Smart switches for decentralized power distribution
- Software over the air
- Secure connectivity, cybersecurity indispensable
- Functional safety, dependable electronics, redundancy
- ADAS/AD: More sensors, more computing performance

Comfort and premium features

- More loads (motors, heating, cooling etc.)
- More elaborate lighting, both exterior (matrix light) and interior (instruments and ceiling)

Overview of growth vectors until 2030

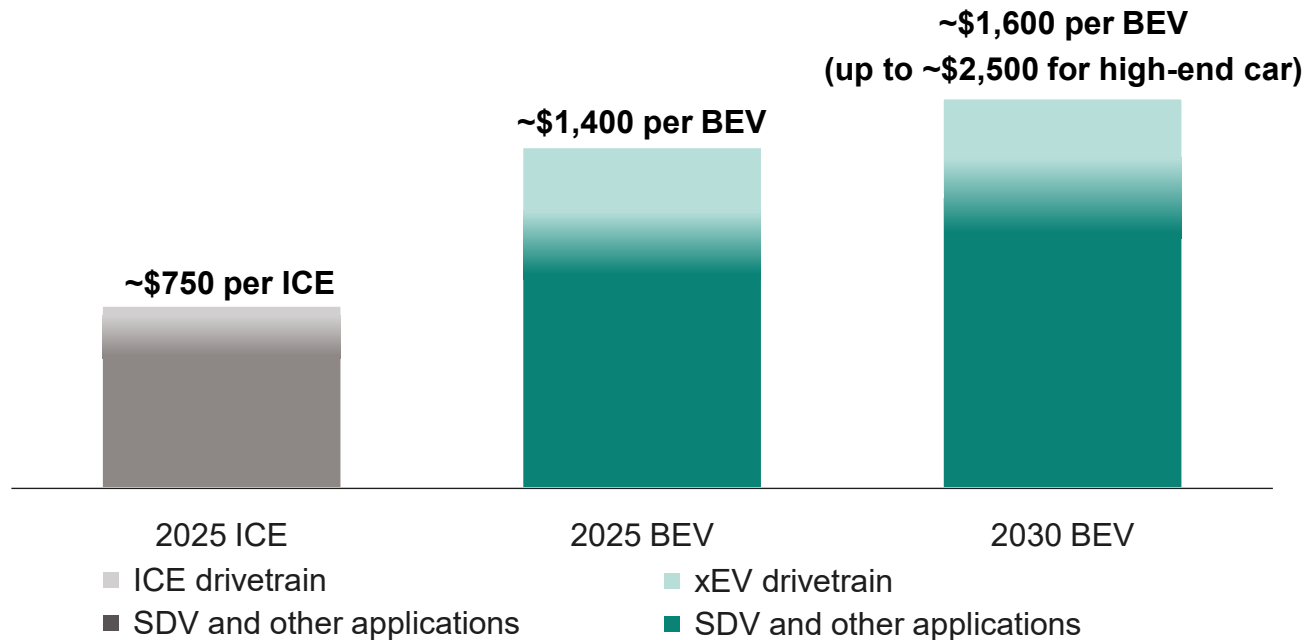


Infineon estimates

Infiniteon is the world leader in automotive semis, serving all key applications and benefiting strongly from content growth



Average semiconductor bill-of-material per car in 2025 and 2030



Semiconductors covered by Infineon

Drivetrain applications:

- Traction inverter, OBC, DC-DC, BMS, auxiliaries
- Drivers for BoM increase:
 - SiC and GaN replacing Si
 - more motors and stronger motors per car
 - slight increase in kW per car

SDV and other non-drivetrain applications:

- Domain/Zone
- SDV, incl. E/E architecture and ADAS
- Safety and advanced security
- Comfort and premium
- Connectivity and infotainment

BEV market size growth (vehicle production)

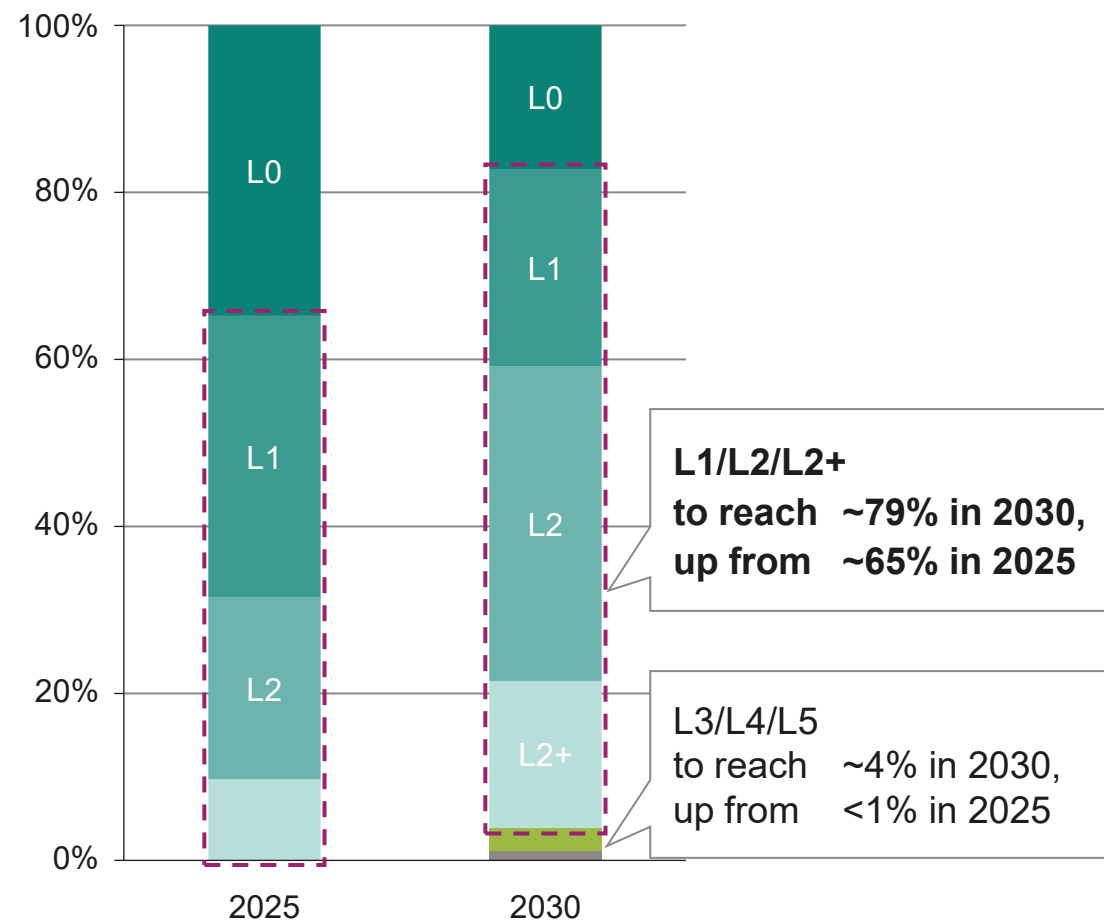


With a growing xEV market and growing non-drivetrain BoM, Infineon profits twice

Infineon estimate based on S&P E/E & Semiconductor Service dataset – October 2025; November 2025

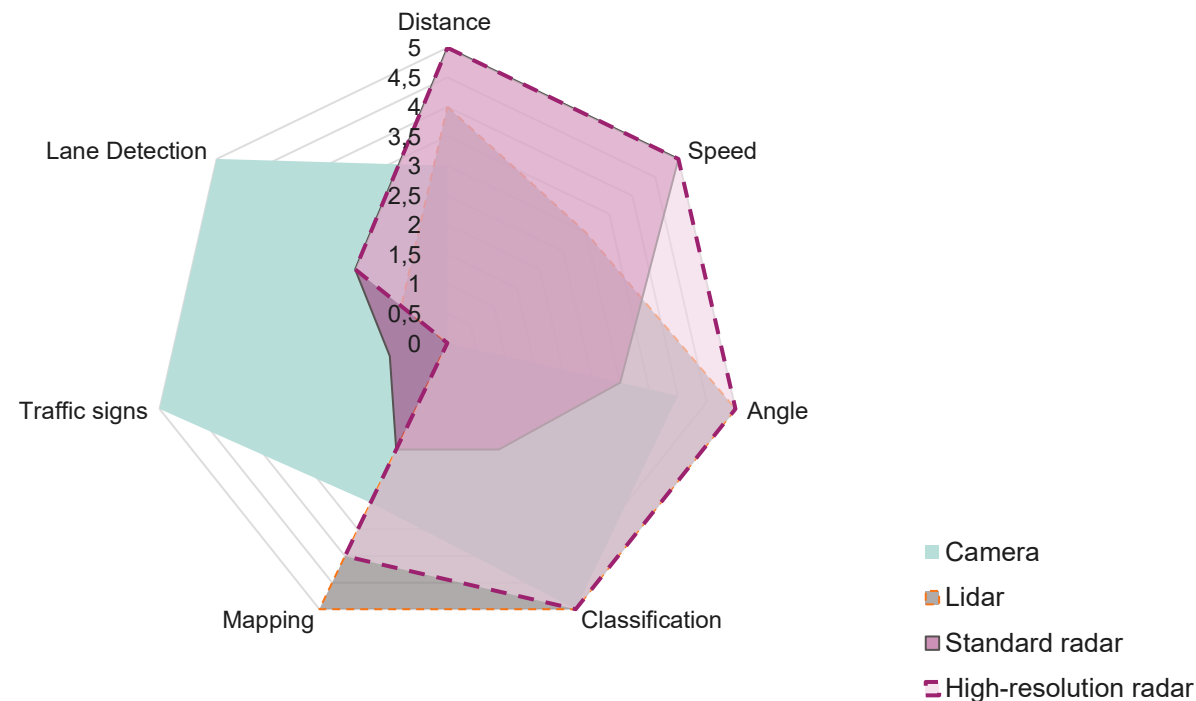
Growth of L1/L2/L2+ is the main driver of ADAS semiconductor content until 2030

Car production by degree of automation (SAE level)



Market research companies; Infineon

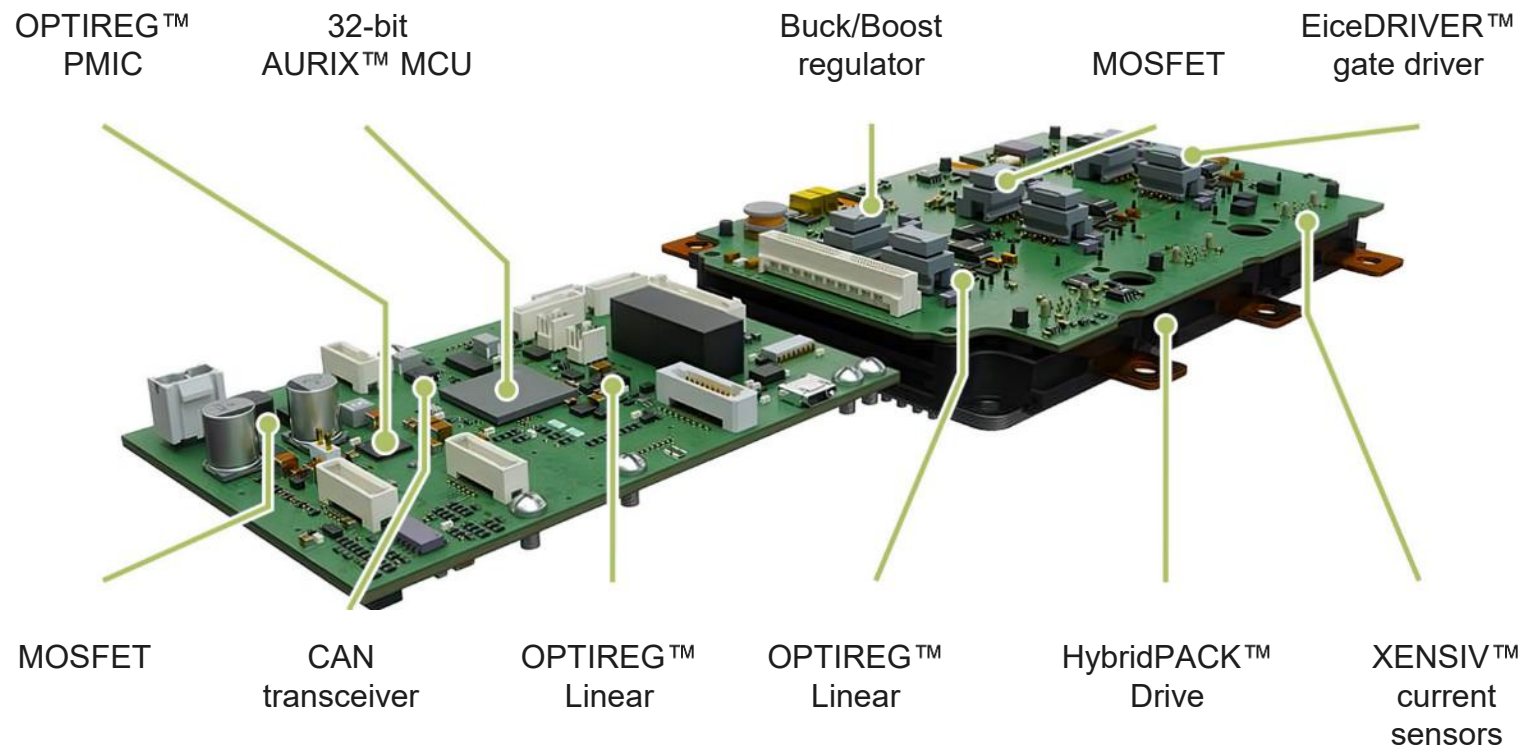
Radar is essential to meet decisive requirements of ADAS/AD



- Standard radar is the technology to detect distance and speed
- High-resolution radar significantly improves angle and classification

Infiniteon's broad product portfolio and system understanding enable higher BoM and allow compact designs and fast T2M

Infineon inverter reference design, covering up to 95% of value



P2S (product-to-system approach)

- Reference design for up to 300 kW, further customization possible
- System solution for easy implementation
- Fast time-to-market (T2M)

Freedom of choice

- IGBT and SiC in 750/1,200 V scale up to preferred power class
- HybridPACK™ Drive CoolSiC™ Gen2 continuous operation at 175°C
- EiceDRIVER™ gate driver Gen3 optimized for CoolSiC™
- Optimized 32-bit AURIX™ MCU

Infineon AURIX™ TC4x with integrated PPU brings AI-on-the-edge to the battery



Battery cost

Battery health

Charging speed

Safety concerns

Range anxiety

**Resale value,
residual value**

**Cloud dependencies
(latency, cost, stability)**

AURIX™ TC4x

PPU

(parallel processing unit)



High computing performance with complex and accurate BMS algorithms

- AI-based battery diagnostic on-the-edge
- temperature model, electro-chemical model
- lithium plating detection
- remaining useful life prediction
- with and without cloud-based updates
- Product-to-System!

Efficient battery cell utilization

- Higher capacity
- Less cells
- Lower battery cost

Faster charging

- Higher user experience

Assure longevity, extended guarantee

- Longer lifetime (in years, in km)
- More charging cycles

Detect and prevent thermal runaway

Accurate battery, health prediction

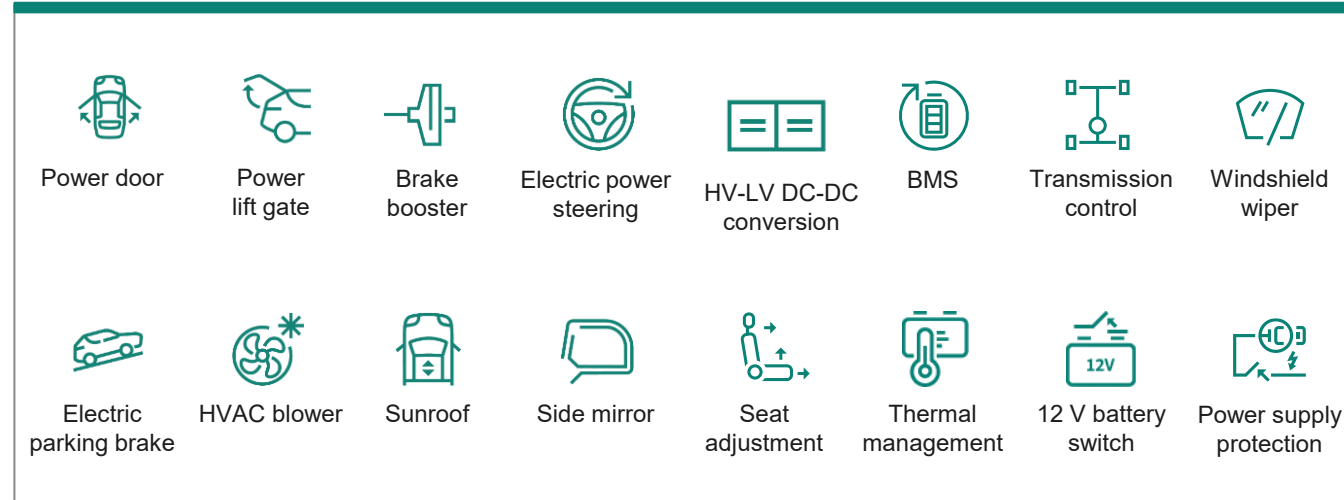
» **Trust in resale market**

- Higher economic value
(impacting insurances, fleets, OEMs, Tier1s, 2nd life market)

Open to partner up with further OEMs, Tier1s, insurance companies

Number of power MOSFETs per car continues to increase, and drives accelerated growth for the leading portfolio

Examples of MOSFET applications



Latest portfolio with constant innovation

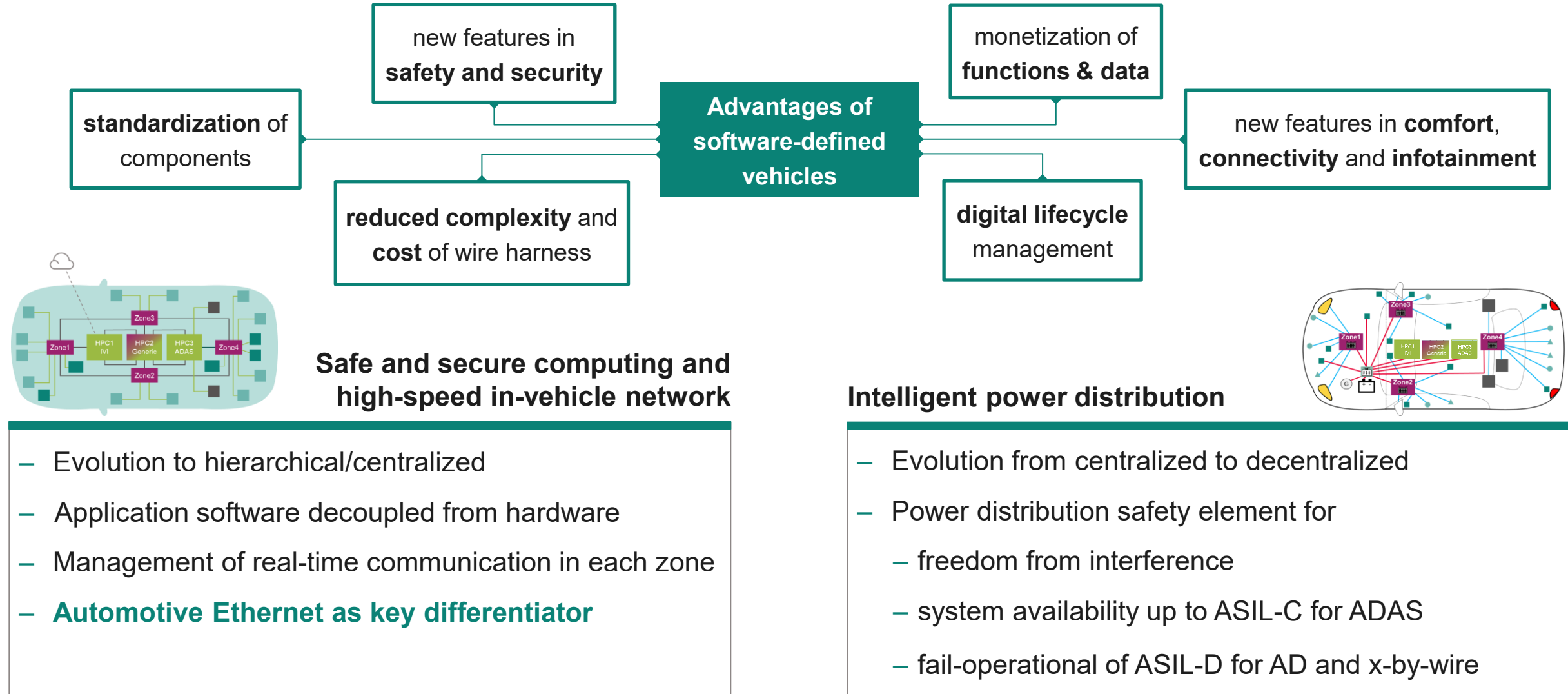
Technologies, packages and voltages

OptiMOS™ 7		40 V	
OptiMOS™ 6		60 V	
OptiMOS™ 5		80 V	
OptiMOS™ T, T2, Gen 12.7		100 V	
		120 V	

New **OptiMOS™ 7** family with outstanding technical performance

- 100 to 180 MOSFETs are used per vehicle in ~90 different applications in all segments: body, chassis, safety, ADAS/AD, powertrain
- Infineon offers broadest portfolio (>600 products) and eco-system to address specific and high-margin applications:
 - embedded control, gate driver, MOSFETs, software, P2S
 - entire eco-system with digital twins
 - simulation environment (esp. for motor control)

Software-defined vehicles are enabled by safe/secure computing, high-speed in-vehicle networks, and intelligent power distribution



The Automotive Ethernet portfolio strengthens our market leading MCU position and increases offering for zonal architectures

Infineon's unique portfolio of MCU and Ethernet

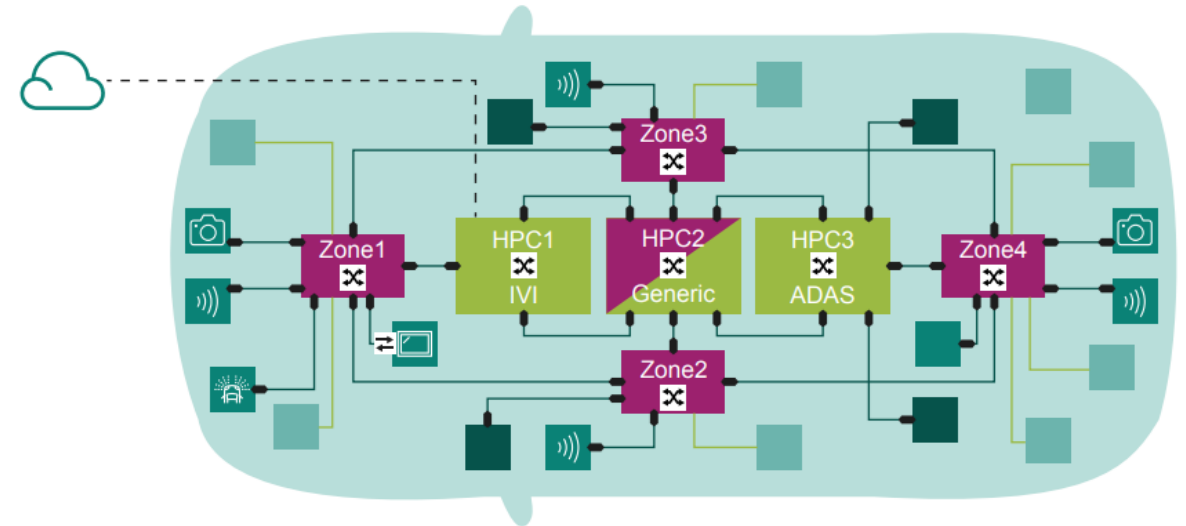
Automotive MCUs



Automotive Ethernet



Components of hierarchical E/E architectures:



High Performance Computing (HPC) Complex sensors & actuators

Simple sensors & actuators Zone controller Control ECU

Scope of Acquisition



PHY



Bridge



Switch

Ethernet

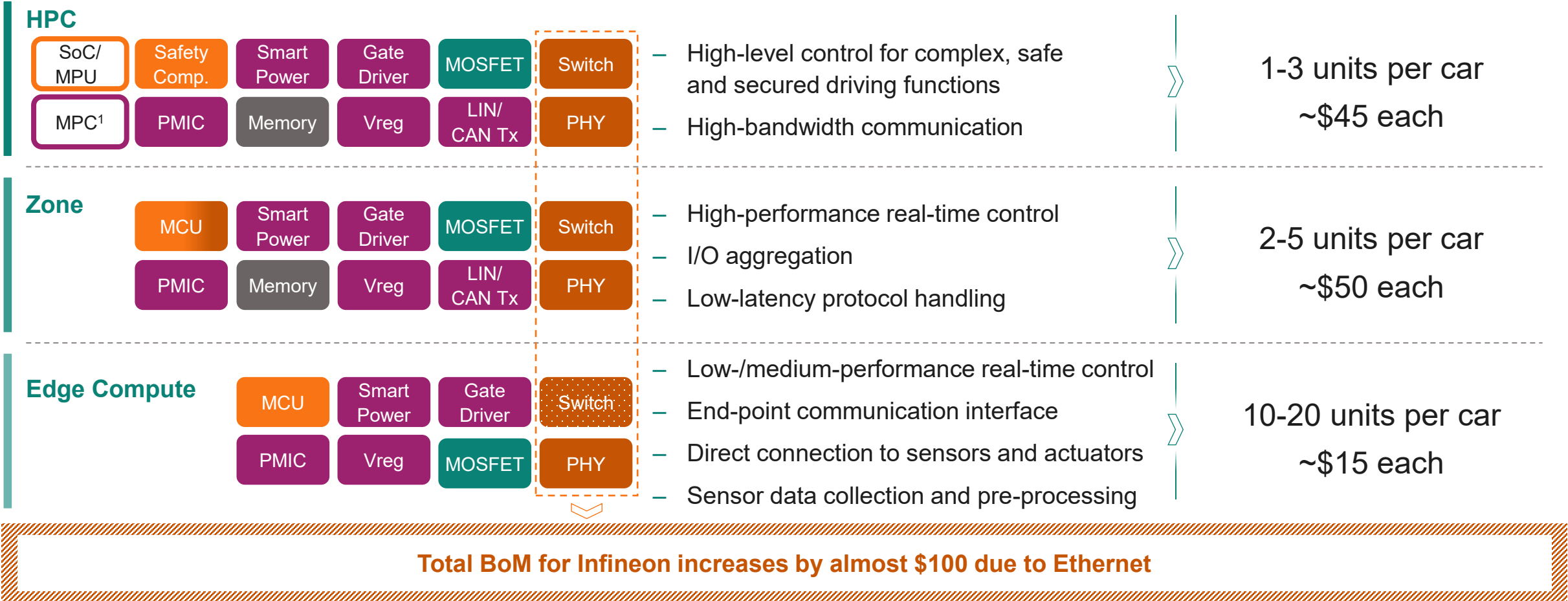
Low-bandwidth network

Infiniteon's extended portfolio contributes essentially to SDV as the second growth pillar alongside e-mobility



Infineon components for hierarchal computing E/E architecture

Infineon BoM potent.: ~\$500



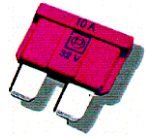
¹ Digital multi-phase controller for SoC/MPU Control Analog Memory Power Ethernet Component if needed Not part of Infineon portfolio

Smart semiconductors in power distribution systems are key enabler for SDV while ensuring high availability and resilience

Infineon PROFET™ Wire Guard enables SDV



Relay
replacement



Fuse
replacement



Load status
diagnostics

Switch

Protect

Diagnose

e.g. PROFET™ Wire Guard



ISO 26262
compliant

Fast failure isolation
($< 500 \mu\text{s}$)

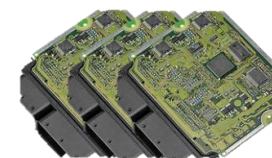
Central fuse box + many individual ECUs



- Big and heavy
- Complex wire harness
- High power loss
- Risk of interference



Decentral zone ECUs



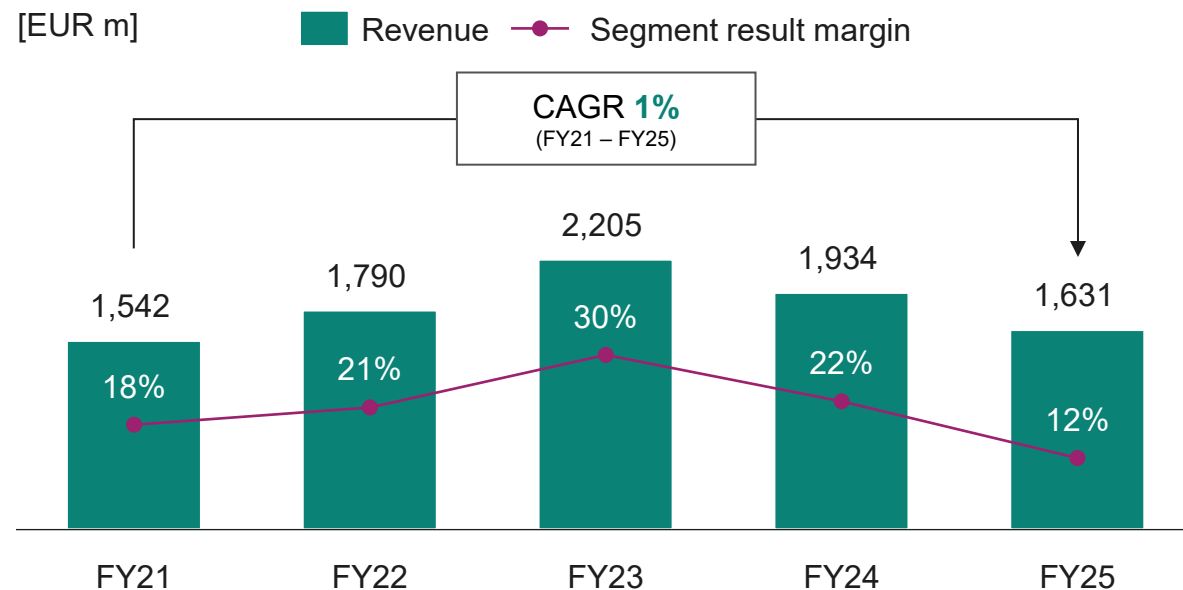
- Light and small
- Simplified wire harness
- Power efficient
- Freedom from interference
- Design flexibility
- Enable ADAS/AD, x-by-wire

Green Industrial Power

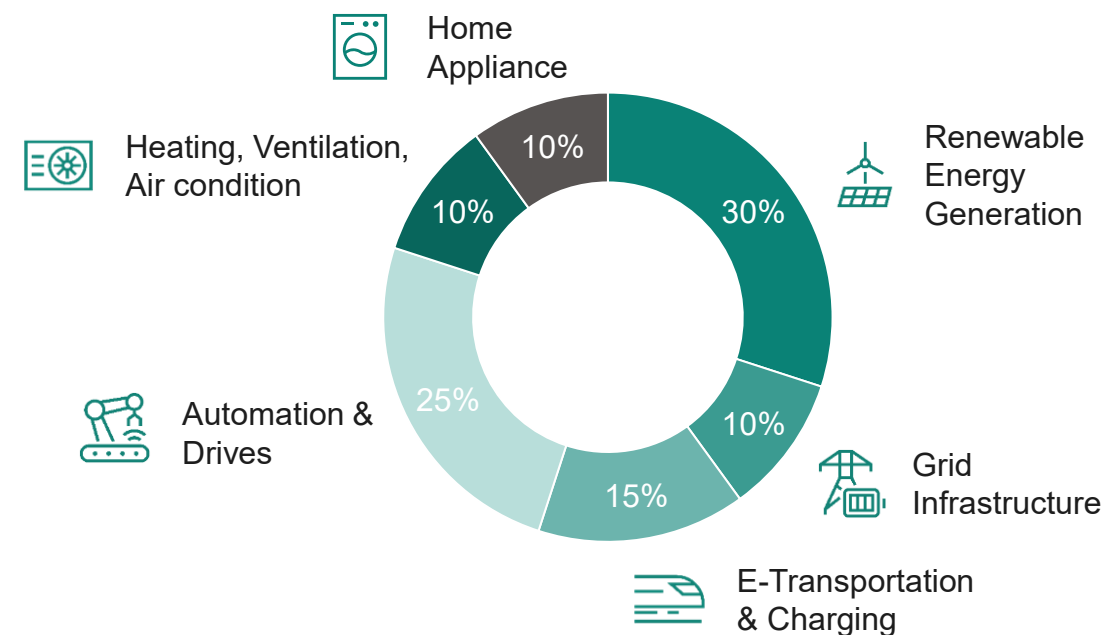


GIP at a glance

GIP revenue and segment result margin



FY25 revenue split by application



Key customers



Huge potential along entire green energy chain until 2030 according to IEA Net Zero scenario



Generation

	Photovoltaic	+ 10,300 GW
	Wind power	+3,300 GW

Infrastructure

	Grid network	\$600bn annual investments
	Grid storage	+2,100 GW
	EV charging	+110m chargers (public and private)
	Electrolysis	+560 GW

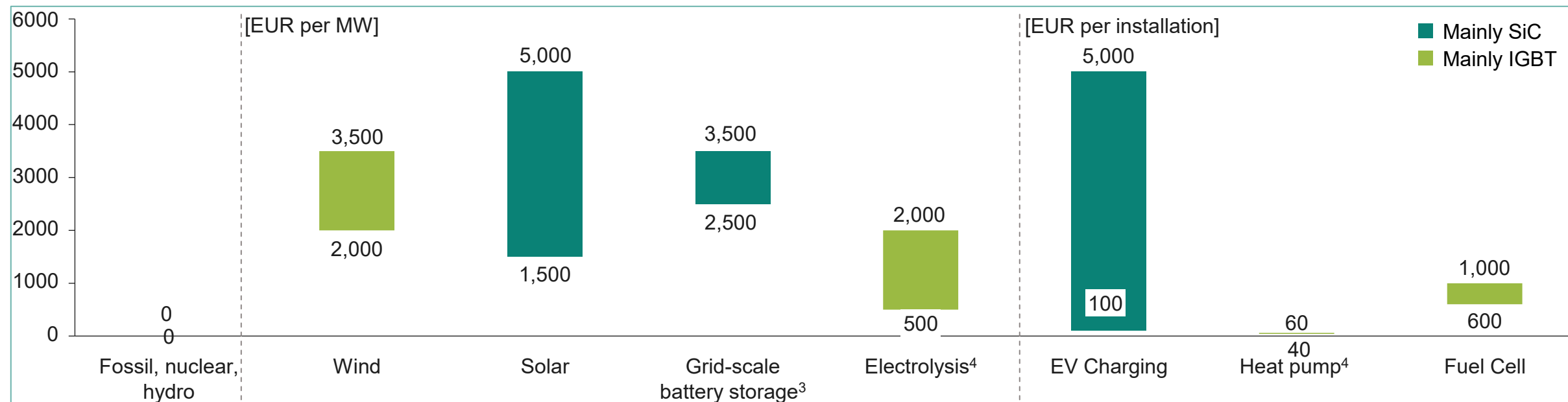
Consumption

	Heat pump	+420m units
	H ₂ Fuel cell ¹	+200k FC EV +200k FC Trucks
	eAviation eMarine	

Note: Based on Net Zero Scenario (IEA) | Source: IEA - World Energy Outlook, November 2025, OMDIA Power Semiconductors in EV Charging Infrastructure - 2025 ¹ Internal Analysis

Green energy generation provides large business opportunities

Power semiconductor content by application



Additions in 2024 ¹	115 GW	538 GW	62 GW	<1 GW	~6m inst.	22m inst.	5k inst.
CAGR 2024-35	13%	17%	30%	92% ²	31%	16%	42%

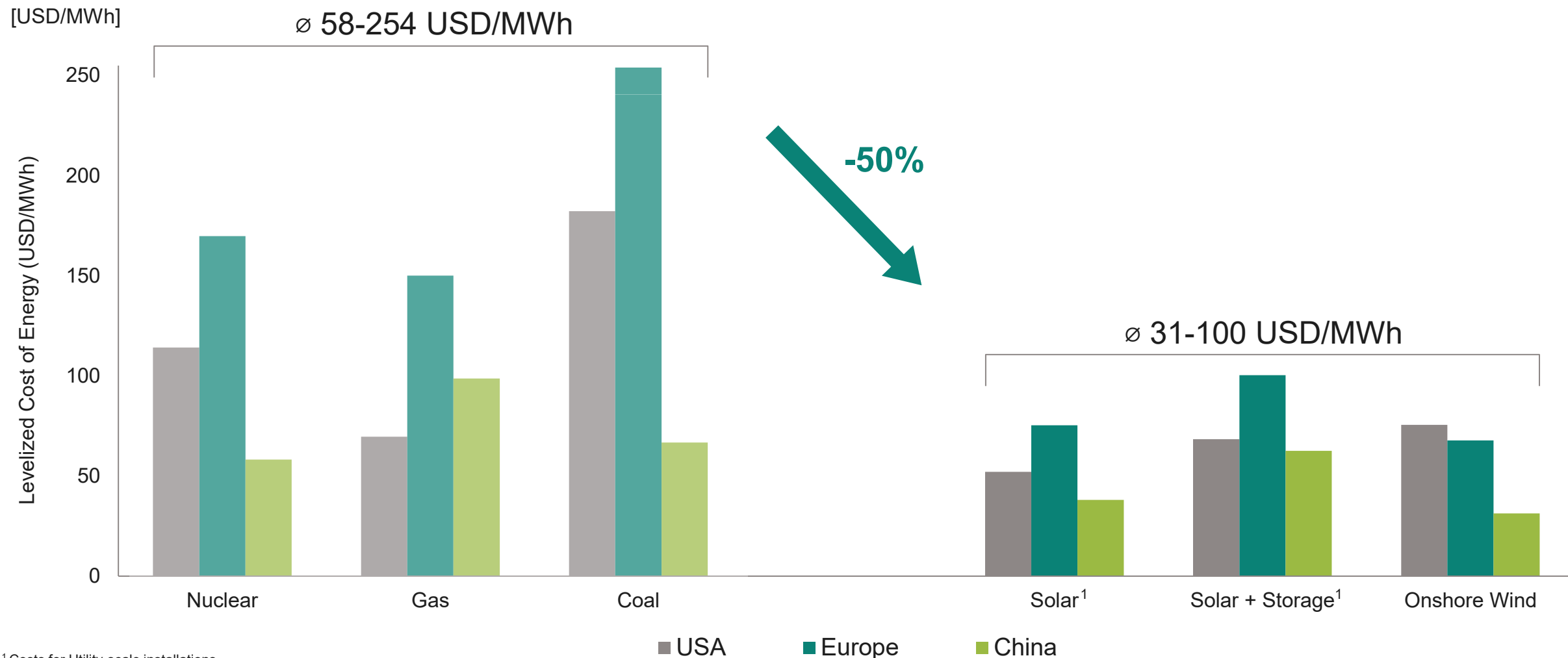
¹ IEA: World Energy Outlook, November 2025; Sector Tracking reports October 2023; internal Analysis

² Based on 270 GW pipeline (midpoint), >100% based on NZE requirements of 560GW

³ Based on assumption 80% of total battery storage equals Grid-scale battery storage

⁴ Additions in 2022, CAGR 2022-2030

Renewables are on average the cheapest source of energy

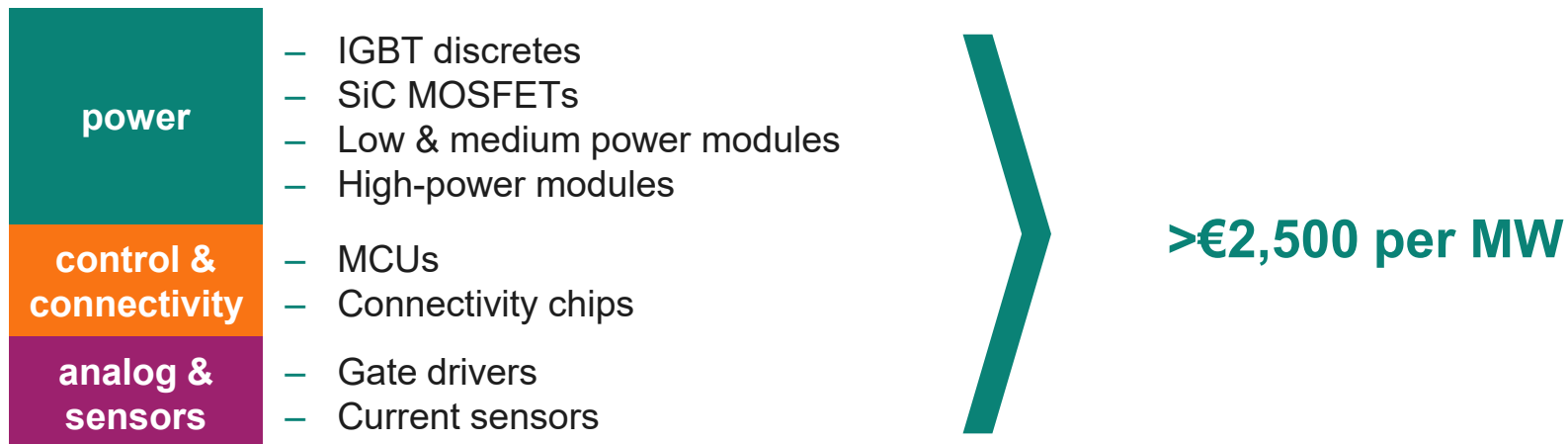


¹ Costs for Utility-scale installations

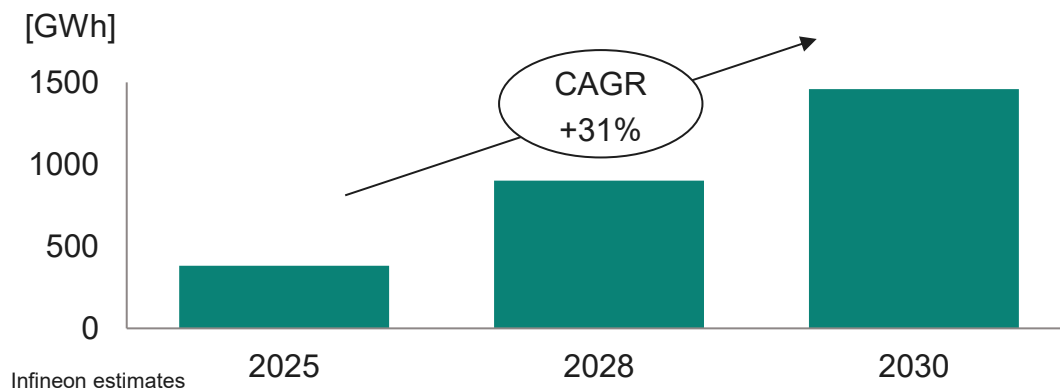
Based on Wood Mackenzie LCOE Levelized Cost Of Energy dataset, 2024

Commercial and Utility Storage Solutions with strong growth potential

Infineon's semiconductor content for energy storage solutions (ESS)



Global ESS battery shipment forecast



Close engagement with key players

- ESS inverter companies
- System integrators
- Battery OEMs



Solid-state transformers: new application for semiconductors with significant additional market potential

Conventional transformer



Conventional transformer market
>USD 15bn

Solid-State transformer (SST)



Infineon expects that **SST will replace a portion of the market**, specifically small power transformer with an expected market of **>USD 1bn in 2030**

SiC

EasyPACK™



Early involvement with leading electronics companies and hyperscalers on architecture & design in Europe, Americas and Asia, e.g:



¹ Comparison refers to multi modular inverter (dual stage with HFT) based on own estimations.

Solid-state circuit breakers: increased safety, energy efficiency and reliability in power distribution

Analog circuit breaker

Traditional electromechanical analog circuit breakers protect electrical circuits against overloads and short circuits.



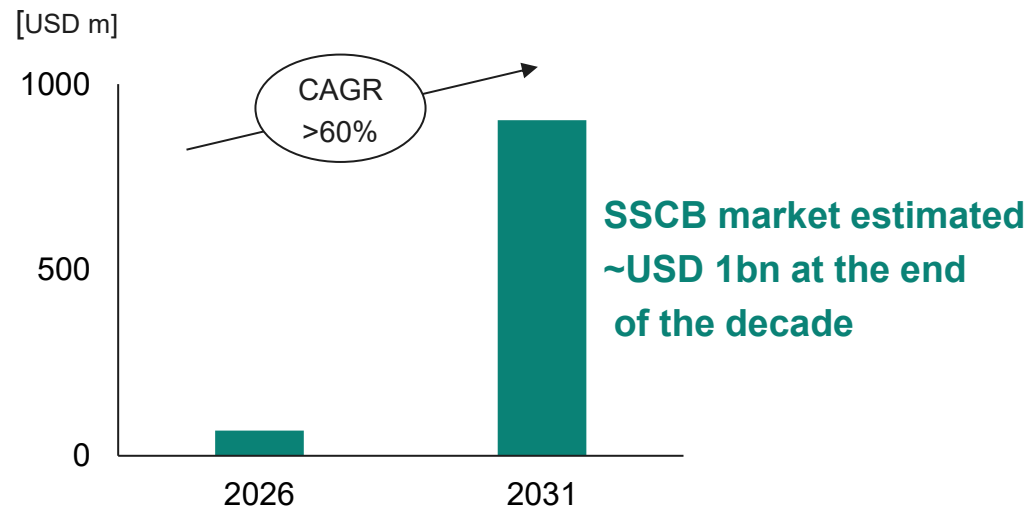
Digital solid-state circuit breaker (SSCB)

Enables **smart energy management**:

- Ultra-fast overload and short circuit **interruption**
- Integrated **monitoring**
- **Remote control**



Solid-state circuit breaker market



SSCB for direct current power grids



SENTRON 3QD2 SSCB
© Siemens AG

SSCBs interrupt current 1,000 times faster than conventional systems. This is essential for direct current grids like in AI data centers to omit costly downtime, data loss or expensive hardware damage.



Adding CoolSiC™ JFET to MOSFETs:

Infineon offers most comprehensive SSCB portfolio in the industry



Sampling now, start of
production in 2026



Q-DPAK with CoolSiC™ JFET



More than 20 SSCB key
customers and
first Design-Wins
with CoolSiC™ JFET



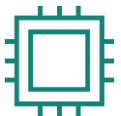
Energy savings

- ✓ Provides ground-breaking ultra-low $R_{DS(on)}$ 1.5 m Ω at 750 V and 2.3 m Ω at 1200 V V_{BDss}



Robustness and reliability

- ✓ Designed and tested to handle extreme over-voltage, over-current and short-circuit conditions



Integration and scalability

- ✓ Developed for ease-of-integration, scalability and manufacturability for industrial and automotive applications

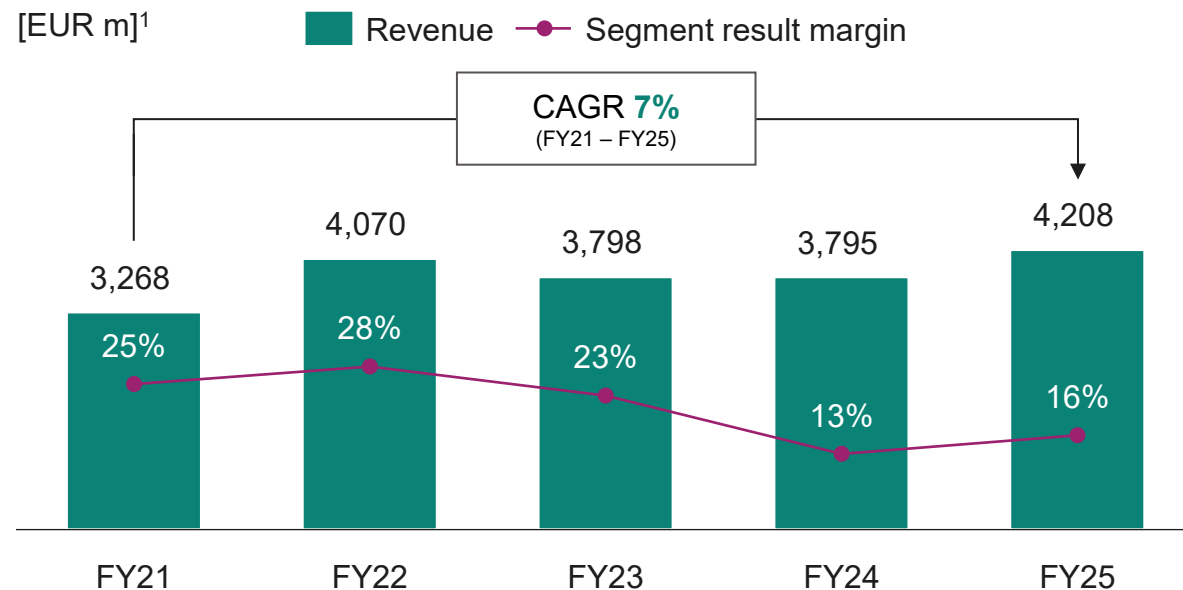


Power & Sensor Systems



PSS at a glance

PSS revenue and segment result margin

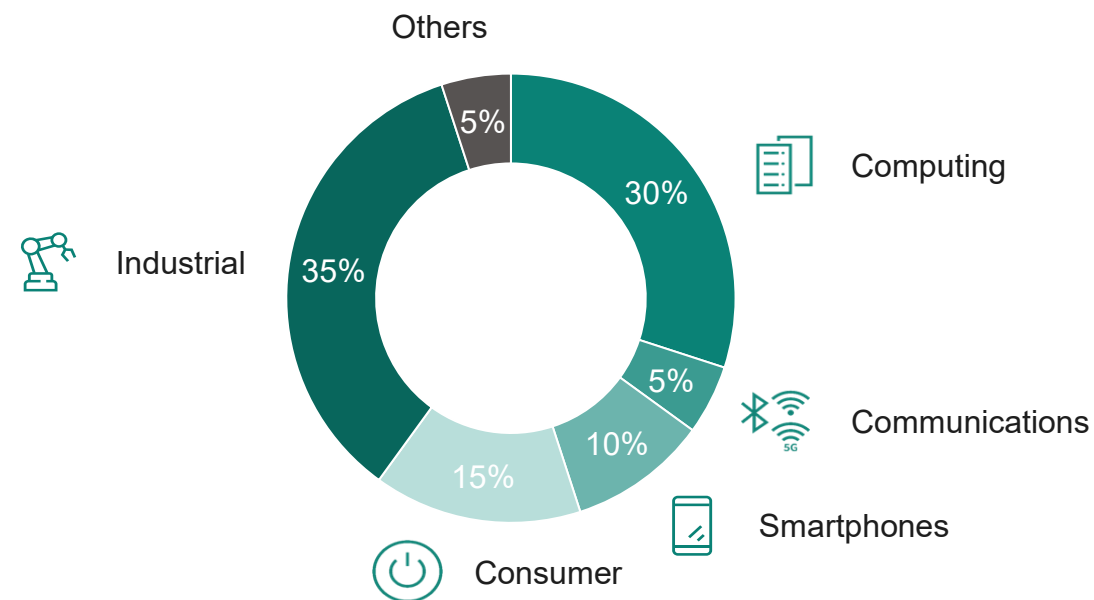


¹ Transfer of "Sense & Control" business line from ATV to PSS from 1 January 2025 onwards not reflected in prior year numbers

Key customers



FY25 revenue split by application

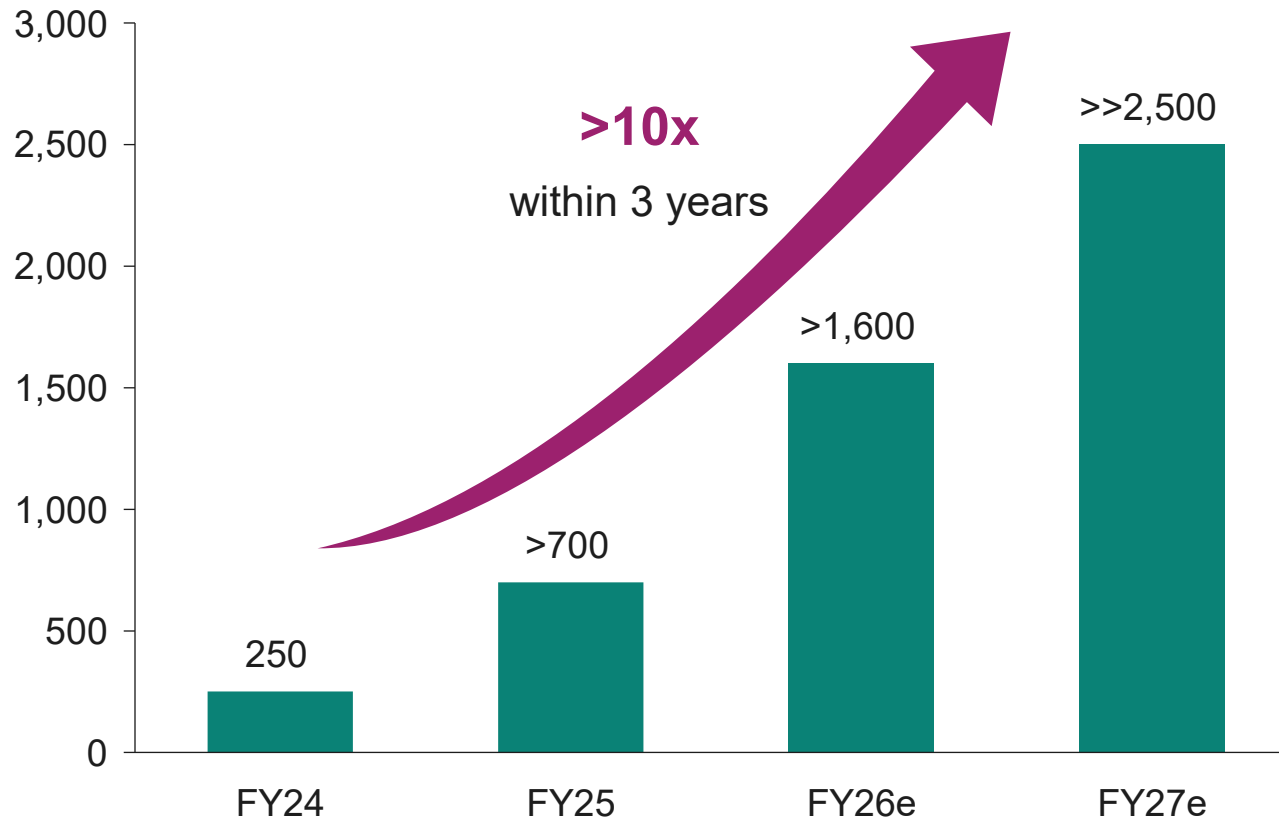


Significant acceleration of our AI revenues due to most advanced technology and broadest portfolio

Infineon is growing together with customers driven by significant AI investments

Revenues from powering AI datacenters

[EUR m]



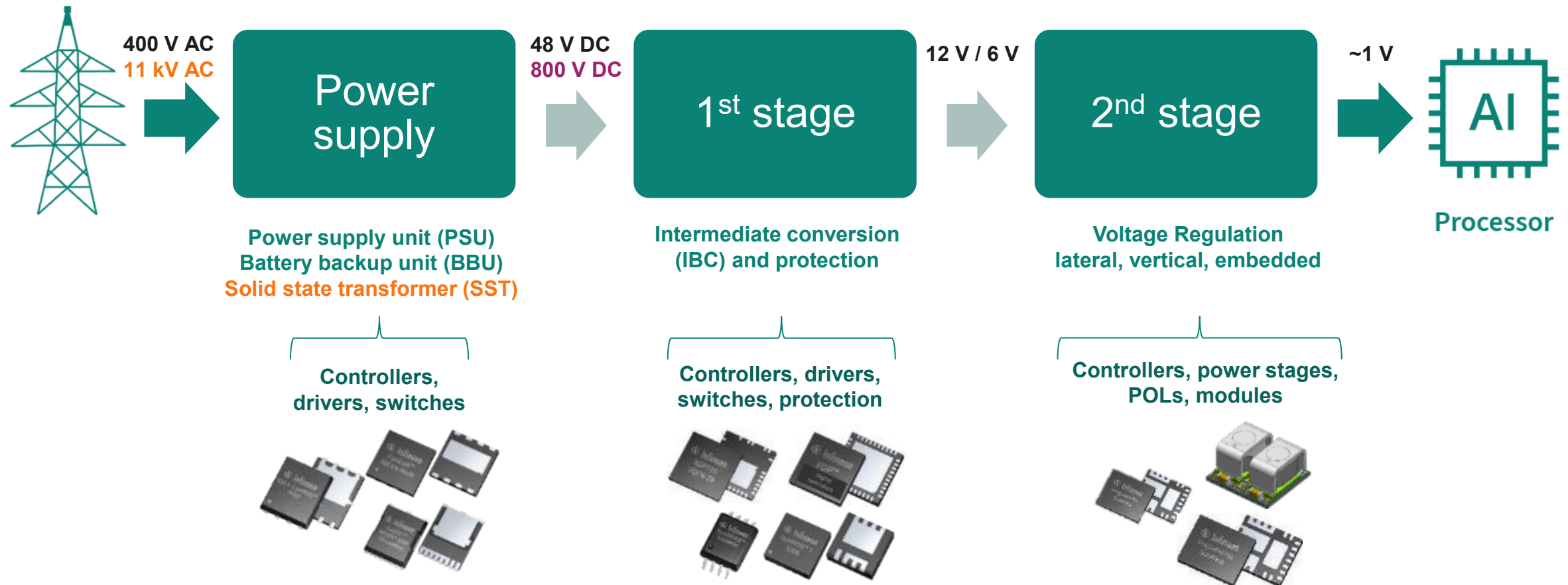
In **FY25**, our AI server business achieved **>€700m** nearly **tripling** vs. FY24

We expect to **more than double** our revenue to **more than €1.6bn** in **FY26** and will materially upgrade our projection of **€2.5bn** for our **2027 fiscal year**

Infineon AI **power content** per kilowatt in the range of **\$100-250**
\$175/kW average today

With its energy efficient power semiconductors Infineon is serving all AI-related power conversion from grid-to-core

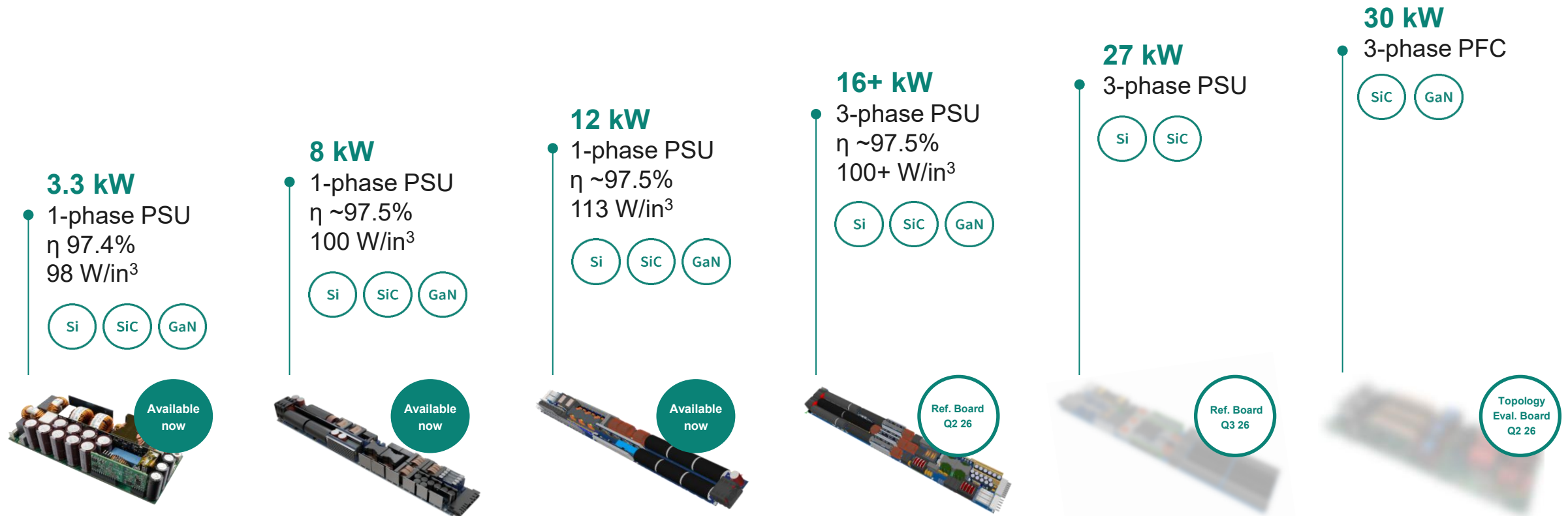
Server power flow for Gen 1 / Gen 2 / Gen 3 server rack architecture



Innovative 3-phase PSU system solutions leverage system expertise and IP to deliver industry-leading performance and efficiency



Infineon's solutions range from 3 kW to 30 kW



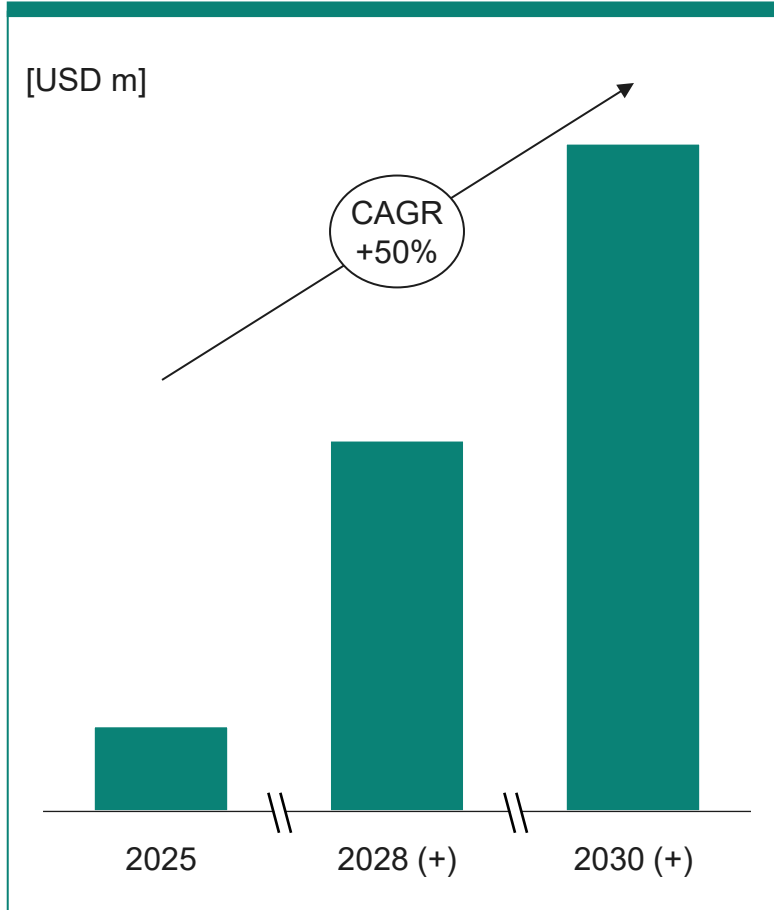
Rising power demands require the transition to advanced three-phase PSU architectures

1-phase PSU

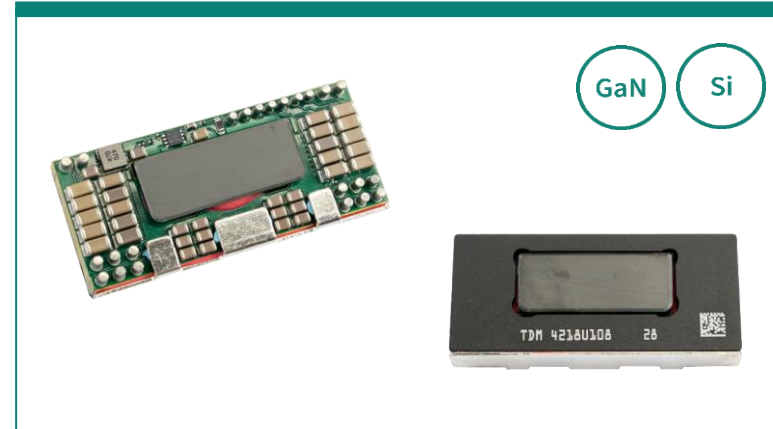
3-phase PSU

Infinion offers a broad portfolio of HV & MV IBCs for current and future AI server rack architectures

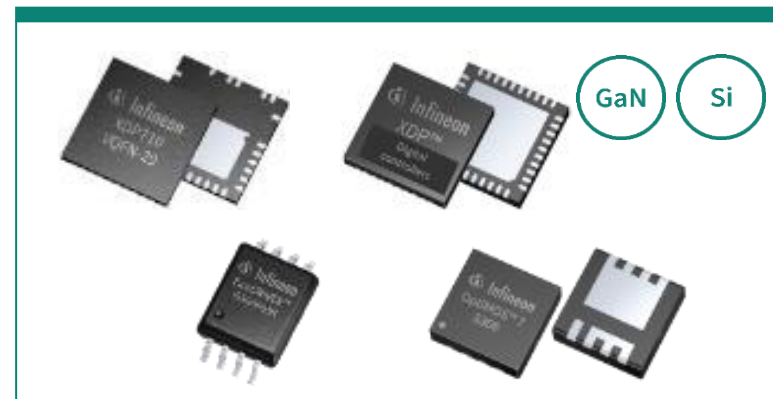
SAM IBC Market



Infinion IBC Module for AI



Discretes

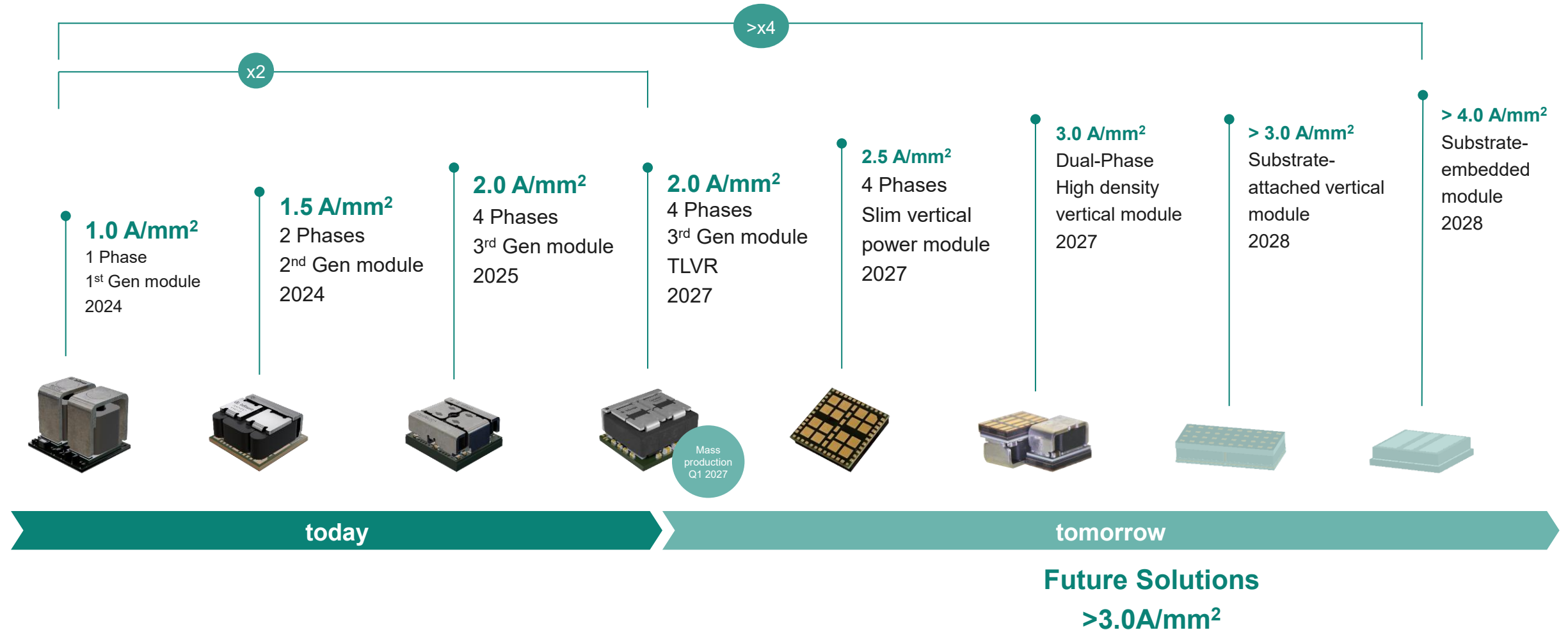


Meeting customer requirements

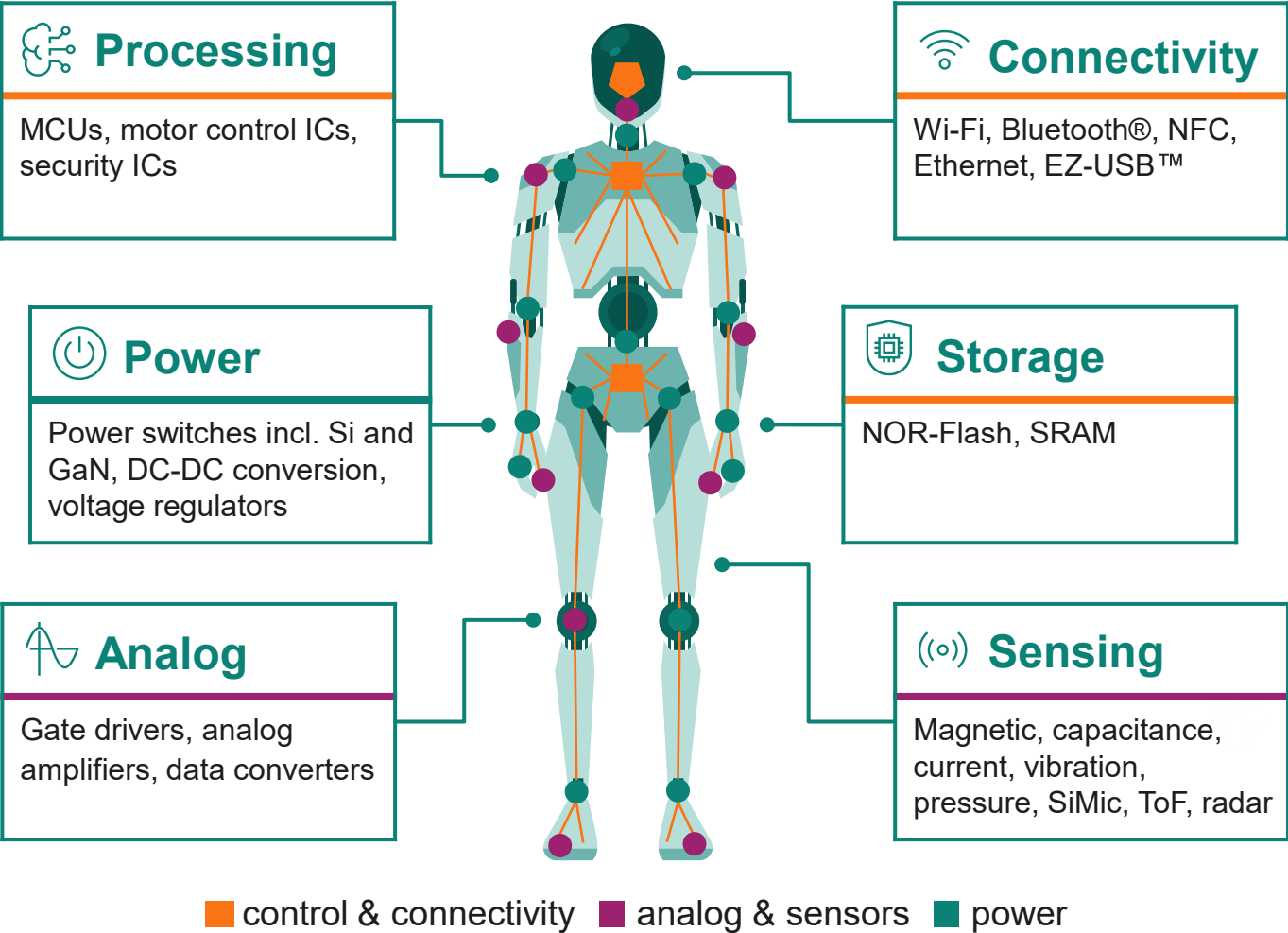
1. With a wide range of **IBC topologies**, Infineon is serving a multitude of data rack configurations while ensuring cost-effectiveness
2. **Quality and Reliability** to improve mean time between failures in complex systems
3. **Power density** as GPU power increases
4. **Efficiency** for total cost of ownership
5. **Thermal Management** in air / liquid cooled environments
6. **Supply security** with 2nd source and fast time to market

Highest-density VRM modules enable true vertical power delivery adjacent to the processor

Breaking the speed and density barrier - Next-gen VRMs achieve 3 A/mm² and more



We empower humanoids to sense, move, act and connect. Safe and secure.



~\$500

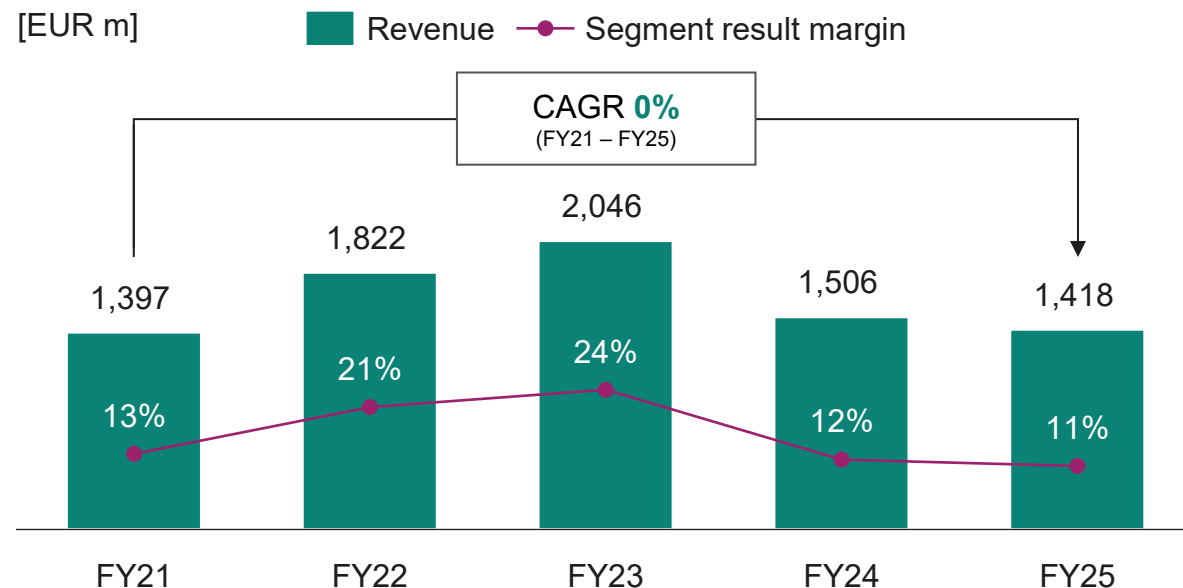
Infineon's addressable content
per humanoid robot

Connected Secure Systems

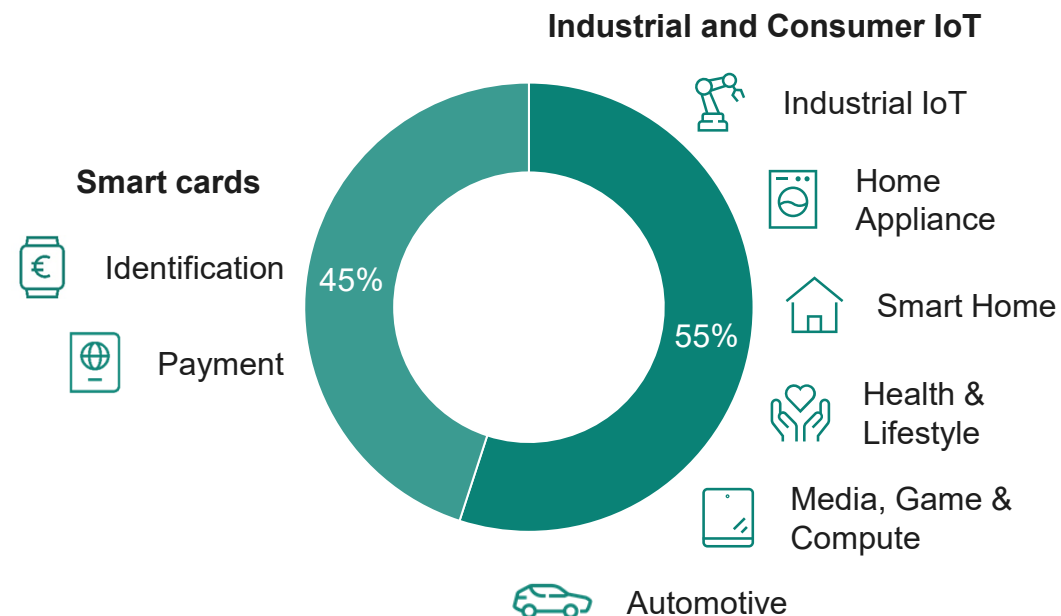


CSS at a glance

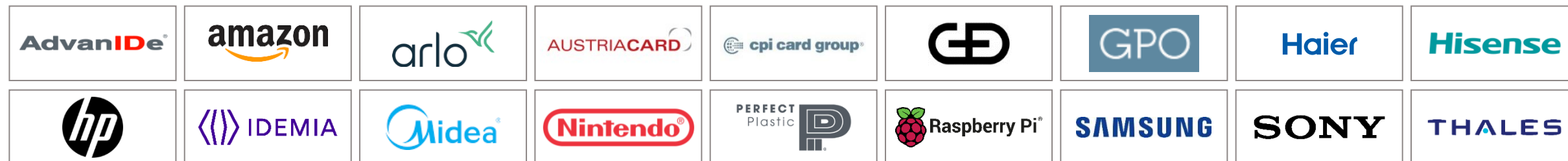
CSS revenue and segment result margin



FY25 revenue split by application



Key customers



Providing the essential building blocks compute, connectivity, security, and software



Consumer



Industrial



Automotive

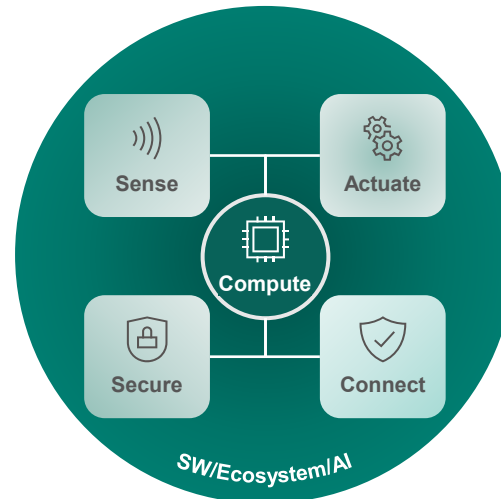


Compute

PSOC™ and **XMC™**
micro-controllers allow
customers to enable smart,
connected products

Security

OPTIGA™, **SECORA™** and
TEGRION™ solutions provide robust
embedded security for IoT devices,
authentication, payments,
identification, and access control



Software

DEEPCRAFT™ Studio and
ModusToolbox™ software
simplifies and accelerates
development for Infineon MCUs

Connectivity

AIROC™ **Wi-Fi** and **Bluetooth®**
products provide ultra-robust,
low-power wireless
communications

CSS seamlessly interconnects **compute, connectivity, security, and software** - the essential building blocks of digitalization

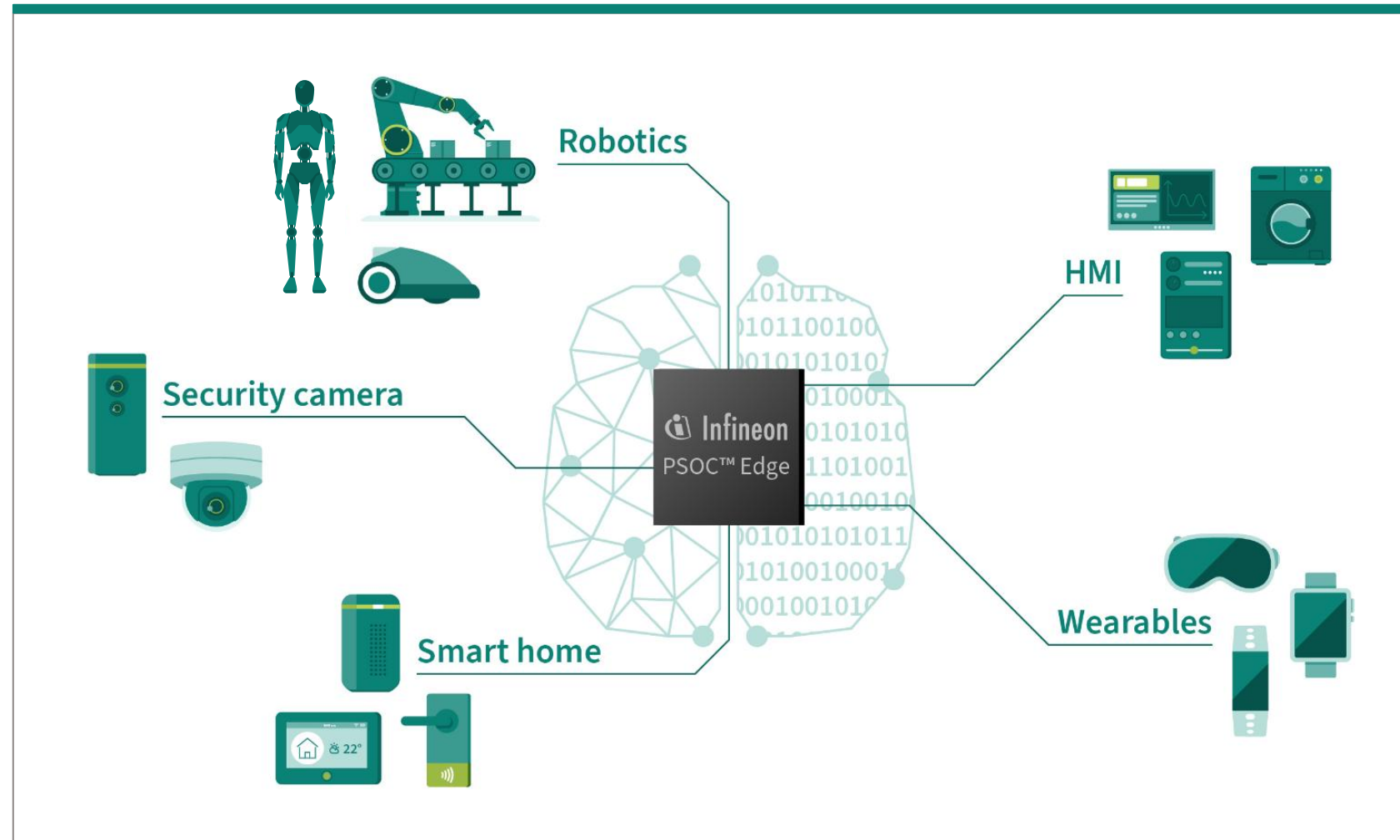
Infineon's MCUs at the heart of every IoT and Edge AI application

New compelling MCU platforms



- Broad application range in **Edge AI, IoT, Consumer, and Industrial**
- Strength in **low power, high performance, security, and reliability**
- Roadmap focus on **AI, security, and integrated connectivity**

PSOC™ Edge – Enables a new generation of responsive machine learning devices



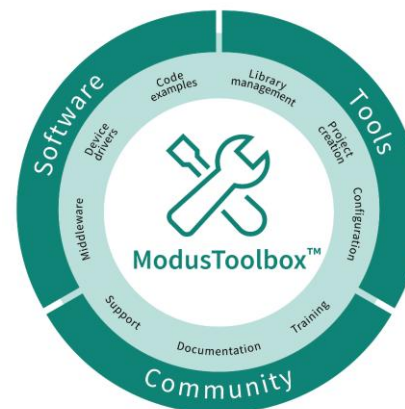
Software with maximal ease of use

DEEPCRAFT™ Studio



- Infineon's Edge AI development platform
- Data collection & pre-processing, model training, model conversion & deployment
- Provides AI-models for a wide variety of applications

ModusToolbox™



- Infineon's modern, extensible development system
- Collection of development tools, libraries, and embedded runtime assets

Full journey from Edge AI model development to embedded software with flexible entry

Build a model

Bring your own model

Buy a ready Model

OR



Optimize & validate your model



Develop your embedded product with Infineon's MCUs

DEEPCRAFT™ Studio

DEEPCRAFT™ Studio + Modus Toolbox™

Modus Toolbox™

Enabling connectivity with Infineon's broad wireless portfolio for IoT, industrial, and automotive applications



Wireless connectivity portfolio & advancements in ultra-wideband

Wi-Fi AIROC™

- **Comprehensive Portfolio:** Wi-Fi 4,5,6/6E and connected MCUs
- **Ultra-low power** consumption
- **Integrated MCUs** for simplified IoT design
- Advanced Wi-Fi 6/6E with **future-ready Wi-Fi 7** capabilities



Bluetooth® AIROC™

- **Full-featured Bluetooth®** portfolio with SoCs and modules
- **Low-energy focus** for extended battery life
- **Long-range Bluetooth® Low Energy (LE)** for industrial and automotive applications



Wi-Fi- & Bluetooth® Combo AIROC™

- Combines Wi-Fi and Bluetooth® in one module for **dual-connectivity use cases**
- Pre-certified for **faster time to market**



Wireless Connectivity

UltraWideband

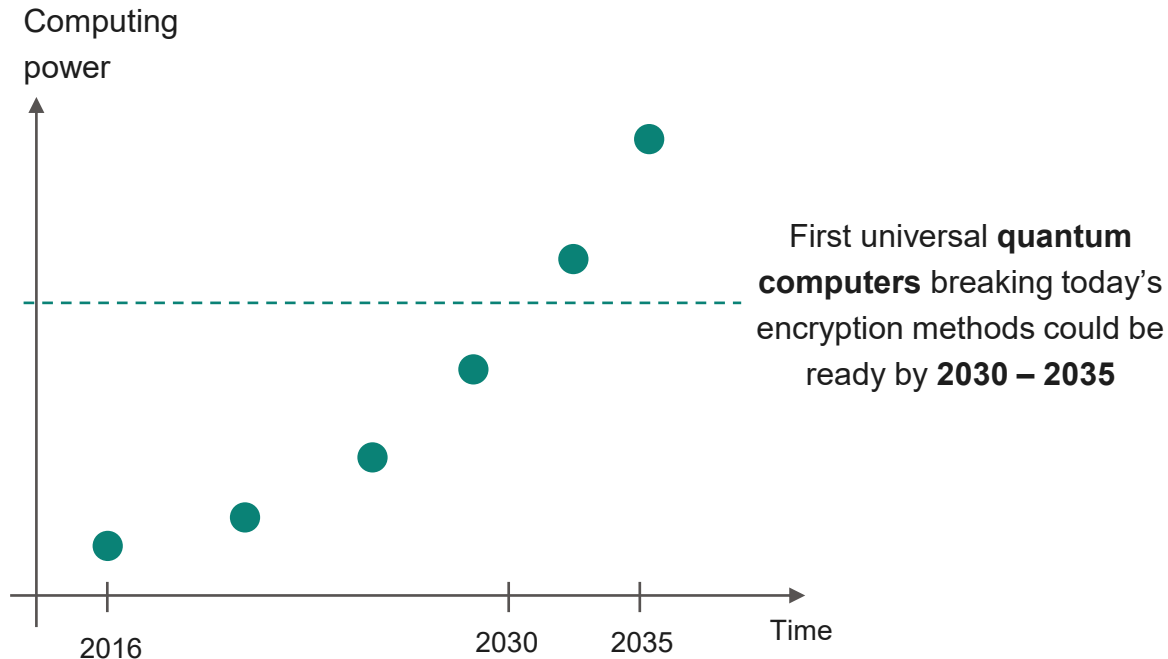
- Acquisition of UWB pioneer **3db**
- **Target applications:** Car access and fine ranging



As quantum computing rises and introduces high security risks, Infineon serves as a trusted advisor in the PQC landscape.



Computing power of quantum computers



Cybersecurity

- **Asymmetric** encryption algorithms (e.g. RSA, ECC) lose appropriate security
- **Symmetric** encryption algorithms are less effected

Threats

- To **sensitive data** from governments and public institutions
- To **products** with long R&D cycles

Legislations

- Government bodies are **working on legislations** to prepare for quantum-safe future

Infineon's post-quantum cryptography approach



Infineon is the **first company** to receive the **Common Criteria EAL6** for the implementation of a **PQC algorithm** in a security controller



Infineon **TEGRION™** product family of **next-gen security controllers** for long-lasting security and superior fault protection



Partnering with customers, partners, and the academic community to prepare for a post-quantum future



Global team of experts and researchers dedicated to the PQC field

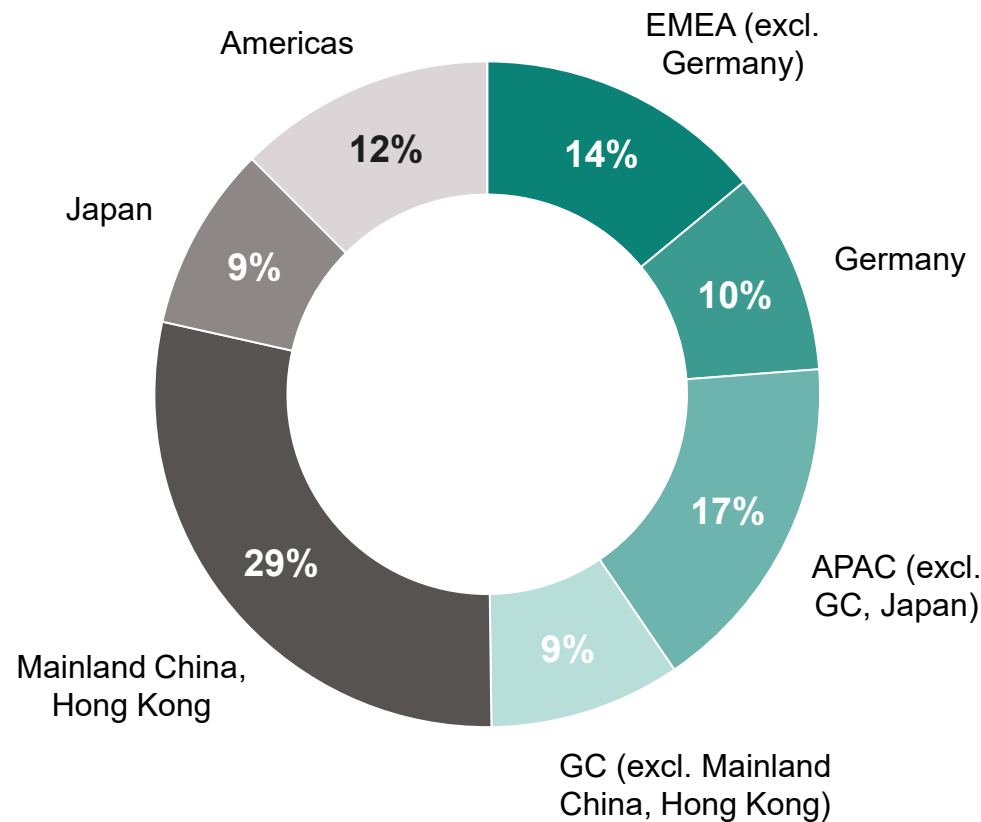
Selected financial figures



Strong presence in all regions; well-balanced customer portfolio; no customer represents more than 10% of total sales

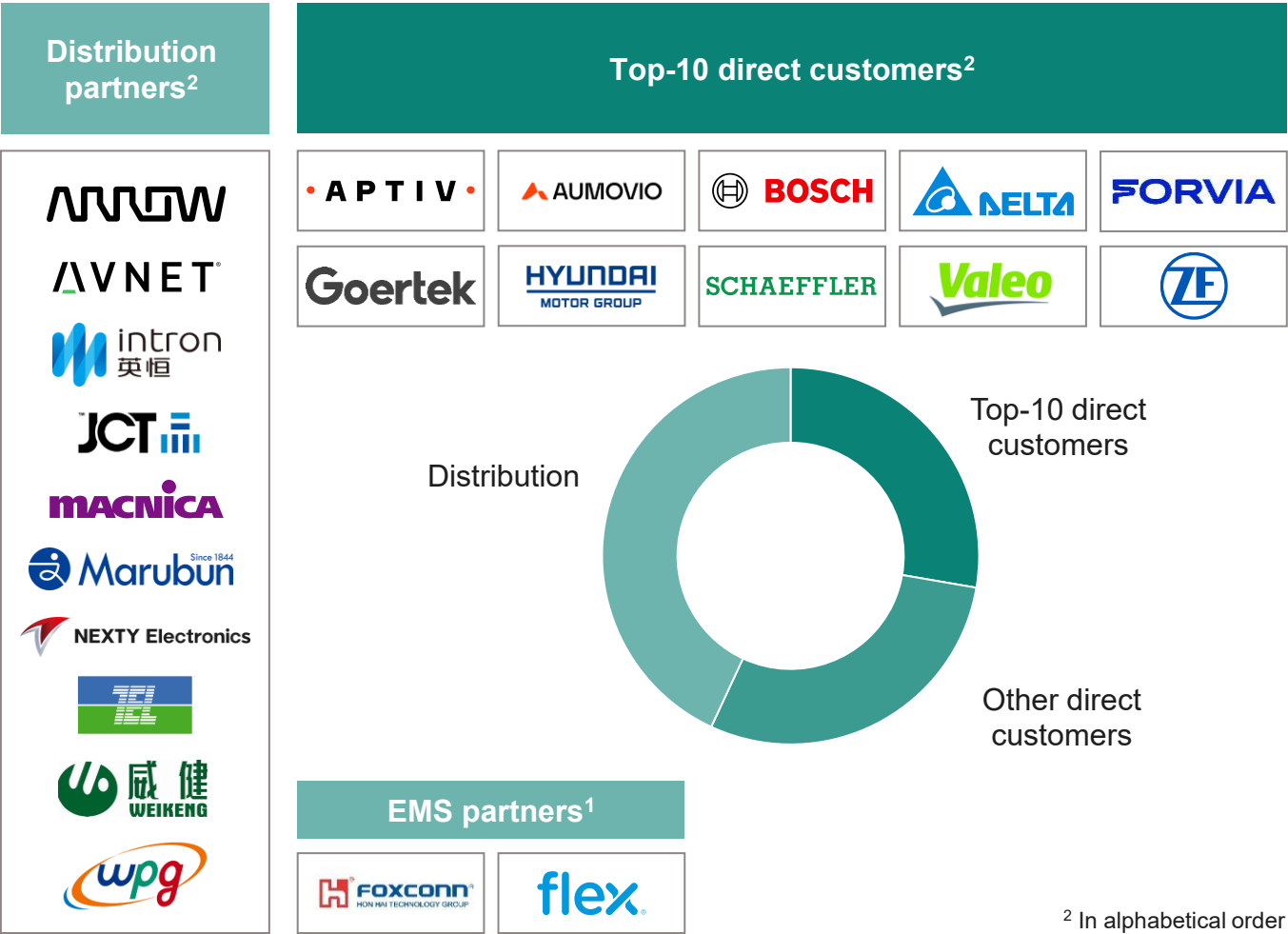


FY25 revenue by region¹



¹ Based on sold-to logic

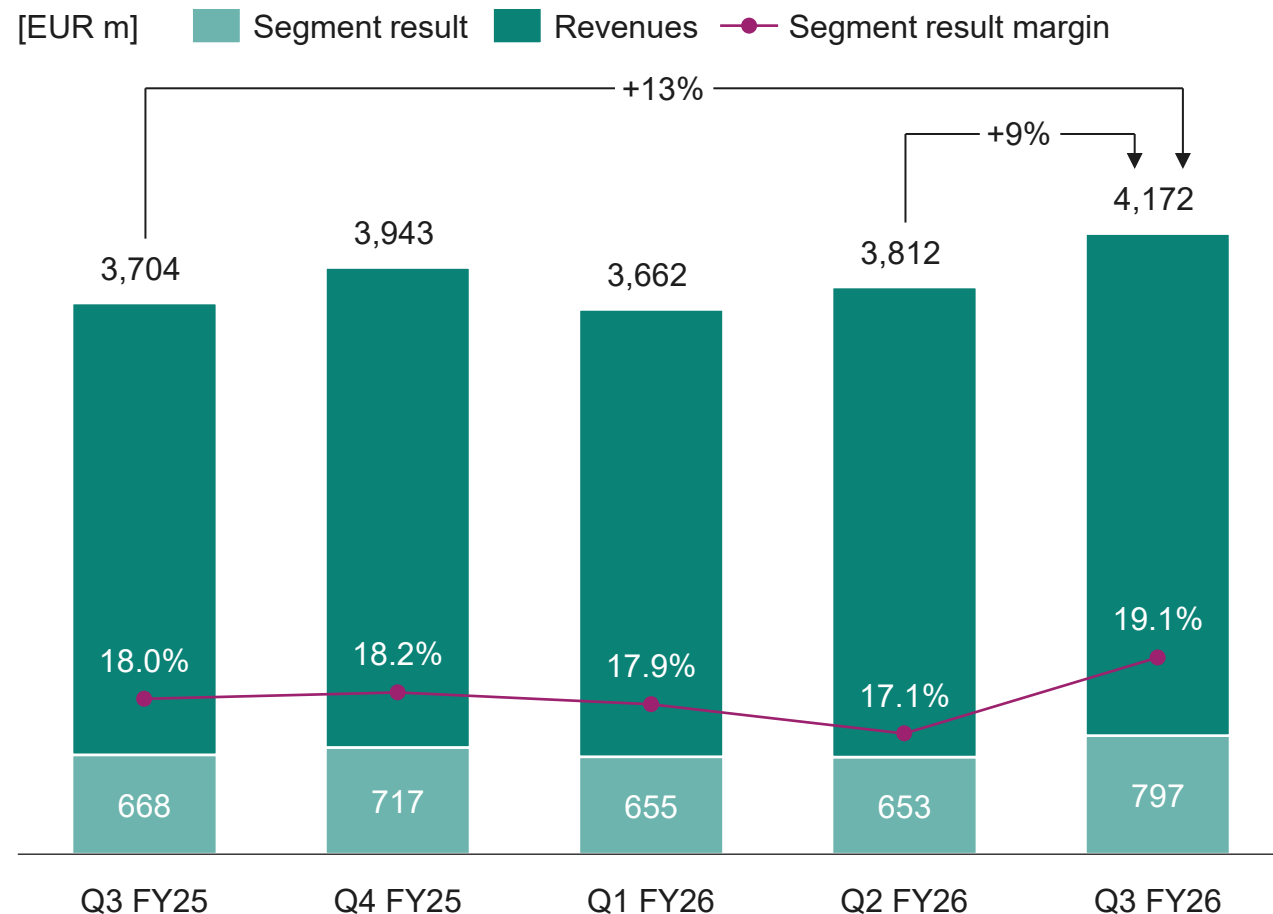
Revenue by sales channel



² In alphabetical order

Group financial performance

Revenues and Segment Result

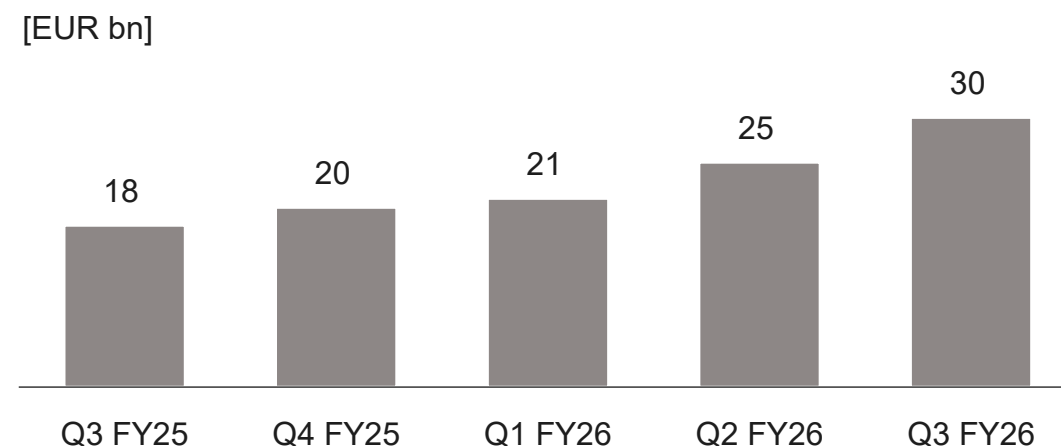


USD exchange rate

Average revenue exchange rate

	Q3 FY25	Q2 FY26	Q3 FY26
Ø USD/EUR	1.14	1.17	1.16

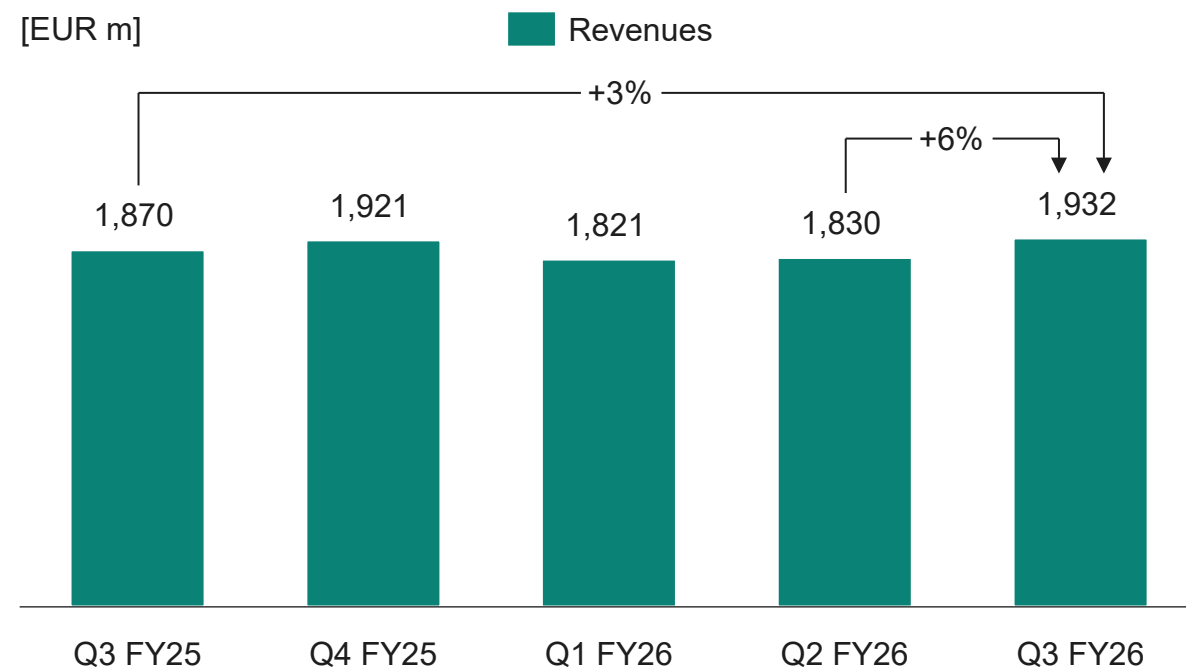
Order backlog¹



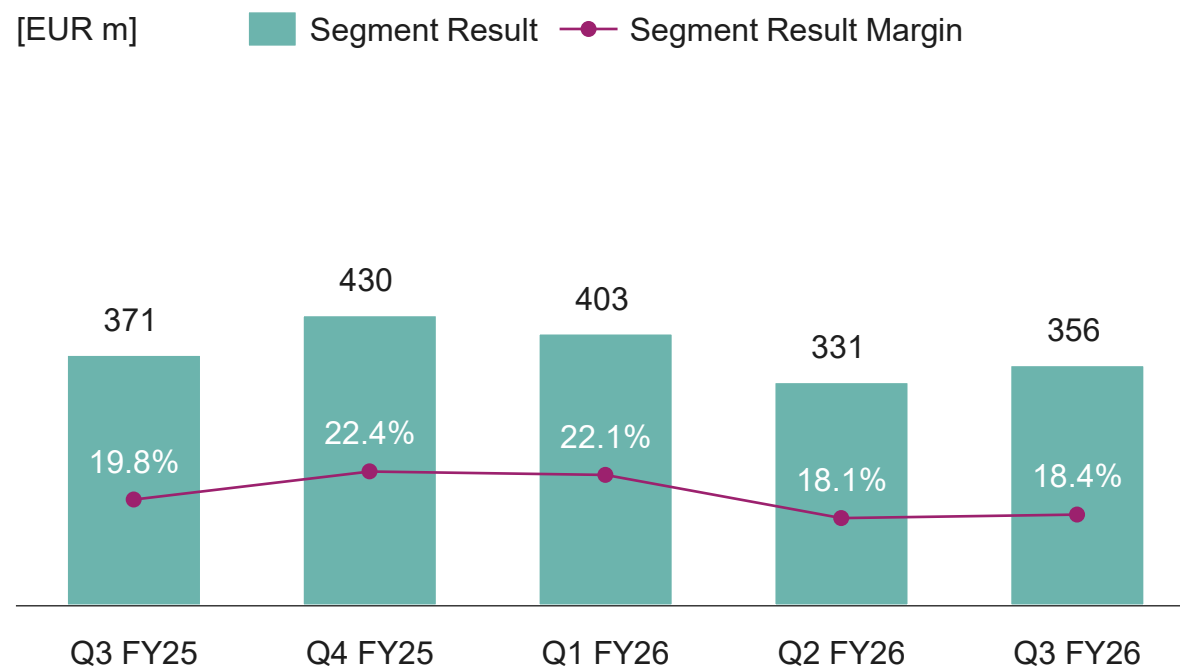
¹ See notes for definition

Automotive (ATV)

Revenues



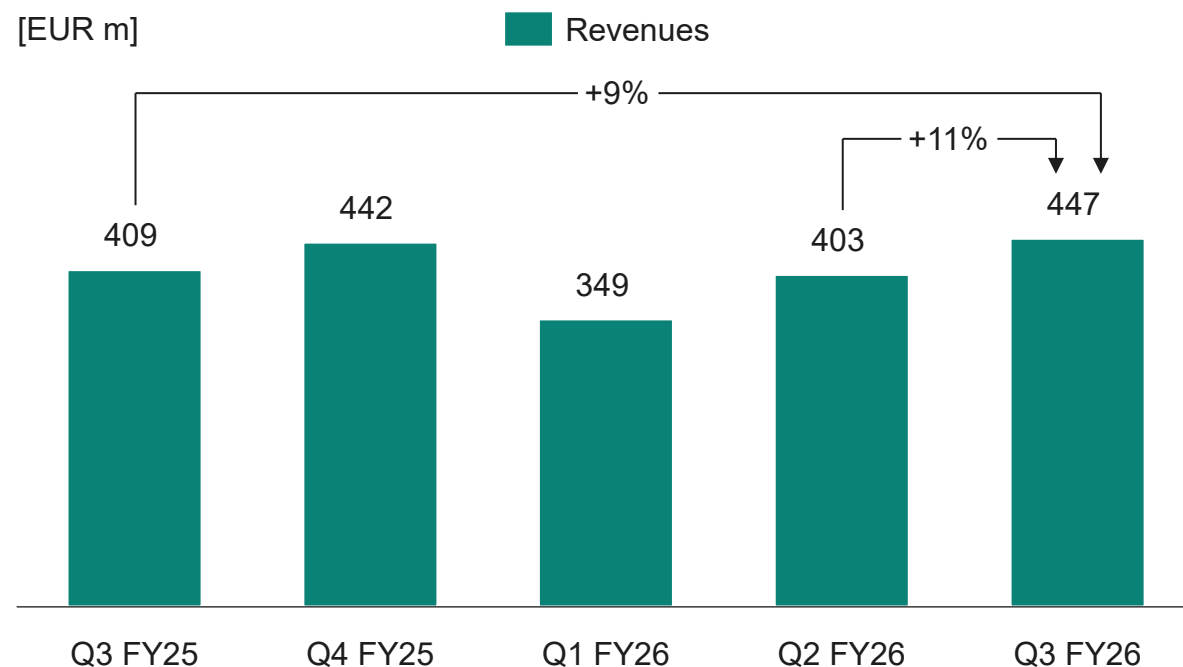
Segment Result



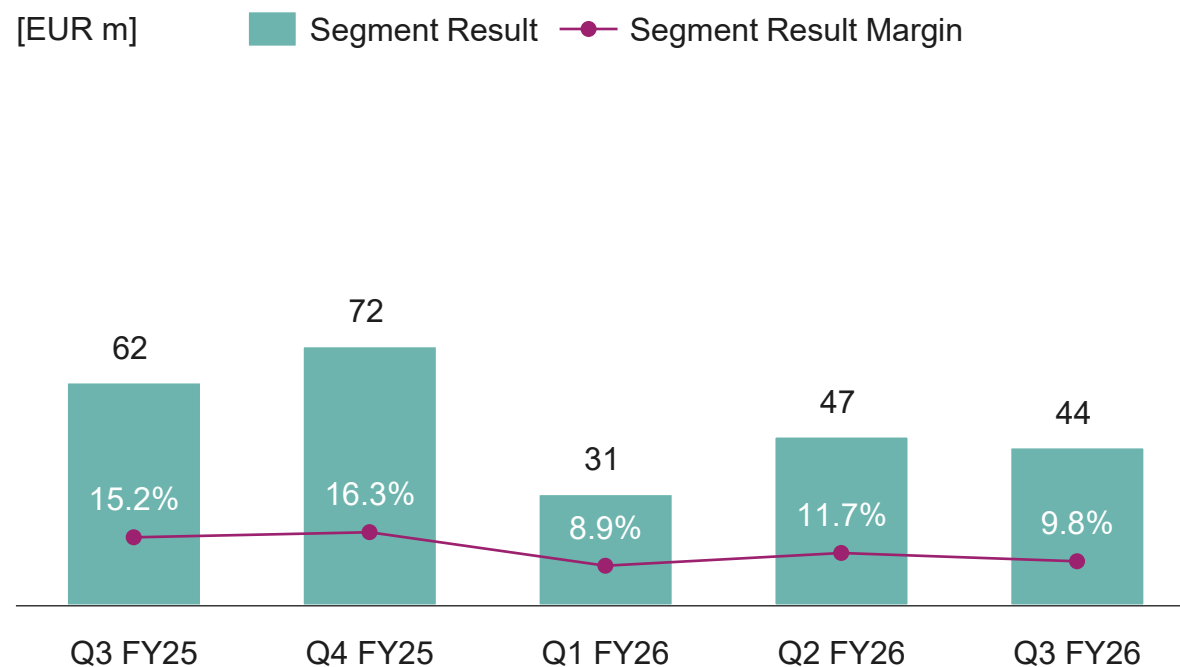
- Q-o-Q revenue growth mainly driven by microcontrollers, smart power components and ethernet solutions – all building blocks of SDVs
- Sequential segment result improvement, though the business with high-voltage power components for electric drivetrains continues to be a burden.
- Automotive order intake strong, driven by structural content growth, share gains and inventory replenishment

Green Industrial Power (GIP)

Revenues¹



Segment Result¹

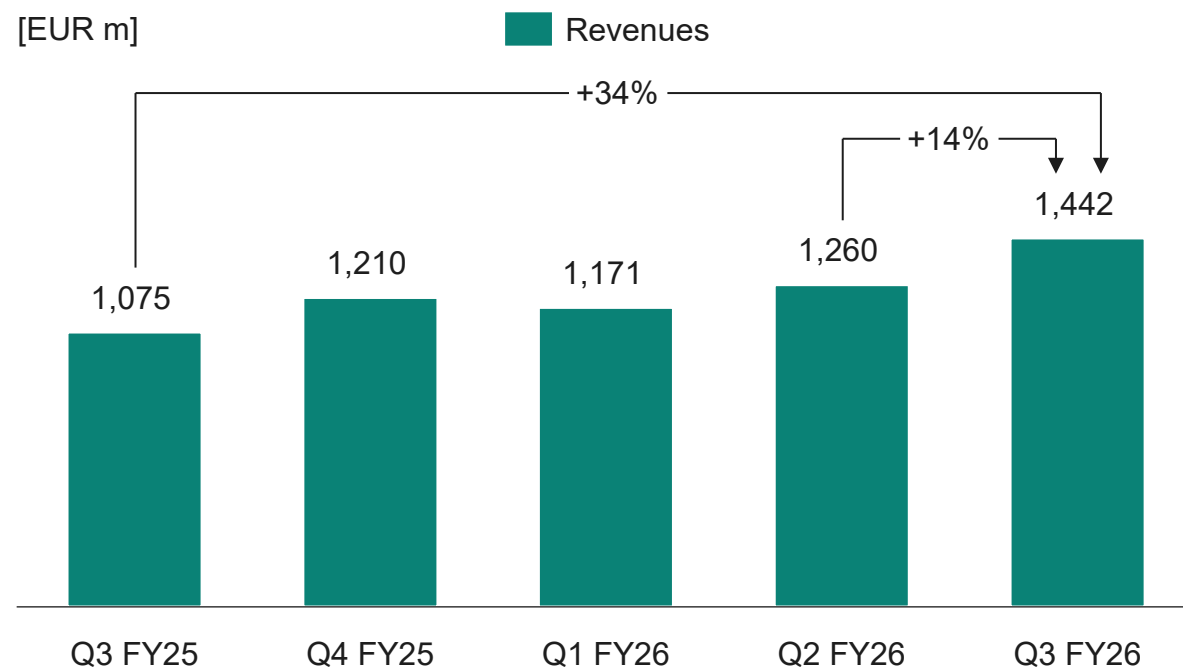


- Revenue growth driven by industrial market recovery and investments in power infrastructure
- Segment result negatively impacted by temporary operational and inventory-related effects.
- Strong structural momentum from grid expansion and modernization, boosting demand for energy storage, transmission & distribution equipment, and high-voltage solid-state devices.

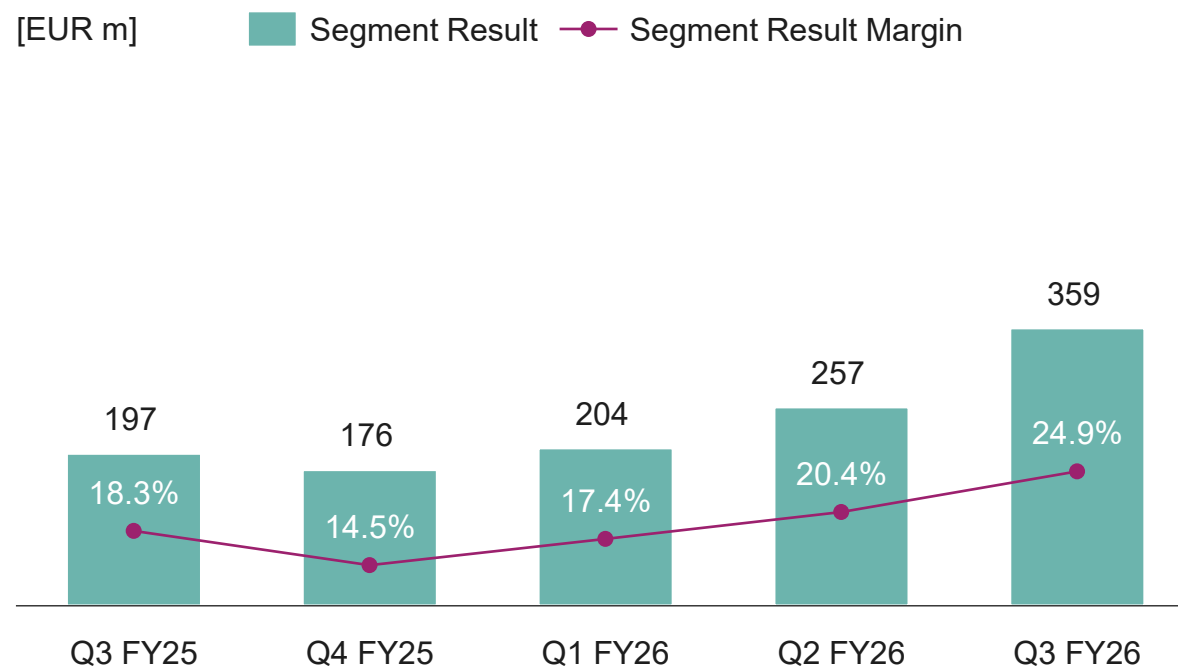
¹ Figures have been historically restated to reflect "Power Drivers & Signal ICs" product line transfer of from GIP to PSS

Power & Sensor Systems (PSS)

Revenues¹



Segment Result¹



- Strong revenue growth driven by further rising demand for power solutions for AI data centers – IFX with leadership position
- Continued margin expansion on the back of accretive AI business, supporting PSS's profitable growth path
- FY26 AI revenue now forecast at more than €1.6bn (previously €1.5bn), significant portion of future data center revenue backed by customers signing CRAs with us

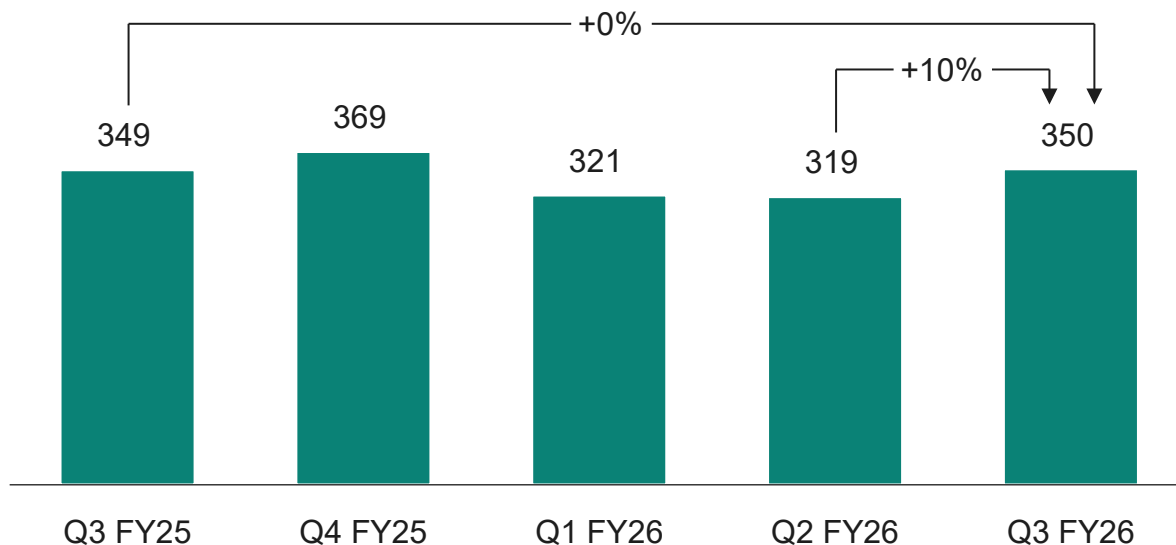
¹ Figures have been historically restated to reflect "Power Drivers & Signal ICs" product line transfer of from GIP to PSS

Connected Secure Systems (CSS)

Revenues

[EUR m]

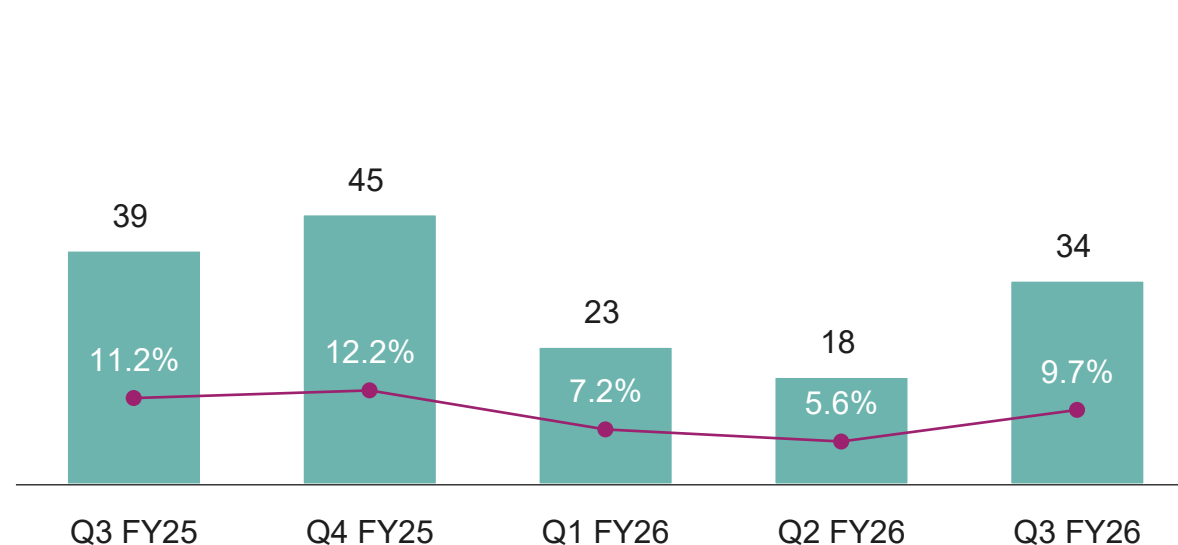
Revenues



Segment Result

[EUR m]

Segment Result Segment Result Margin

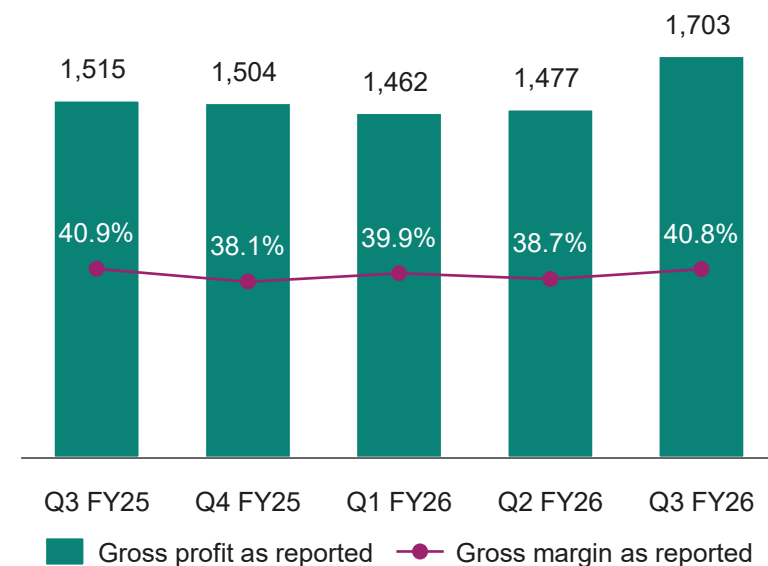


- Revenue growth across all product areas, led by strong demand for authentication and identification solutions.
- Segment result increase due to higher volumes.
- AI adoption at the edge continues to broaden across industrial and consumer applications. Increasing demand for integrated system-level solutions combining sensors, microcontrollers, connectivity and security.

Gross margin and Opex

Gross profit

[EUR m]



Therein Non-Segment Result charges

[EUR m]

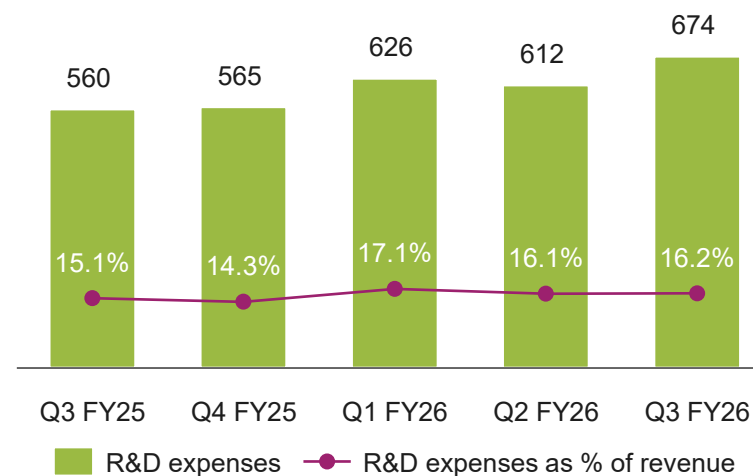
76	99	113	85	84
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Adjusted gross margin

43.0%	40.7%	43.0%	41.0%	42.8%
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R&D

[EUR m]



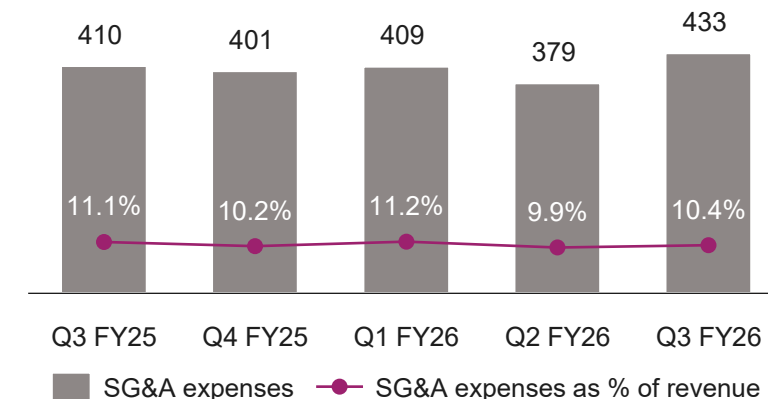
Therein Non-Segment Result charges

[EUR m]

18	17	35	29	44
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SG&A

[EUR m]



Therein Non-Segment Result charges

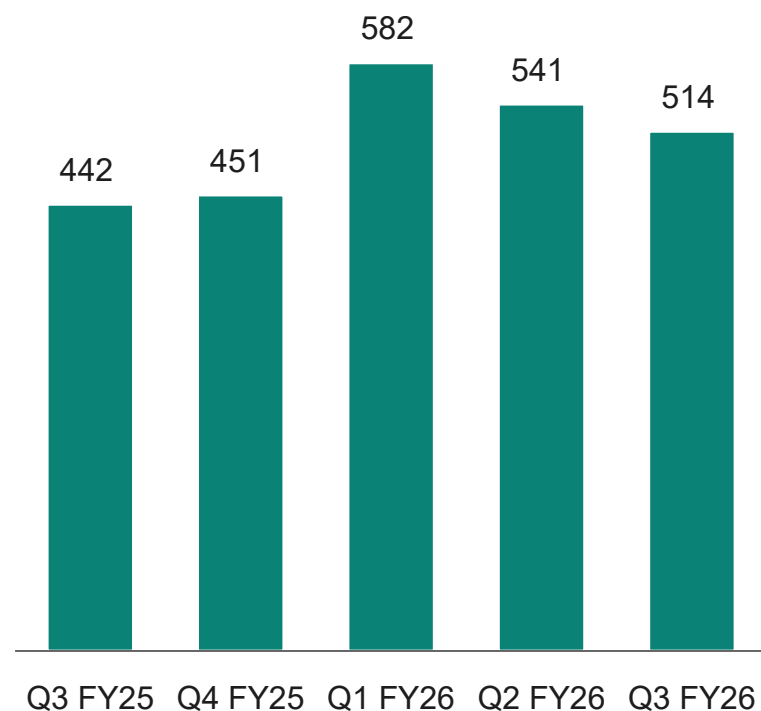
[EUR m]

50	67	77	52	72
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Investments, Depreciation & Amortization and Free Cash Flow

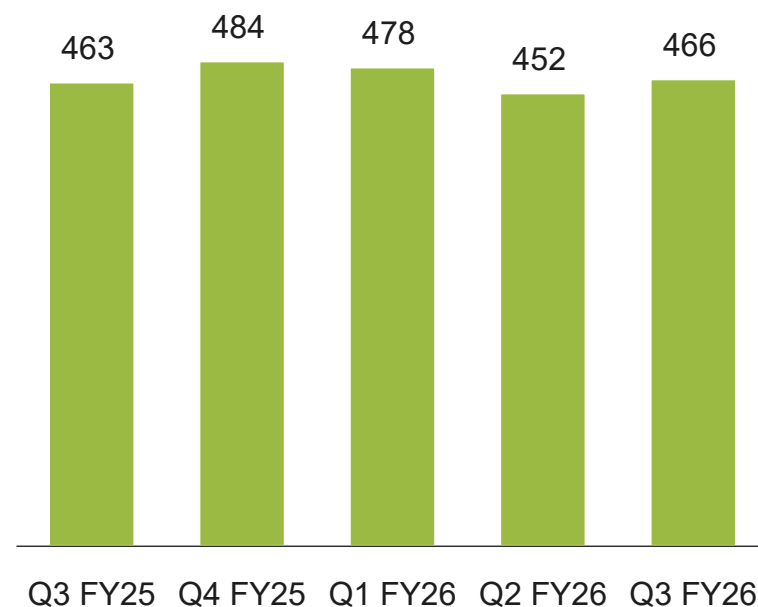
Investments

[EUR m]



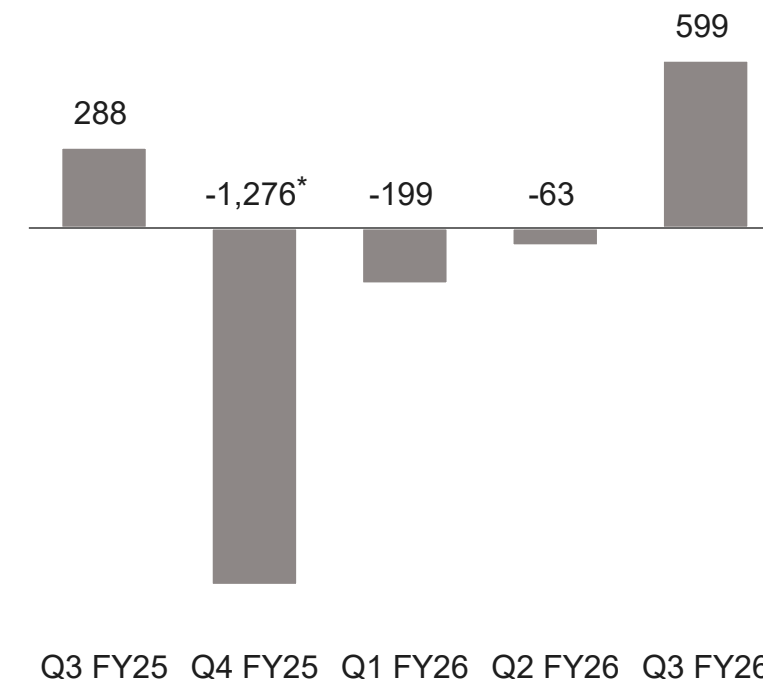
Depreciation & Amortization

[EUR m]



Free Cash Flow

[EUR m]

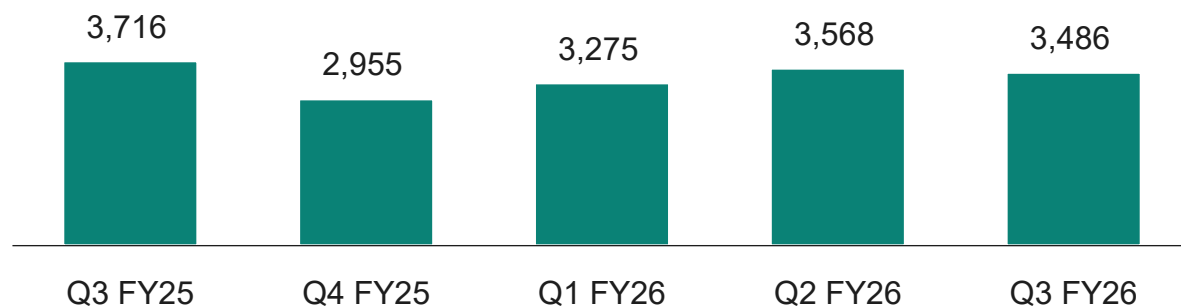


*FCF incl. 2,180m acquisition related outflows for Marvell's automotive Ethernet business

Working capital, in particular trade working capital components

Working capital¹

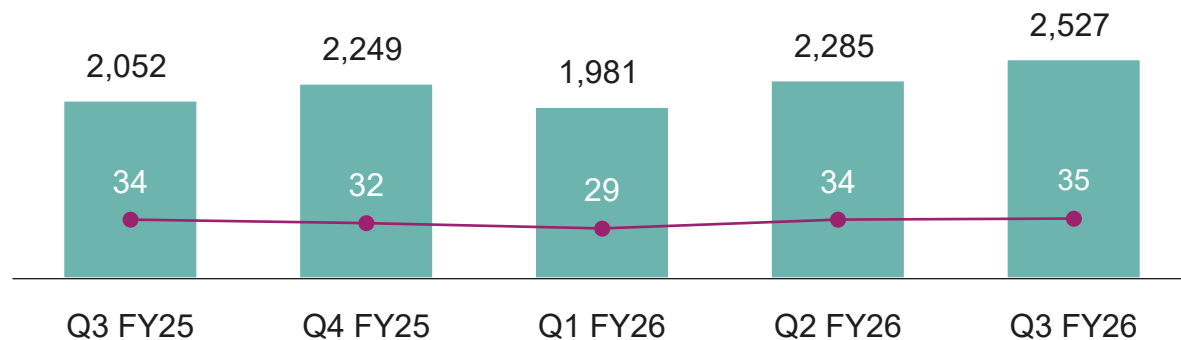
[EUR m]



Trade receivables

[EUR m]

[days²]



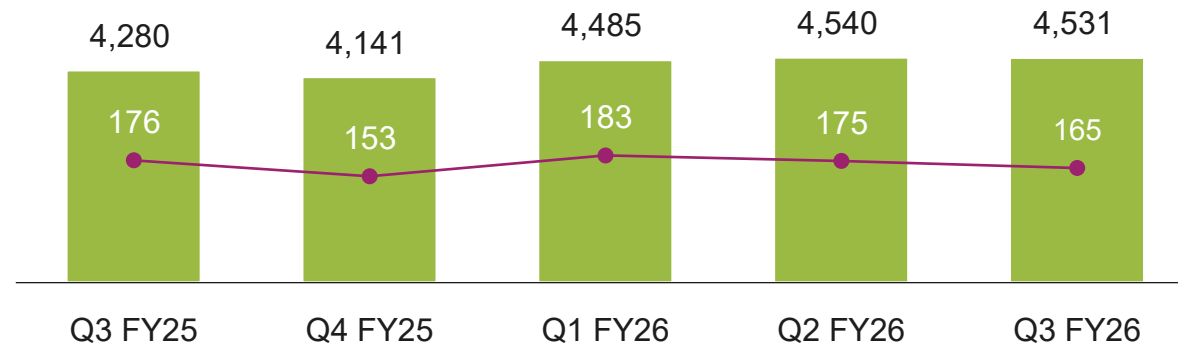
¹ See notes for definition

² The calculation of DSO was adjusted effective 1 October 2025. The adjustment increases the transparency and informative value of the key figure and improves its comparability. The figures for the comparative periods have been adjusted accordingly.

Inventories

[EUR m]

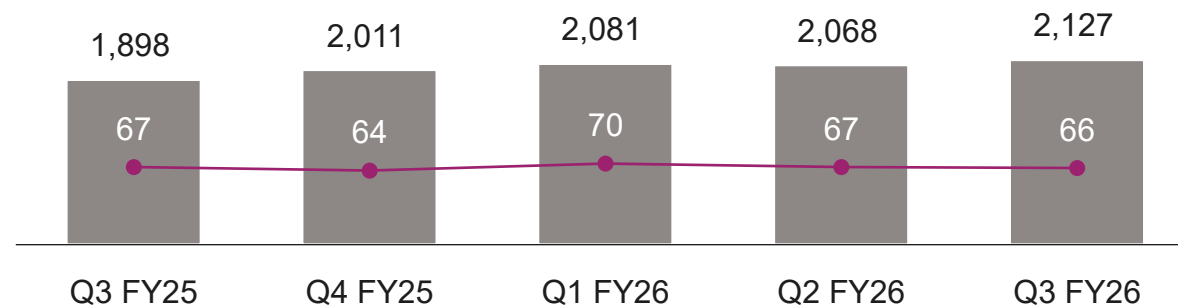
[days]



Trade payables

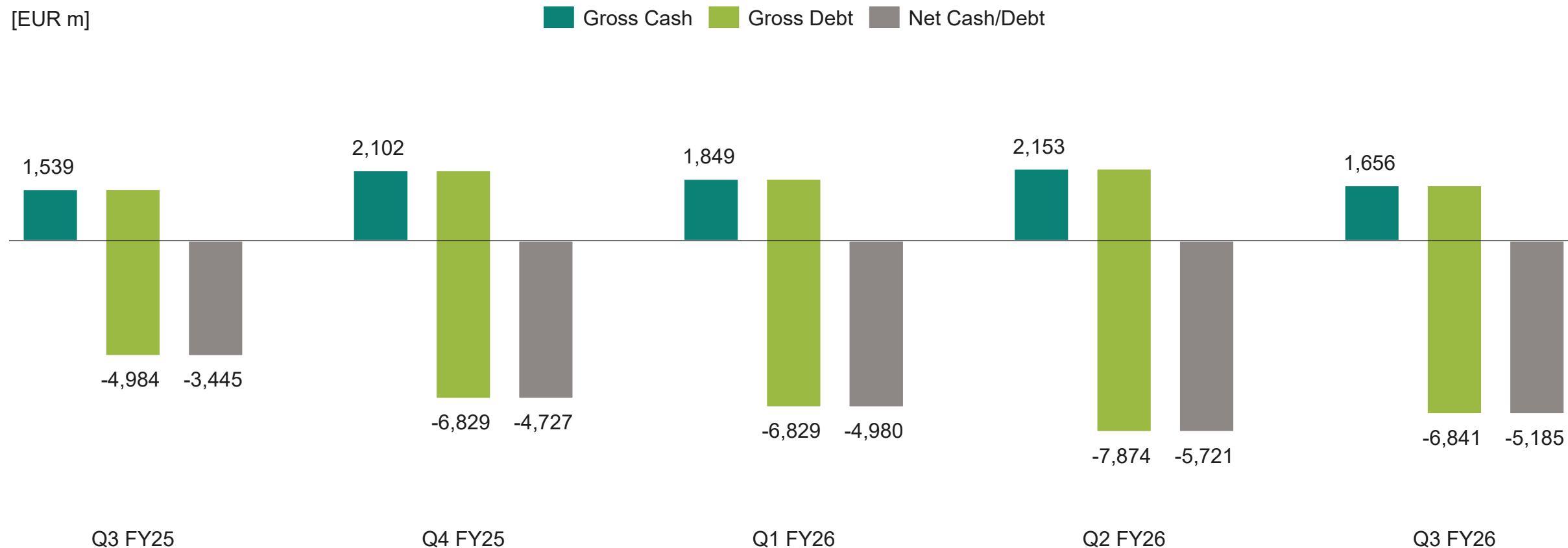
[EUR m]

[days]



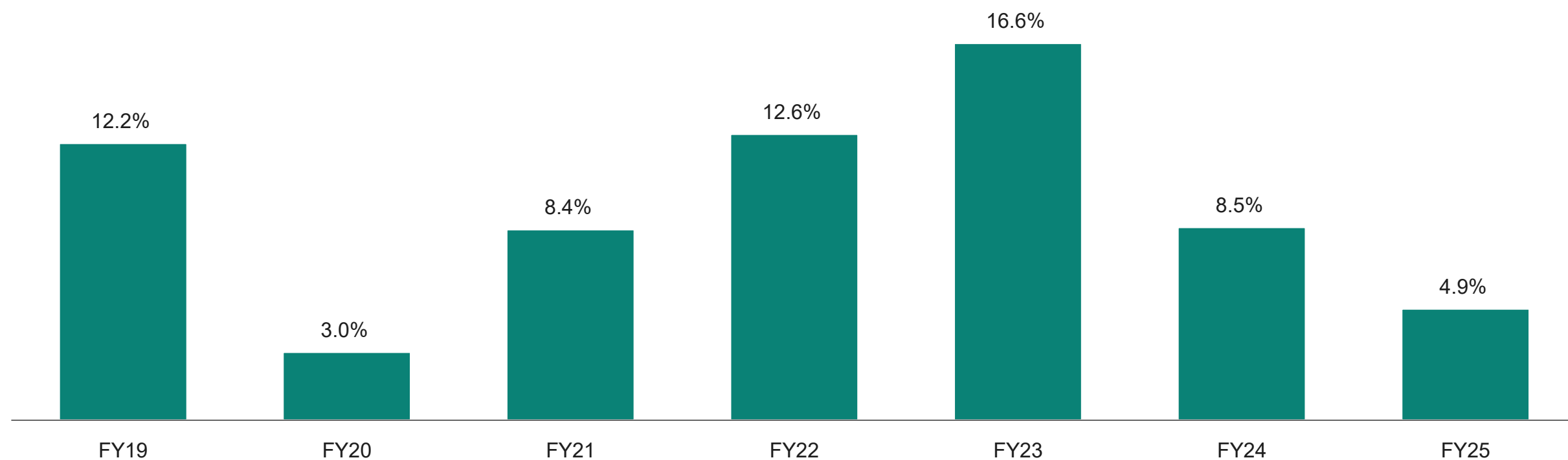
Development of liquidity and debt

Capital structure



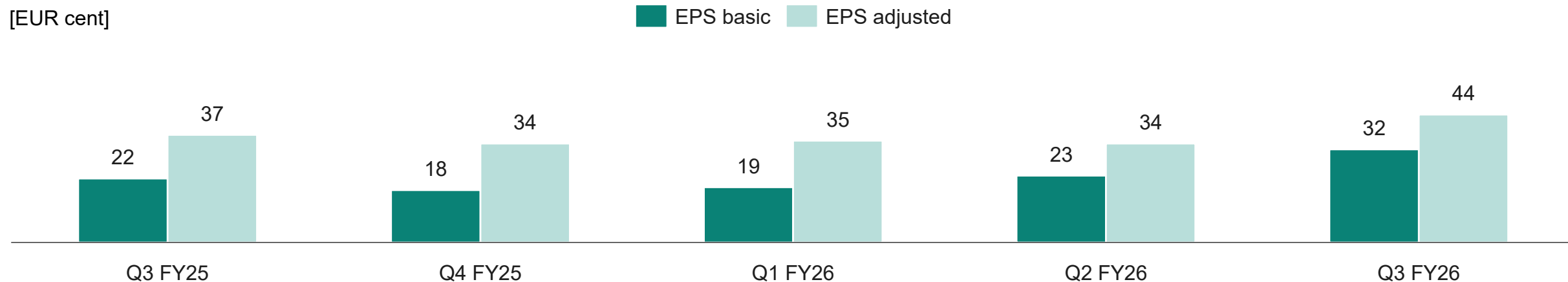
Return on capital employed

Historical development

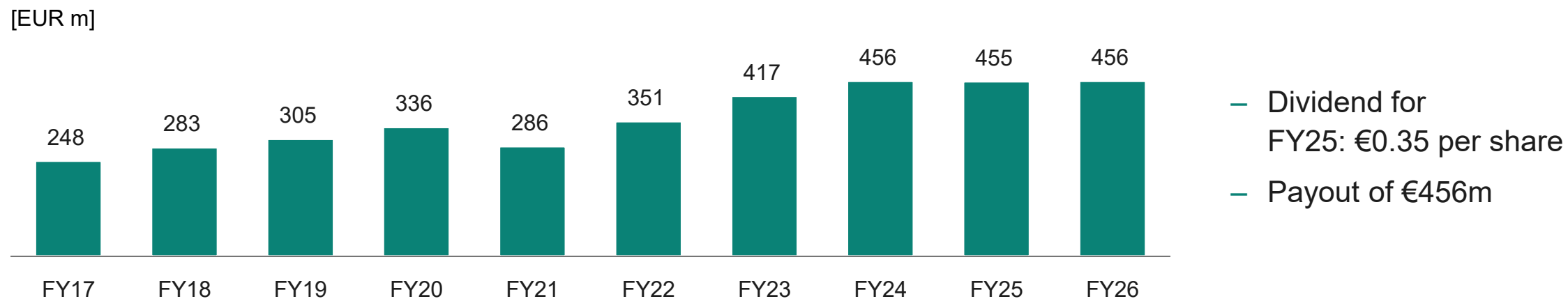


Earnings-per-share and total cash return

Development of earnings-per-share (EPS) from continuing operations

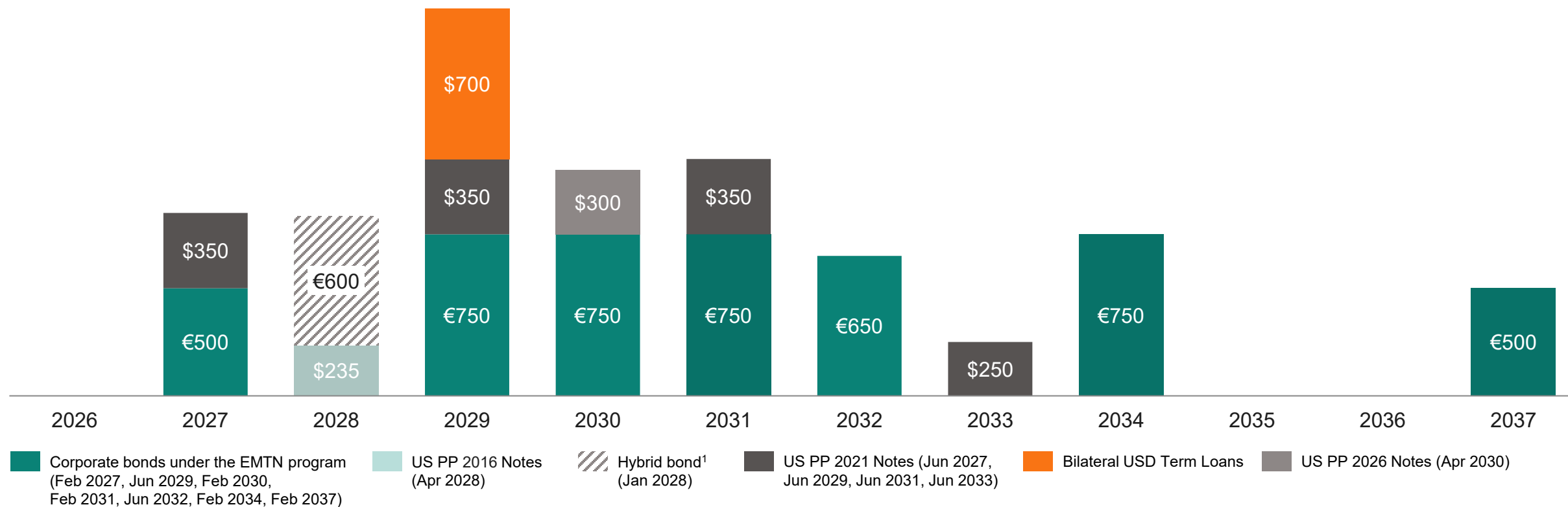


Total cash return to shareholders via dividends



Maturity profile for calendar years 2026 to 2037

[EUR m; USD m; nominal values]



¹ On 1 Oct 2019, Infineon issued a €600m perpetual hybrid bond with first call date in 2028; the hybrid bond is accounted as equity under IFRS.

Conservative financial policy and strict commitment to investment-grade rating are the basis for through-cycle flexibility



	Financial Policy Targets	Status Quo (LTM 30 June 2026)
Gross Cash ¹	At least 10% of revenue ³	11% of revenue → €1.7bn
Gross Debt ²	≤ 2.0x EBITDA	1.8x EBITDA
Comfortable liquidity position	— Flexibility for financing operating activities and investments through the cycle	
Balanced debt position	— Gross debt target commensurate with investment-grade rating	
Rating	Investment grade	BBB+ stable outlook (by S&P Global Ratings) ⁴

¹ Gross cash position is defined as cash and cash equivalents plus financial investments | ² Gross debt is defined as short-term debt and current maturities of long-term debt plus long-term debt. EBITDA is calculated as the total of earnings from continued operations before interest and taxes plus scheduled depreciation and amortization | ³ Gross cash target: At least 10 percent of revenue on average throughout the fiscal year | ⁴ Latest confirmation February 2026



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Disclaimer

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These statements and/or assessments are based on assumptions and management expectation resting upon currently available information and present estimates. They are subject to a multitude of uncertainties and risks, many of which are partially or entirely beyond Infineon's control. Infineon's actual business development, financial condition, performance and strategy may therefore differ materially from what is discussed in this presentation.

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Glossary

AC	alternating current
AD	automated driving
ADAS	advanced driver assistance system
AI	artificial intelligence
BBU	battery back-up unit
BEV	battery electric vehicle
BLE	Bluetooth low energy
BMS	battery management system
BoM	bill of materials
BVM	backside vertical module
DC	direct current
DSC/SSC	double/single sided cooling
E/E	electrical/electronic architecture
ECPD	electronic circuit protection device
ECU	electronic control unit
EMS	electronics manufacturing service
ESS	energy storage system
EV	electric vehicle
FCEV	fuel cell electric vehicle
FHEV/MHEV	full/mild hybrid electric vehicle
GaN	gallium nitride
GPU	graphic processing unit
HEMT	high-electron-mobility transistor
HFT	high-frequency transformation
HV	high voltage
HVAC	heating, ventilation, air conditioning
HVDC	high-voltage direct current
IBC	intermediate bus converter
IC	integrated circuit
ICE	internal combustion engine
IGBT	insulated gate bipolar transistor
IoT	internet of things
LED	light-emitting diode
LLC	resonant tank converter

MCU	microcontroller unit
LV	low voltage
MEMS	micro electro-mechanical system
MOSFET	metal-oxide silicon field-effect transistor
MPU	micro processing unit
MV	medium voltage
NFC	near-field communication
OBC	on-board charger
OEM	original equipment manufacturer
P2S	Infineon's strategic product-to-system approach
PCS	power capacitor system
PFC	power factor correction
PDN	power delivery network
PHEV	plug-in hybrid electric vehicle
PHY	physical layer transceiver
PMIC	power management integrated circuits
PSU	power supply unit
RAM	random access memory
RF	radio frequency
SAE	Society of Automotive Engineers
SAM	serviceable available market
SDK	software development kit
Si	silicon
SiC	silicon carbide
SiVR	substrate integrated voltage regulator
SoC	system-on-chip / state of charge
SSCB	solid-state circuit breaker
SST	solid-state transformer
ToF	time-of-flight
UPS-ESS	uninterruptable power supply energy storage solution
UWB	ultra-wideband
VRM	voltage regulator module
xSC	different switched capacitor topologies

Notes and ESG footnotes

Investments =	'Investments in property, plant and equipment' + 'Investments in other intangible assets and capitalized developments costs'
Adjusted Free Cash Flow Margin =	Adjusted for large investments in frontend buildings and major M&A transactions, for full definition see chapter "Internal management system" in the annual report
Capital Employed =	'Total assets' – 'Cash and cash equivalents' – 'Financial investments' – 'Assets classified as held for sale' – ('Total Current liabilities' – 'Short-term financial debt and current maturities of long-term financial debt' – 'Liabilities classified as held for sale')
RoCE =	'Operating profit from continuing operations'/'Capital Employed' = 'Profit (loss) from continuing operations adjusted for interest result'/'Capital Employed'
Working Capital =	('Total current assets' – 'Cash and cash equivalents' – 'Financial investments' – 'Assets classified as held for sale') – ('Total current liabilities' – 'Short term financial debt and current portion of long-term financial debt' – 'Liabilities classified as held for sale')
DIO (days inventory outstanding; quarter-to-date) =	('Net Inventories'/'Cost of goods sold') x 90
DPO (days payables outstanding; quarter-to-date) =	('Trade payables'/'Cost of goods sold' + 'Purchase of property, plant and equipment') x 90
DSO (days sales outstanding; quarter-to-date) =	('Trade receivables' - 'reimbursement obligation' + 'contract assets') / 'revenue' x 90

Order backlog = The total amount of orders received regardless of their current status

ESG footnotes:

- 1) This figure takes into account manufacturing, transportation, own vehicles, travel, raw materials and consumables, chemicals, water/waste water, direct emissions, energy consumption, waste, etc. as well as direct and indirect energy-related emissions by manufacturing service providers. It is based on data collected internally and publicly available conversion factors and relates to the 2021 fiscal year.
- 2) This figure is based on internally established criteria, which are described in the explanatory notes. The figure relates to the 2020 calendar year and takes into account the following application areas: automotive, LED, induction cookers, servers, renewable energy (wind, photovoltaic) and cell phone chargers as well as drives. CO₂ savings are calculated based on the potential savings generated by technologies in which semiconductors are used. The CO₂ savings are allocated based on Infineon's market share, semiconductor share, and the lifetime of the technologies concerned, based on internal and external experts' estimations. Despite the fact that carbon footprint calculations are subject to imprecision due to the complex issues involved, the results are nevertheless clear.
- 3) Carbon neutrality is defined in terms of Scope 1 and Scope 2 emissions.

Financial calendar

Date	Event	Location
2 September 2026	dbAccess TMT Conference	London
8 September 2026	Communacopia and Technology Conference	San Francisco
10 September 2026	Citi Global Technology Conference	New York
16-17 September 2026	Exane ESG Conference	Paris
17 September 2026	JP Morgan Milan Access Day	Milan
21 September 2026	Berenberg Goldman Sachs German Corporate Conference	Unterschleißheim
10 November 2026 ¹	Earnings release for the fourth quarter and the 2026 fiscal year	
19-20 November 2026	Morgan Stanley TMT Conference	Barcelona
30 November 2026	UBS Tech Conference	Scottsdale
3 February 2027 ¹	Earnings release for the first quarter of the 2027 fiscal year	
25 February 2027 ¹	Annual General Meeting 2027	

¹ Preliminary

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